

NEC

User's Manual

V850ES/DJ2

32-bit System in Package Microcontroller

Hardware

μPD70F3325

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NOTES FOR CMOS DEVICES

① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

⑤ POWER ON/OFF SEQUENCE

In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current.

The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

⑥ INPUT OF SIGNAL DURING POWER OFF STATE

Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

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Preface

Readers This manual is intended for users who want to understand the functions of the V850ES/DJ2.

Purpose This manual presents the hardware manual of the V850ES/DJ2. This User's Manual is an extension of the F_Series User's Manual.

F_Series Items:

For all of the items regarding the FG2 please refer to the F_Series User's Manual/Data sheet (U17215EJ2V0UD00 (2nd edition) and further releases).

MTRC of D_Series:

In this User's Manual/Data Sheet all of the MTRC relevant items and the internal connection or pinout of the D_Series device are regarded.

Organization This system specification describes the following sections:

- Pin function
- Port function
- Internal peripheral function
- Electrical target specification

Legend Symbols and notation are used as follows:

Weight in data notation : Left is high-order column, right is low order column

Active low notation : $\overline{\text{xxx}}$ (pin or signal name is over-scored) or /xxx (slash before signal name)

Memory map address: : High order at high stage and low order at low stage

Note : Explanation of (Note) in the text

Caution : Item deserving extra attention

Remark : Supplementary explanation to the text

Numeric notation : Binary . . . xxxx or xxxB
Decimal . . . xxxx
Hexadecimal . . . xxxxH or 0x xxxx

Prefixes representing powers of 2 (address space, memory capacity)

K (kilo): $2^{10} = 1024$

M (mega): $2^{20} = 1024^2 = 1,048,576$

G (giga): $2^{30} = 1024^3 = 1,073,741,824$

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Chapter 1 Introduction

The V850ES/DJ2 is a product of the NEC's V850 D_Series Series of single-chip microcontroller designed for application with up to 6 stepper motor channels.

It provides low-power operation for real-time control applications especial for automotive Dashboard applications.

1.1 General

The V850ES/DJ2 is a 32-bit System in Package (SiP) microcontroller that includes a V850ES CPU core device of the F_Series (V850ES/FG2) and a Meter Controller/Driver (MTRC) in one package.

The F_Series includes peripheral functions such as ROM/RAM, a timer/counter, serial interfaces, and an A/D converter.

In addition to high real-time response characteristics and 1-clock-pitch basic instructions, the V850ES/FG2 features multiply instructions, saturated operation instructions, bit manipulation instructions, etc., realised by a hardware multiplier, as optimum instructions for digital servo control applications. Moreover, as a real-time control system, the V850ES/FG2 enables extremely high cost-performance for applications that require a low power consumption, such as automotive applications. For an overview of the V850ES/FG2 refer to "V850ES/FG2 Introduction" on page 25.

The integrated MTRC supplies a meter controller driver macro for up to 6 stepper motor channels and GPIOs. Via the dedicated interface the controlling will be handled with a dedicated protocol.

For this internal interface the 3-wire serial interface CSIB1 of the V850ES/DG2 device is used for the serial communication and the PCM0 port of the V850ES/FG2 device is used as the CS function for the MTRC.

1.2 Features (V850ES/D_Series)

Table 1-1: Features (V850ES/D_Series)

Part Number	Name	V850ES/FG2 device	Pin	Internal Memory		CAN	SM
				Flash (KB)	RAM (KB)		
μPD70F3325	V850ES/DJ2	μPD70F3235(A)/FG2	144	256	12	2	6

Note: In the following the product term V850ES/Fx2 is used for V850ES/FG2, unless otherwise noted.

1.3 About the Subject of this User's Manual

This User's Manual is an extension of the F_Series User's Manual.

F_Series Items:

For all of the items regarding the V850ES/DG2 please refer to the F_Series User's Manual/Data Sheet (U17215EJ2V0UD00 (2nd edition) and further releases).

MTRC of D_Series:

In this User's Manual/Data Sheet all of the MTRC relevant items and the internal connection or pinout of the D_Series device are regarded.

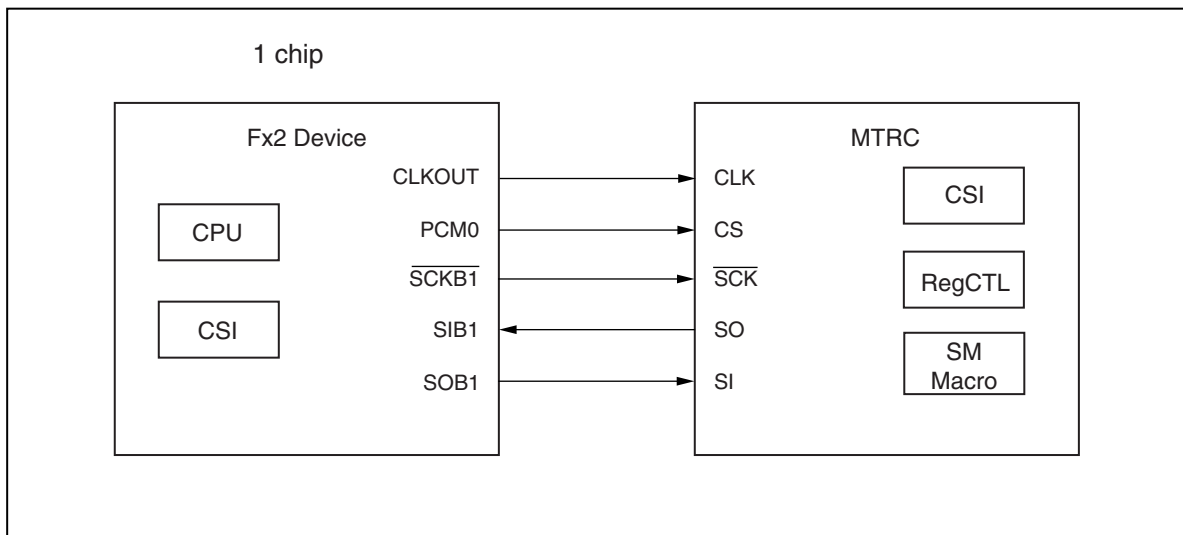
1.4 Internal Connection

The following pins of the V850ES/Fx2 device are connected to the MTRC:

- CSI I/F: SIB1, SOB1, $\overline{\text{SCKB1}}$
- Chip select: PCM0 as CS

1.4.1 System in Package (SiP)

Figure 1-1: D_Series SiP



1.5 Communication Between the V850ES/Fx2 and MTRC

The clocked synchronous serial interface CSIB1 of the V850ES/Fx2 device is used for the communication with the MTRC.

The communication I/F of the MTRC is fixed to the following settings:

- I/F: CSI
- Mode: Slave mode
- Data length: 8-bits
(support continuous data transfer, therefore the V850ES/Fx2 CSIB1 can use 16-bit data length)
- Transfer: MSB first
- Transmission: transmission/reception mode

1.5.1 Communication

The software for the communication between the V850ES/Fx2 device and the MTRC has to manage the I/F of the CSIB1 and the PCM0 pin as chip select signal.

The CSIB1 of the V850ES/Fx2 device has been set to master mode, because the MTRC CSI is always in slave mode. Therefore it is necessary, that the CSIB1 sends dummy data if the V850ES/Fx2 device wants to read data from the MTRC.

The MTRC CSI is always in 8-bit mode but is capable of continuous data transfer. Therefore the 16-bit mode of the CSIB1 can be used for faster communication for example.

1.5.2 Internal and external communication via CSIB1

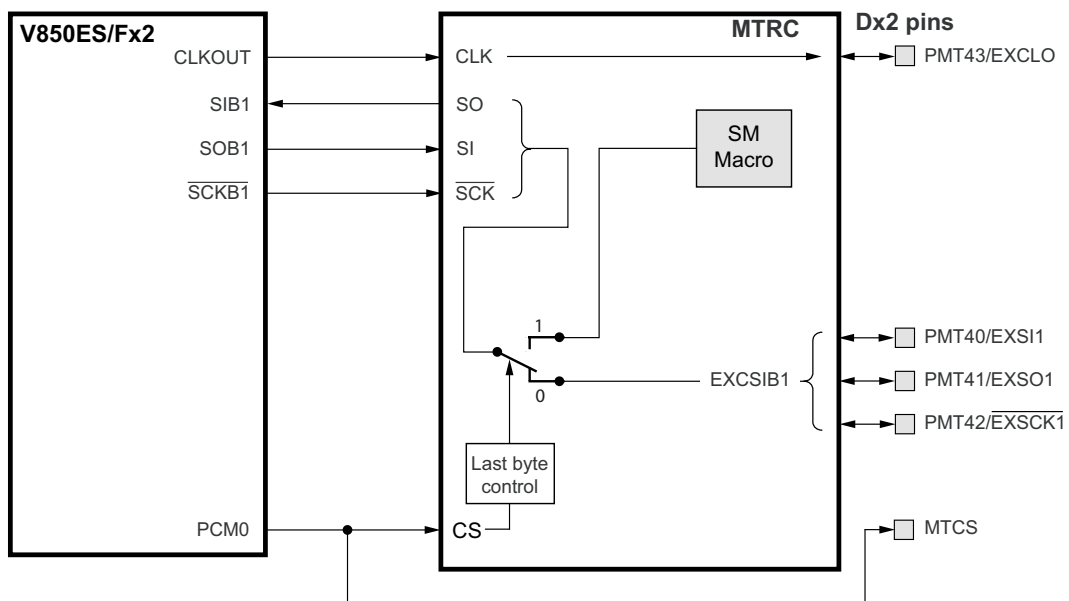
In case the PMT4 pins are operated in alternate function mode (PMCMT4n = 1), the function of the PMT40 to PMT42 (EXCSIB1 pins) ports is further controlled by the PCM0/CS signal:

- PMCMT4n = 1, PCM0/CS = 0:
PMT40 to PMT42 (EXCSIB1) provide the function of the V850ES/Fx2's CSIB1 interface pins. Thus if no communication between the V850ES/Fx2 and the MTRC is ongoing, the V850ES/Fx2 can connect to an external device via the CSIB1 interface.
A special "Last byte control" circuit ensures, that an ongoing CSIB data transfer between the V850ES/Fx2 and an external device is not interrupted by setting PCM0/CS = 1. CSIB1 and EXCSIB1 is disconnected only after data transfer is completed.
- PMCMT4n = 1, PCM0/CS = 1:
PMT40 to PMT42 have no function.

The MTCS pin reflects the status of PCM0/CS, and therefore the mode of the EXCSIB1 pins.

If PMT40 to PMT42 are in port mode (PMCMT4n = 0), they are controlled by the PMT4 control registers.

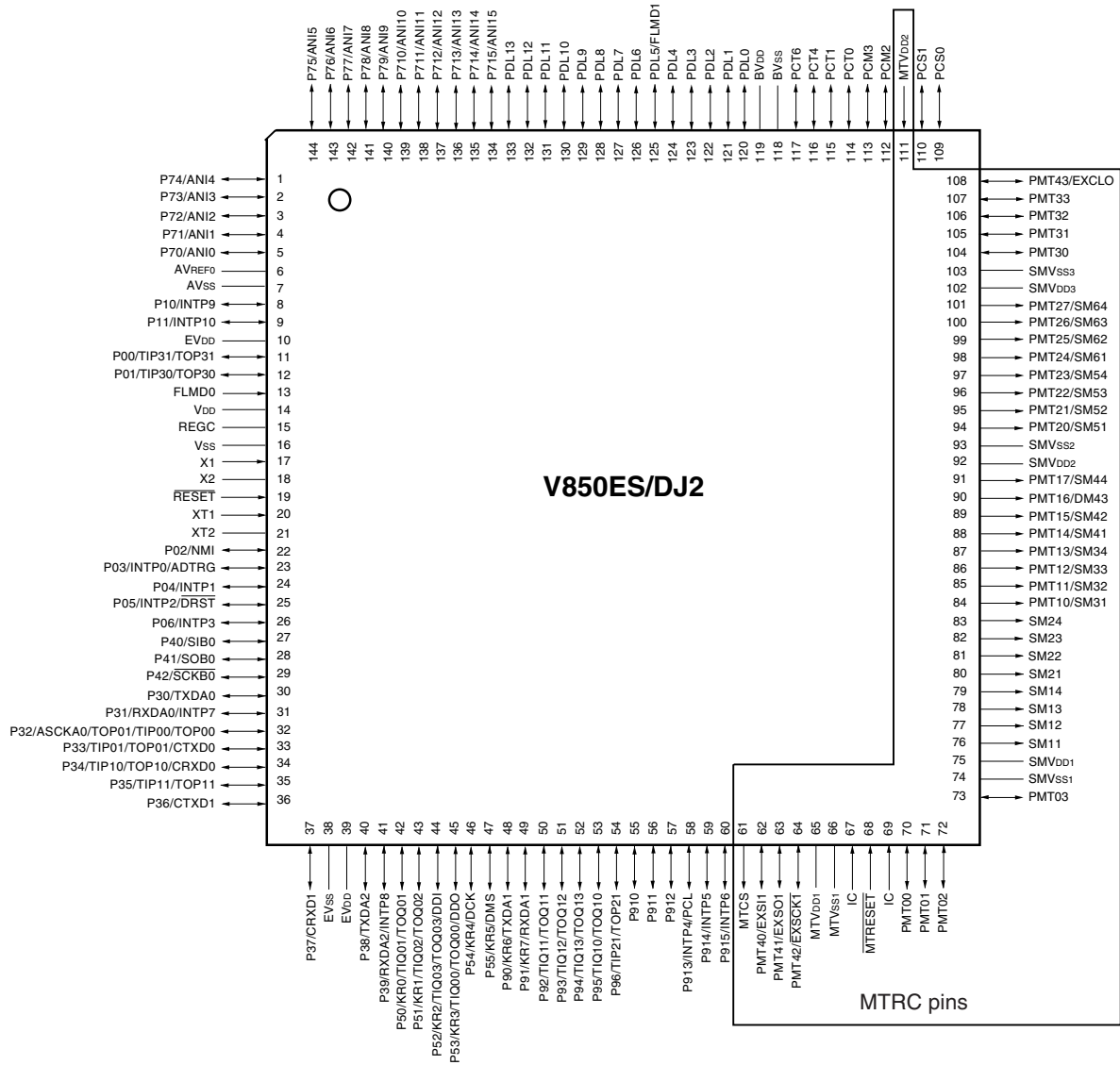
Figure 1-2: CS Functionality



PCM0/CS MTCS	EXCSIB1 signals
1	EXCSIB1 signals have no function
0	EXCSIB1 signals have the function of the V850ES/Fx2's CSIB1 interface pins

1.6 Pinout of DJ2

Figure 1-3: Pinout of DJ2

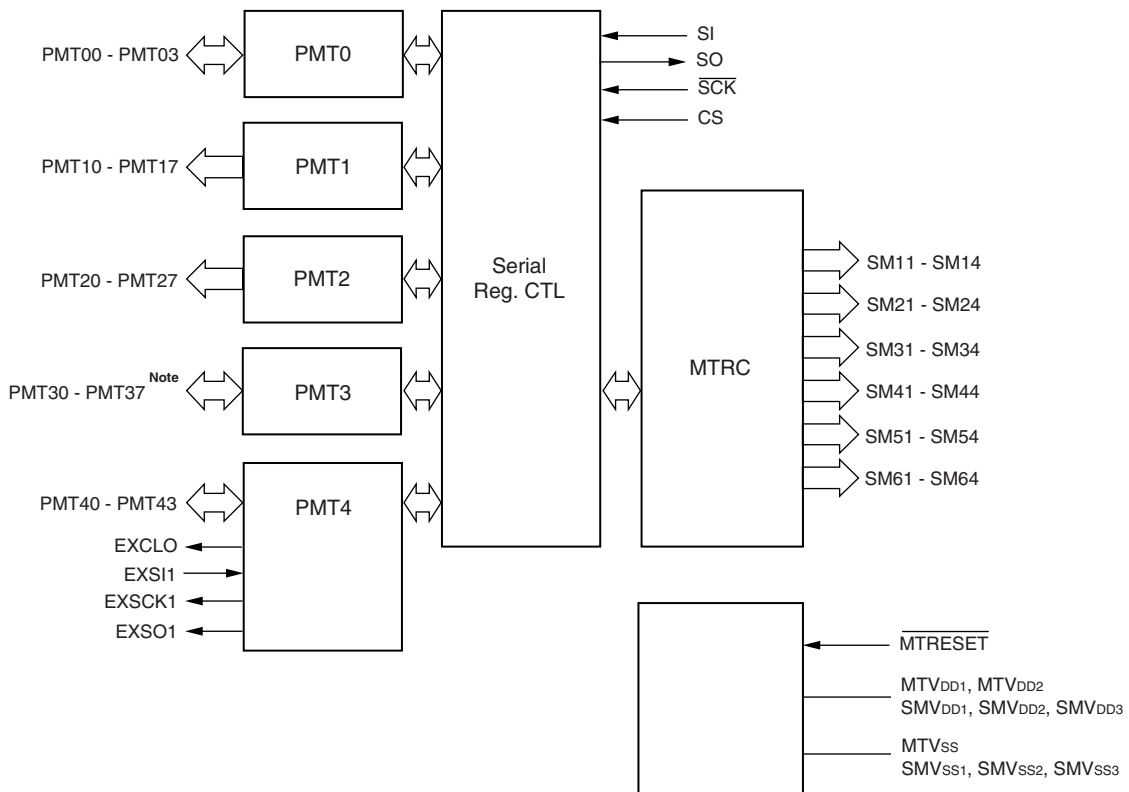


1.7 Overview of MTRC Functions

Table 1-2: Overview of MTRC Functions

Operating Frequency		Max. 16 MHz (typ. 8 MHz)
Meter Driver		360° × 6 channels
Ports	I/O	16
	O	16
Connection between V850ES/Fx2 device and MTRC		3-Wire Serial Interface (CSI) slave mode, 8-bit, single/continuous mode
Power Supply voltage range		4.0 V to 5.5 V

Figure 1-4: Block Diagram of the MTRC



Note: I/O ports of PMT3 are used in the V850ES/DJ2 as follows:

- V850ES/DJ2, 144-pin: PMT30-PMT33

1.8 Peripheral I/O Registers

Table 1-3: Peripheral I/O Registers

Address	Register Name	Symbol	Initial Value After Reset	Access			R/W
				1-bit	8-bit	16-bit	
00H	Compare Register 10	MCMP10	00H		×		R/W
01H	Compare Register 11	MCMP11	00H		×		R/W
02H	Compare Control Register 1	MCMPC1	00H		×		R/W
03H	Compare Register 20	MCMP20	00H		×		R/W
04H	Compare Register 21	MCMP21	00H		×		R/W
05H	Compare Control Register 2	MCMPC2	00H		×		R/W
06H	Compare Register 30	MCMP30	00H		×		R/W
07H	Compare Register 31	MCMP31	00H		×		R/W
08H	Compare Control Register 3	MCMPC3	00H		×		R/W
09H	Compare Register 40	MCMP40	00H		×		R/W
0AH	Compare Register 41	MCMP41	00H		×		R/W
0BH	Compare Control Register 4	MCMPC4	00H		×		R/W
0CH	Compare Register 50	MCMP50	00H		×		R/W
0DH	Compare Register 51	MCMP51	00H		×		R/W
0EH	Compare Control Register 5	MCMPC5	00H		×		R/W
0FH	Compare Register 60	MCMP60	00H		×		R/W
10H	Compare Register 61	MCMP61	00H		×		R/W
11H	Compare Control Register 6	MCMPC6	00H		×		R/W
12H	Timer Mode Control Register 0	MCNTC0	00H		×		R/W
13H	Timer Mode Control Register 1	MCNTC1	00H		×		R/W
20H	Port MT0	PMT0	Undefined		×		R/W
21H	Port MT1	PMT1	Undefined		×		R/W
22H	Port MT2	PMT2	Undefined		×		R/W
23H	Port MT3	PMT3	Undefined		×		R/W
24H	Port MT4	PMT4	Undefined		×		R/W
25H	Port MT0 Mode Register	PMMT0	FFH		×		R/W
26H	Port MT1 Mode Register	PMMT1	FFH		×		R/W
27H	Port MT2 Mode Register	PMMT2	FFH		×		R/W
28H	Port MT3 Mode Register	PMMT3	FFH		×		R/W
29H	Port MT4 Mode Register	PMMT4	FFH		×		R/W
2AH	Port MT1 Mode Control Register	PMCMT1	00H		×		R/W
2BH	Port MT2 Mode Control Register	PMCMT2	00H		×		R/W
2CH	Port MT4 Mode Control Register	PMCMT4	00H		×		R/W
2DH	SM1SM2 Mode Control Register	SM12MC	00H		×		R/W
2EH	Ring Oscillator Control Register	MRCTL	50H		×		R/W
31H	Calibration Register	MRCAL	10H		×		R/W

[MEMO]

Chapter 2 V850ES/FG2 Introduction

The V850ES/FG2 is one of the products of NEC Electronics' V850 Series of single-chip microcontrollers for real-time control.

The V850ES/FG2 is a 32-bit single-chip microcontroller that includes the V850ES CPU core and integrate peripheral functions such as ROM/RAM, DMA controller, and timers/counters. These microcontrollers also incorporate a CAN (Controller Area Network) as an automotive LAN.

In addition to highly real-time responsive, 1-clock-pitch basic instructions, this microcontroller have instructions ideal for digital servo applications, such as multiplication instructions using a hardware multiplier, sum-of-products operation instructions, and bit manipulation instructions. This microcontroller can also realize a real-time control system that is highly cost effective and can be used in automotive instrumentation fields.

- Number of instructions: 83
- Minimum instruction execution time: 50 ns (main clock (f_{xx}) = 20 MHz)
- General-purpose registers: 32 bits \times 32
- Power-on clear function
- Low-voltage detection function
- Ring-OSC: 200 kHz (TYP.)
- Interrupts/exceptions
 - Non-maskable interrupts
 - Maskable interrupts
- I/O lines I/O ports: 84
- Timer/counters
 - 16-bit interval timer M (TMM): 1 ch
 - 16-bit timer/event counter P (TMP): 4 ch
 - 16-bit timer/event counter Q (TMQ): 2 ch
- Watch timer: 1 ch
- Watchdog timer 2: 1 ch
- Serial interface (SIO)
 - Asynchronous serial interface A (UART)
 - 3-wire variable-length serial interface B (CSIB)
- CAN controller: 2 ch
- A/D converter 10-bit resolution: 16 ch

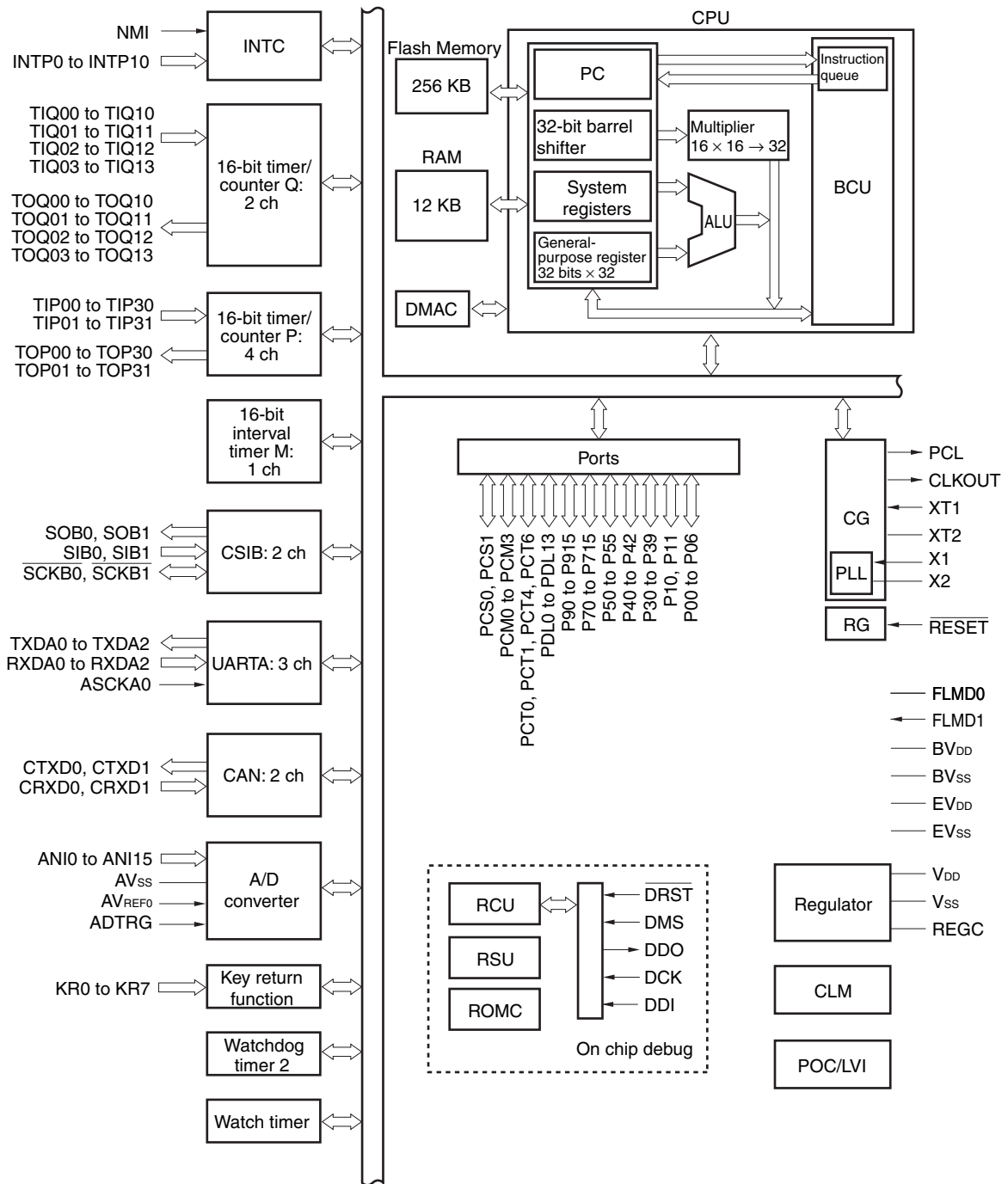
- Clock generator
 - Main clock/subclock operation
 - CPU clock in seven steps (f_{xx} , $f_{xx}/2$, $f_{xx}/4$, $f_{xx}/8$, $f_{xx}/16$, $f_{xx}/32$, f_{xT})
 - Clock-through mode/PLL mode selectable

- Power save function
 - HALT
 - IDLE1
 - IDLE2
 - software STOP
 - subclock
 - sub-IDLE modes

Pin identification

ADTRG:	A/D trigger input	PCM0 to PCM3:	Port CM
ANI0 to ANI15:	Analog input	PCS0, PCS1:	Port CS
ASCKA0:	Asynchronous serial clock	PCT0, PCT1,	
AV _{REF0} :	Analog reference voltage	PCT4, PCT6:	Port CT
AV _{SS} :	Analog V _{SS}	PDL0 to PDL13:	Port DL
BV _{DD} :	Power supply for bus interface	REGC:	Regulator control
BV _{SS} :	Ground for bus interface	RESET:	Reset
CLKOUT:	Clock output	RXDA0 to RXDA2:	Receive data
CRXD0, CRXD1:	Receive data for controller area network	SCKB0, SCKB1:	Serial clock
CTXD0, CTXD1:	Transmit data for controller area network	SIB0, SIB1:	Serial input
DCK:	Debug clock	SOB0, SOB1:	Serial output
DDI:	Debug data input	TIP00, TIP01,	
DDO:	Debug data output	TIP10, TIP11,	
DMS:	Debug mode select	TIP20, TIP21,	
DRST:	Debug reset	TIP30, TIP31,	
EV _{DD} :	Power supply for port	TIQ00 to TIQ03,	
EV _{SS} :	Ground for port	TIQ10 to TIQ13:	Timer input
FLMD0, FLMD1:	Flash programming mode	TOP00, TOP01,	
INTP0 to INTP10:	Interrupt request from peripherals	TOP10, TOP11,	
KR0 to KR7:	Key return	TOP20, TOP21,	
NMI:	Non-maskable interrupt request	TOP30, TOP31,	
P00 to P06:	Port 0	TOQ01 to TOQ03,	
P10, P11:	Port 1	TOQ11 to TOQ13:	Timer output
P30 to P39:	Port 3	TXDA0 to TXDA2:	Transmit data
P40 to P42:	Port 4	V _{DD} :	Power supply
P50 to P55:	Port 5	V _{SS} :	Ground
P70 to P715:	Port 7	X1, X2:	Crystal for main clock
P90 to P915:	Port 9	XT1, XT2:	Crystal for subclock
PCL:	Programmable clock output		

Figure 2-1: V850ES/FG2 - μ PD70F3235 Block Diagram



2.1 Pin Functions

This section explains the names and functions of the pins of the V850ES/FG2.

Three I/O buffer power supplies, AV_{REF0} , BV_{DD} and EV_{DD} , are available. The relationship between the power supplies and the pins is shown below.

Table 2-1: Pin I/O Buffer Power Supplies (V850ES/FG2)

Power Supply	Corresponding Pin
AV_{REF0}	Port 7
EV_{DD}	Port 0, Port 1, Port 3, Port 4, Port 5, Port 9, RESET
BV_{DD}	Port CM, Port CS, Port CT, Port DL

Table 2-2: Pin List (Port Pins)

Pin Name	I/O	Function	Alternate Function
P00	I/O	Port 0 7-bit I/O port Input/output can be specified in 1-bit units.	TIP31/TOP31
P01			TIP30/TOP30
P02			NMI
P03			INTP0/ADTRG
P04			INTP1
P05			INTP2/DRST
P06			INTP3
P10	I/O	Port 1 2-bit I/O port Input/output can be specified in 1-bit units.	INTP9
P11			INTP10
P30	I/O	Port 3 10-bit I/O port Input/output can be specified in 1-bit units.	TXDA0
P31			RXDA0/INTP7
P32			ASCKA0/TIP00/TOP00/ TOP01
P33			TIP01/TOP01/CTXD0
P34			TIP10/TOP10/CRXD0
P35			TIP11/TOP11
P36			CTXD1
P37			CRXD1
P38			TXDA2
P39			RXDA2/INTP8
P40	I/O	Port 4 3-bit I/O port Input/output can be specified in 1-bit units.	SIB0
P41			SOB0
P42			SCKB0

Table 2-2: Pin List (Port Pins) (Continued)

Pin Name	I/O	Function	Alternate Function
P50	I/O	Port 5 6-bit I/O port Input/output can be specified in 1-bit units.	KR0/TIQ01/TOQ01
P51			KR1/TIQ02/TOQ02
P52			KR2/TIQ03/TOQ03/DDI
P53			KR3/TIQ00/TOQ00/DDO
P54			KR4/DCK
P55			KR5/DMS
P70 to P715	I/O	Port 7 16-bit I/O port Input/output can be specified in 1-bit units.	ANI0 to ANI15
P90	I/O	Port 9 16-bit I/O port Input/output can be specified in 1-bit units.	KR6/TXDA1
P91			KR7/RXDA1
P92			TIQ11/TOQ11
P93			TIQ12/TOQ12
P94			TIQ13/TOQ13
P95			TIQ10/TOQ10
P96			TIP21/TOP21
P97			SIB1/TIP20/TOP20
P98			SOB1
P99			SCKB1
P910			-
P911			-
P912			-
P913			INTP4/PCL
P914			INTP5
P915	INTP6		
PCM0	I/O	Port CM 4-bit I/O port Input/output can be specified in 1-bit units.	-
PCM1			CLKOUT
PCM2, PCM3			-
PCS0, PCS1	I/O	Port CS 2-bit I/O port Input/output can be specified in 1-bit units.	-
PCT0, PCT1, PCT4, PCT6	I/O	Port CT 4-bit I/O port Input/output can be specified in 1-bit units.	- -
PDL0 to PDL4	I/O	Port DL 14-bit I/O port Input/output can be specified in 1-bit units.	-
PDL5			FLMD1
PDL6 to PDL13			-

Table 2-3: Pin List (Non-Port Pins)

Pin Name	I/O	Function	Alternate Function
NMI	Input	External interrupt input (non-maskable, with analog noise eliminated)	P02
INTP0	Input	External interrupt request input (maskable, with analog noise eliminated)	P03/ADTRG
INTP1			P04
INTP2			P05/DRST
INTP3			P06
INTP4			P913/PCL
INTP5			P914
INTP6			P915
INTP7			P31/RXDA0
INTP8			P39/RXDA2
INTP9			P10
INTP10			P11
TIP00	Input	External event/clock input (TMP00)	P32/ASCKA0/TOP00/TOP01
TIP01		External event/clock input (TMP01)	P33/TOP01/CTXD0
TIP10		External event/clock input (TMP10)	P34/TOP10/CRXD0
TIP11		External event/clock input (TMP11)	P35/TOP11
TIP20		External event/clock input (TMP20)	P97/SIB1/TOP20
TIP21		External event/clock input (TMP21)	P96/TOP21
TIP30		External event/clock input (TMP30)	P01/TOP30
TIP31		External event/clock input (TMP31)	P00/TOP31
TOP00	Output	Timer output (TMP00)	P32/ASCKA0/TIP00/TOP01
TOP01		Timer output (TMP01)	P32/ASCKA0/TIP00/TOP00 P33/TIP01/CTXD0
TOP10		Timer output (TMP10)	P34/TIP10/CRXD0
TOP11		Timer output (TMP11)	P35/TIP11
TOP20		Timer output (TMP20)	P97/SIB1/TIP20
TOP21		Timer output (TMP21)	P96/TIP21
TOP30		Timer output (TMP30)	P01/TIP30
TOP31		Timer output (TMP31)	P00/TIP31
TIQ00	Input	External event/clock input (TMQ00)	P53/KR3/TOQ00/DDO
TIQ01		External event input (TMQ01)	P50/KR0/TOQ01
TIQ02		External event input (TMQ02)	P51/KR1/TOQ02
TIQ03		External event input (TMQ03)	P52/KR2/TOQ03/DDI
TIQ10		External event input (TMQ10)	P95/TOQ10
TIQ11		External event input (TMQ11)	P92/TOQ11
TIQ12		External event input (TMQ12)	P93/TOQ12
TIQ13		External event input (TMQ13)	P94/TOQ13

Table 2-3: Pin List (Non-Port Pins) (Continued)

Pin Name	I/O	Function	Alternate Function
TOQ00	Output	Timer output (TMQ00)	P53/KR3/TIQ00/DDO
TOQ01		Timer output (TMQ01)	P50/KR0/TIQ01
TOQ02		Timer output (TMQ02)	P51/KR1/TIQ02
TOQ03		Timer output (TMQ03)	P52/KR2/TIQ03/DDI
TOQ10		Timer output (TMQ10)	P95/TIQ10
TOQ11		Timer output (TMQ11)	P92/TIQ11
TOQ12		Timer output (TMQ12)	P93/TIQ12
TOQ13		Timer output (TMQ13)	P94/TIQ13
SIB0	Input	Serial receive data input (CSIB0)	P40
SIB1		Serial receive data input (CSIB1)	P97/TIP20/TOP20
SOB0	Output	Serial transmit data output (CSIB0)	P41
SOB1		Serial transmit data output (CSIB1)	P98
SCKB0	I/O	Serial clock I/O (CSIB0)	P42
SCKB1		Serial clock I/O (CSIB1)	P99
RXDA0	Input	Serial receive data input (UARTA0)	P31/INTP7
RXDA1		Serial receive data input (UARTA1)	P91/KR7
RXDA2		Serial receive data input (UARTA2)	P39/INTP8
TXDA0	Output	Serial transmit data output (UARTA0)	P30
TXDA1		Serial transmit data output (UARTA1)	P90/KR6
TXDA2		Serial transmit data output (UARTA2)	P38
ASCKA0	Input	Baud rate clock input to UARTA0	P32/TIP00/TOP00/TOP01
CRXD0	Input	CAN receive data input (CAN0)	P34/TIP10/TOP10
CRXD1		CAN receive data input (CAN1)	P37
CTXD0	Output	CAN transmit data output (CAN0)	P33/TIP01/TOP01
CTXD1		CAN transmit data output (CAN1)	P36
ANI0 to ANI15	Input	Analog voltage input to A/D converter	P70 to P715
AV _{REF0}	Input	Reference voltage input to A/D converter (same potential as V _{DD})	–
AV _{SS}	–	Ground potential for A/D and D/A converters (same potential as V _{SS})	–
ADTRG	Input	A/D converter external trigger input	P03/INTP0
KR0	Input	Key interrupt input	P50/TIQ01/TOQ01
KR1			P51/TIQ02/TOQ02
KR2			P52/TIQ03/TOQ03/DDI
KR3			P53/TIQ00/TOQ00/DDO
KR4			P54/DCK
KR5			P55/DMS
KR6			P90/TXDA1
KR7			P91/RXDA1
DMS	Input	Debug mode select	P55/KR5
DDI	Input	Debug data input	P52/KR2/TIQ03/TOQ03
DDO	Output	Debug data output	P53/KR3/TIQ00/TOQ00

Table 2-3: Pin List (Non-Port Pins) (Continued)

Pin Name	I/O	Function	Alternate Function
DCK	Input	Debug clock input	P54/KR4
DRST	Input	Debug reset input	P05/INTP2
FLMD0	Input	Flash programming mode setting pins	-
FLMD1			PDL5
CLKOUT	Output	Internal system clock output	PCM1
PCL	Output	Clock output (timing output of X1 input clock and sub-clock)	P913/INTP4
REGC	-	Regulator output stabilizing capacitor connection	-
RESET	Input	System reset input	-
X1	Input	Main clock resonator connection	-
X2	-		-
XT1	Input	Subclock resonator connection	-
XT2	-		-
V _{DD}	-	Positive power supply pin for internal circuitry	-
V _{SS}	-	Ground potential for internal circuitry	-
EV _{DD}	-	Positive power supply pin for external circuitry (same potential as V _{DD})	-
EV _{SS}	-	Ground potential for external circuitry (same potential as V _{SS})	-
BV _{DD}	-	Positive power supply pin for external circuitry (same potential as V _{DD})	-
BV _{SS}	-	Ground potential for external circuitry (same potential as V _{SS})	-

Table 2-4: Pin I/O Circuit Types and Recommended Connection of Unused Pins

Pin	I/O Circuit Type	Recommended Connection
P00/TIP31/TOP31	5-W	Input: Independently connect to EVDD or EVSS via a resistor Output: Leave open
P01/TIP30/TOP30		
P02/NMI		
P03/INTP0/ADTRG		
P04/INTP1		
P05/INTP2/DRST	5-AF	Input: Independently connect to EVSS via a resistor Output: Leave open
P06/INTP3	5-W	Input: Independently connect to EVDD or EVSS via a resistor Output: Leave open
P10/INTP9	5-W	Input: Independently connect to EVDD or EVSS via a resistor Output: Leave open
P11/INTP10		
P30/TXDA0	5-A	Input: Independently connect to EVDD or EVSS via a resistor Output: Leave open
P31/RXDA0/INTP7	5-W	
P32/ASCKA0/TIP00/TOP00/ TOP01		
P33/TIP01/TOP01/CTXD0		
P34/TIP10/TOP10/CRXD0		
P35/TIP11/TOP11		
P36/CTXD1	5-A	
P37/CRXD1	5-W	
P38/TXDA2	5-A	
P39/RXDA2/INTP8	5-W	
P40/SIB0	5-W	
P41/SOB0	5-A	
P42/SCKB0	5-W	
P50/KR0/TIQ01/TOQ01	5-W	Input: Independently connect to EVDD or EVSS via a resistor Output: Leave open
P51/KR1/TIQ02/TOQ02		
P52/KR2/TIQ03/TOQ03/DDI		
P53/KR3/TIQ00/TOQ00/DDO		
P54/KR4/DCK		
P55/KR5/DMS		
P70/ANI0 to P711/ANI11	11-G	Input: Independently connect to AVREF0 or AVSS via a resistor Output: Leave open
P712/ANI12 to P715/ANI15		
P90/KR6/TXDA1	5-W	Input: Independently connect to EVDD or EVSS via a resistor Output: Leave open
P91/KR7/RXDA1		
P92/TIQ11/TOQ11		
P93/TIQ12/TOQ12		
P94/TIQ13/TOQ13		
P95/TIQ10/TOQ10		

Table 2-4: Pin I/O Circuit Types and Recommended Connection of Unused Pins (Continued)

P96/TIP21/TOP21	5-W	Input: Independently connect to EVDD or EVSS via a resistor Output: Leave open	
P97/SIB1/TIP20/TOP20			
P98/SOB1			5-A
P99/SCKB1			5-W
P910	5-A		
P911			
P912			
P913/INTP4/PCL	5-W		
P914/INTP5			
P915/INTP6			
PCM0	5	Input: Independently connect to BVDD or BVSS via a resistor Output: Leave open	
PCM1/CLKOUT			
PCM2, PCM3			
PCS0, PCS1	5	Input: Independently connect to BVDD or BVSS via a resistor Output: Leave open	
PCT0, PCT1, PCT4, PCT6	5	Input: Independently connect to BVDD or BVSS via a resistor Output: Leave open	
PDL0 to PDL4	5	Input: Independently connect to BVDD or BVSS via a resistor Output: Leave open	
PDL5/ FLMD1			
PDL6 to AD13			
AVREF0	-	Directly connect to VDD	
AVSS	-	-	
FLMD0 ^a	-	Directly connect to VSS	
REGC	-	-	
RESET	2	-	
X1	-	-	
X2	-	-	
XT1	16	Connect to VSS via a resistor	
XT2	16	Leave open	
VDD	-	-	
VSS	-	-	
BVDD	-	-	
BVSS	-	-	
EVDD	-	-	
EVSS	-	-	

- a. If noise that exceeds the noise elimination width is input to the RESET pin during self programming, the flash on-board mode may be entered depending on the capacitance charge end timing when a capacitor is connected to the FLMD0 pin. Therefore, do not connect a capacitor to the FLMD0 pin.

Figure 2-2: Pin I/O Circuit Types (1/2)

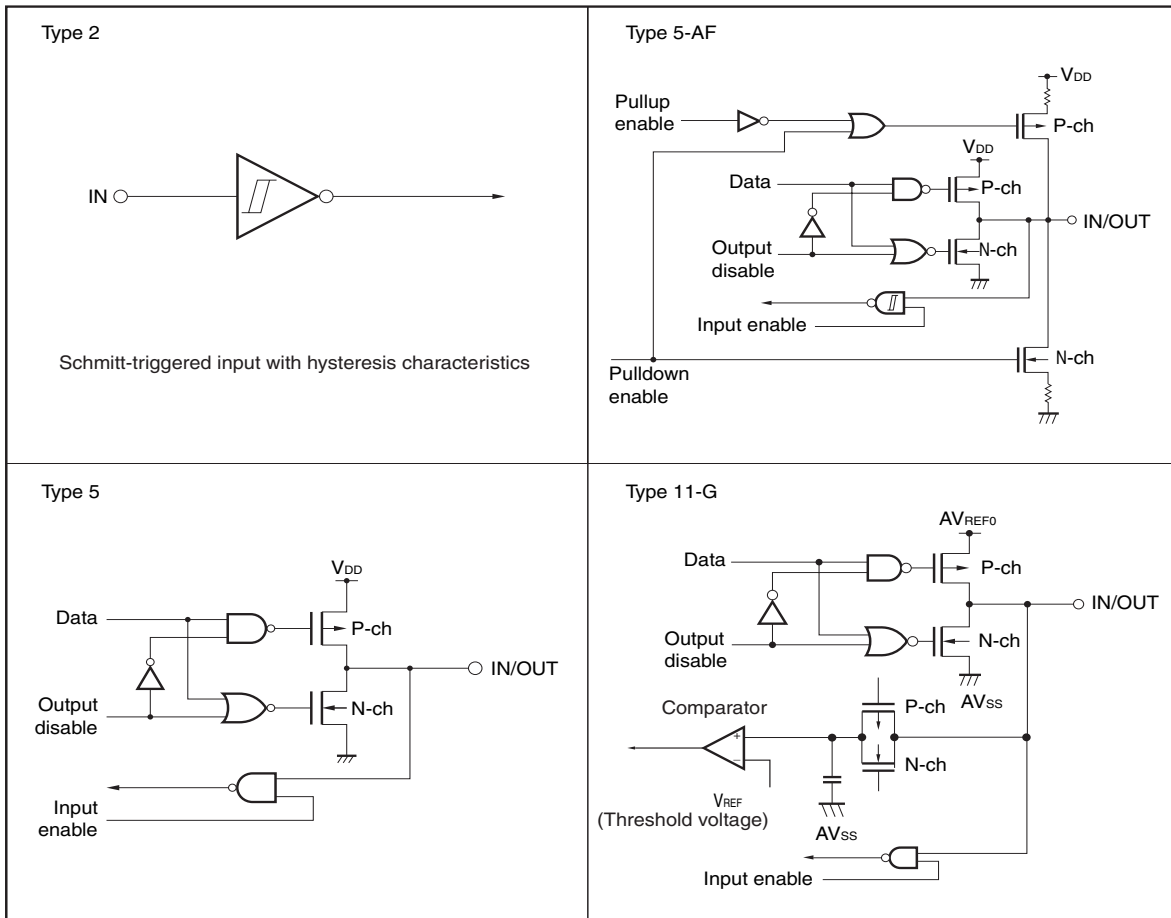
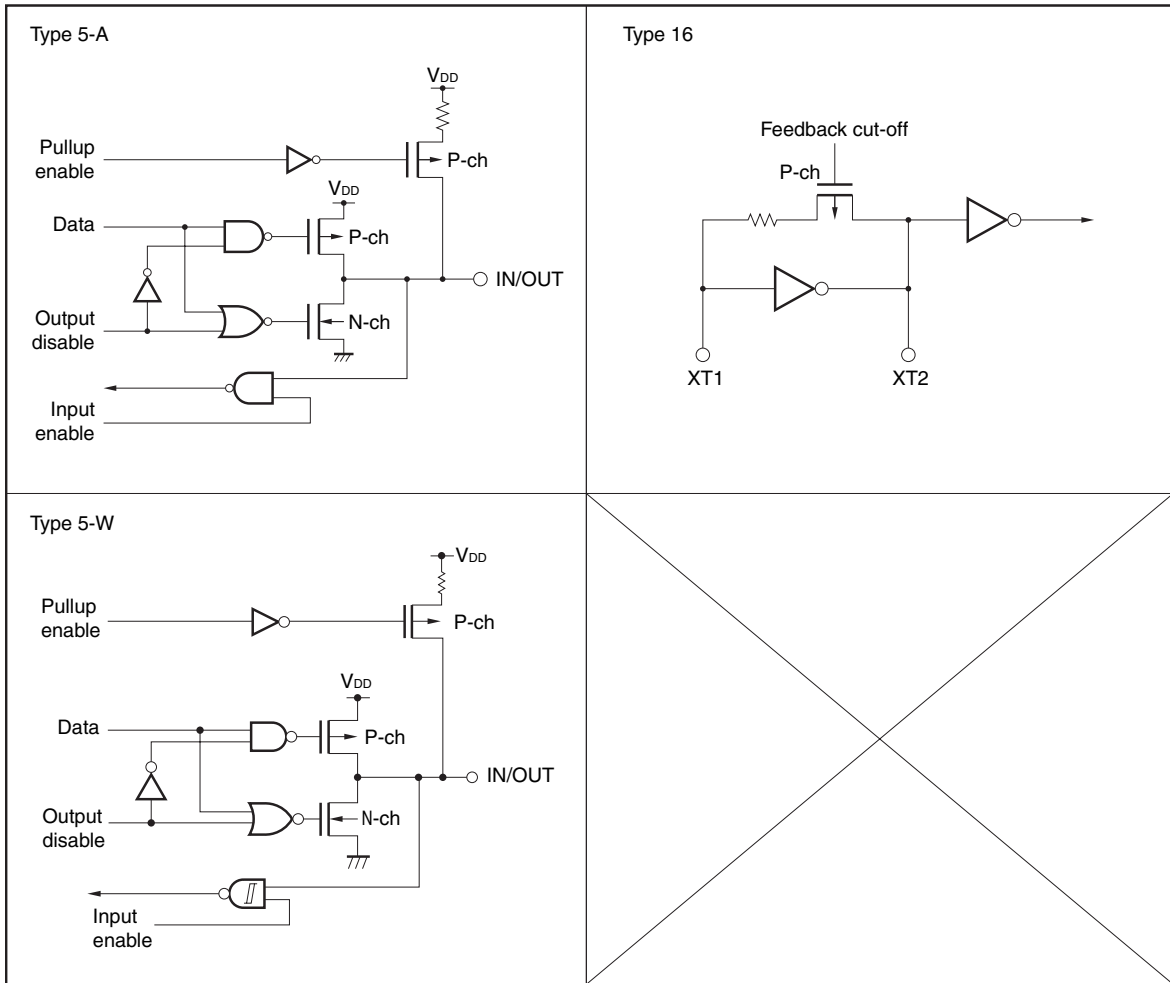


Figure 2-3: Figure 2-1. Pin I/O Circuit Types (2/2)



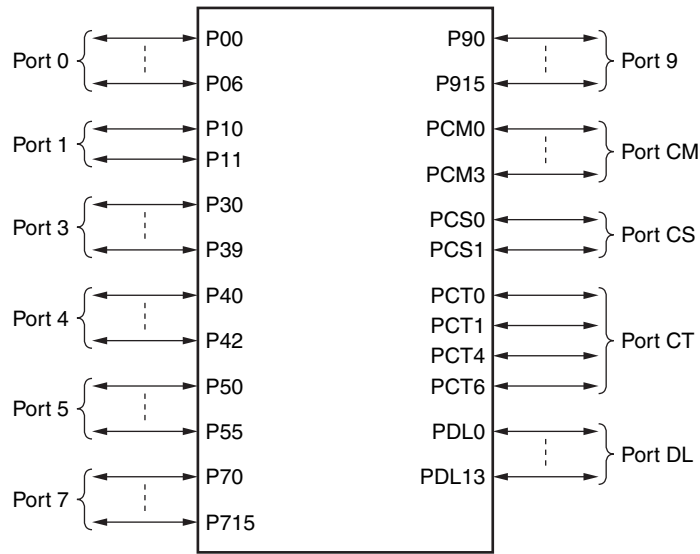
2.2 Port Functions

Features

- I/O ports: 84
- Port pins function alternately as other peripheral-function I/O pins
- Can be set in input or output mode in 1-bit units.

The V850ES/FG2 has a total of 84 I/O ports, ports 0, 1, 3 to 5, 7, 9, CM, CS, CT, and DL. The port configuration is shown below.

Figure 2-4: Port Configuration



2.3 CPU Functions

Based on the RISC architecture, the CPU of the V850ES/FG2 executes most of the instructions in one clock under control of a five-stage pipeline.

Features

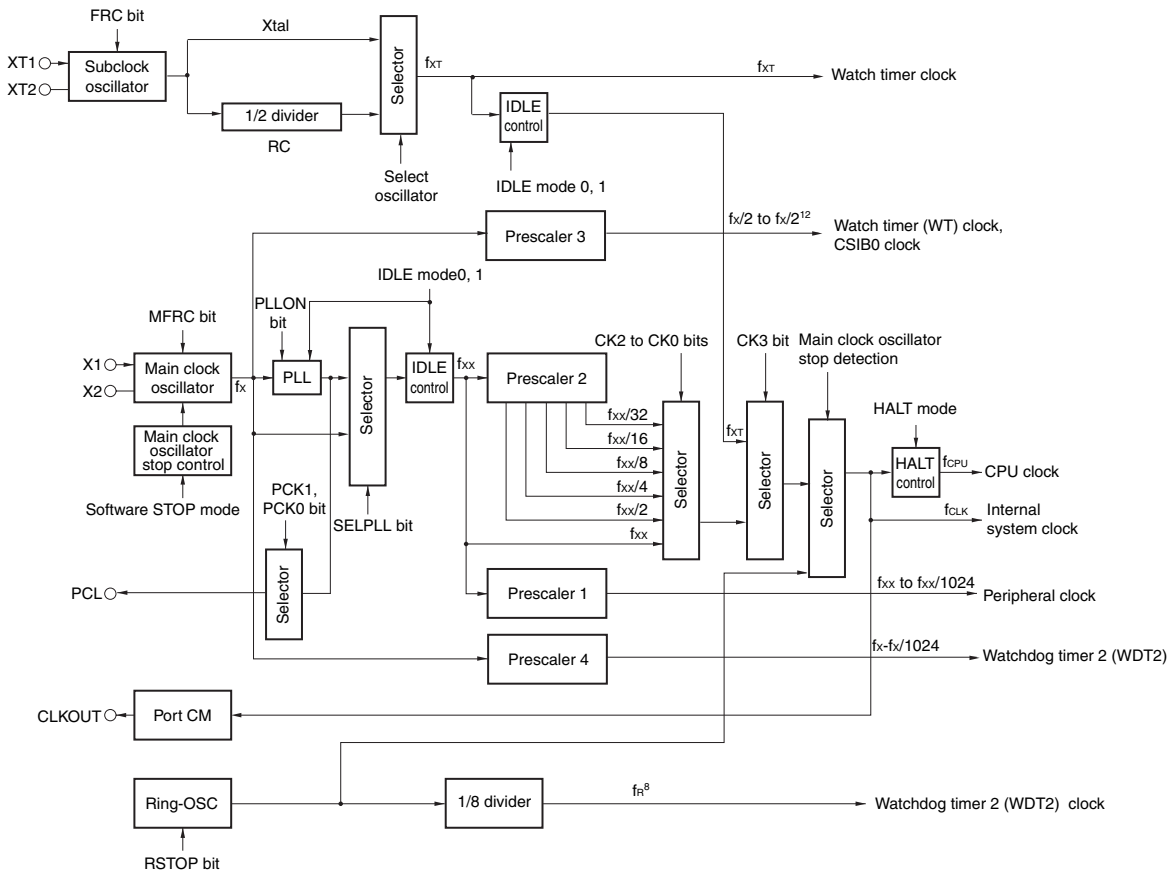
- Minimum instruction execution time: 50 ns (at 20 MHz operation)
- Memory space
 - Program space: 64 MB, linear
 - Data space: 4 GB, linear
- General-purpose registers: 32 bits × 32
- Internal 32-bit architecture
- Five-stage pipeline control
- Multiplication/division instructions
- Saturation operation instructions
- 32-bit shift instructions: 1 clock
- Load/store instructions with long/short format
- Four types of bit manipulation instructions
 - SET1
 - CLR1
 - NOT1
 - TST1

2.4 Clock Generation Function

The following clock generation functions are available.

- Main clock oscillator
- In clock-through mode
 $f_x = 4$ to 5 MHz ($f_{xx} = 4$ to 5 MHz)
- In PLL (Phase Locked Loop) mode
 $f_x = 4$ to 5 MHz ($f_{xx} = 16$ to 20 MHz)
- Subclock oscillator (sub-resonator)
- 32.768 kHz
- 20 kHz (RCR = 390 k Ω , C = 47 pF)
- Multiply ($\times 4$) function via PLL (Phase Locked Loop)
- Clock-trough mode/PLL mode selectable
- Ring OSC
- $f_R = 100$ to 400 kHz
- Internal system clock generation
- 7 steps (f_{xx} , $f_{xx}/2$, $f_{xx}/4$, $f_{xx}/8$, $f_{xx}/16$, $f_{xx}/32$, f_{xt})
- Peripheral clock generation
- Clock output function
- Programmable clock output (PCL) function

Figure 2-5: Clock Generator



2.5 16-bit Timer/event Counter P

The V850ES/FG2 includes 16-bit timer/event counter P (TMP0 to TMP3).

Features

Timer P (TMP) is a 16-bit timer/event counter that can be used in various ways. TMP can perform the following operations.

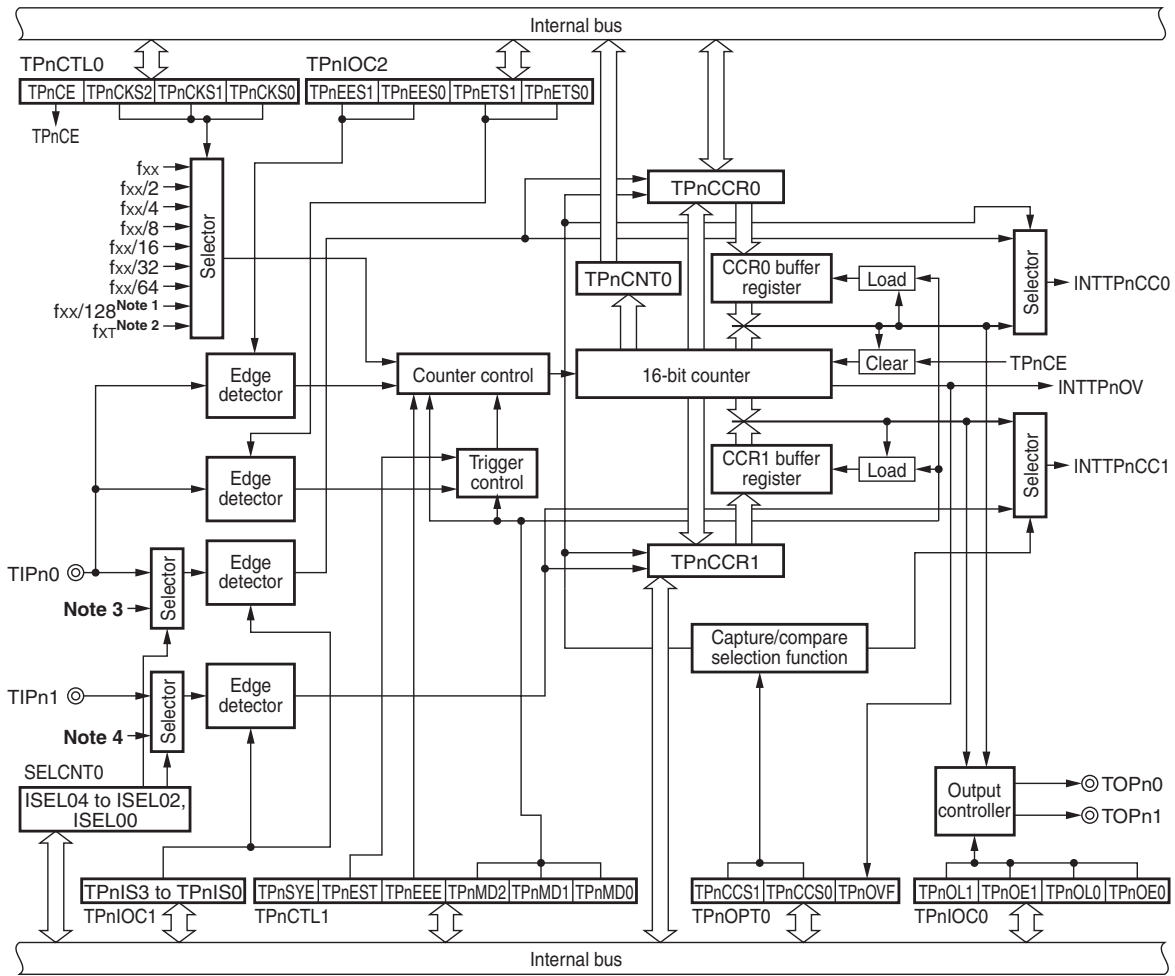
- PWM output
- Interval timer
- External event counter (operation disabled when clock is stopped)
- One-shot pulse output
- Pulse width measurement function
- Timer synchronized operation function
- Free-running function
- External trigger pulse output function

Functional Outline

- Capture trigger input signal × 2
- External trigger input signal × 1
- Clock selection × 8
- External event count input × 1
- Readable counter × 1
- Capture/compare reload register × 2
- Capture/compare match interrupt × 2
- Timer output (TOPn0, TOPn1) × 2

Remark: n = 0 to 3

Figure 2-6: Figure 6-1. Block Diagram of Timer P



- Notes:**
1. TMP0, TMP2
 2. TMP1, TMP3 (when main clock is stopped, count operation by subclock cannot be performed.)
 3. TSOUT signal of CAN0 block (TMP0)
RXDA0 pin (TMP1)
 4. INTTM0EQ0 interrupt of TMM block or TSOUT signal of CAN1 block (TMP0)
RXDA1 pin (TMP1)

Remark: n = 0 to 3

2.6 16-bit Timer/event Counter Q

The V850ES/FG2 includes 16-bit timer/event counter Q (TMQ0, TMQ1).

Features

Timer Q (TMQ) is a 16-bit timer/event counter that can be used in various ways. TMQ can perform the following operations.

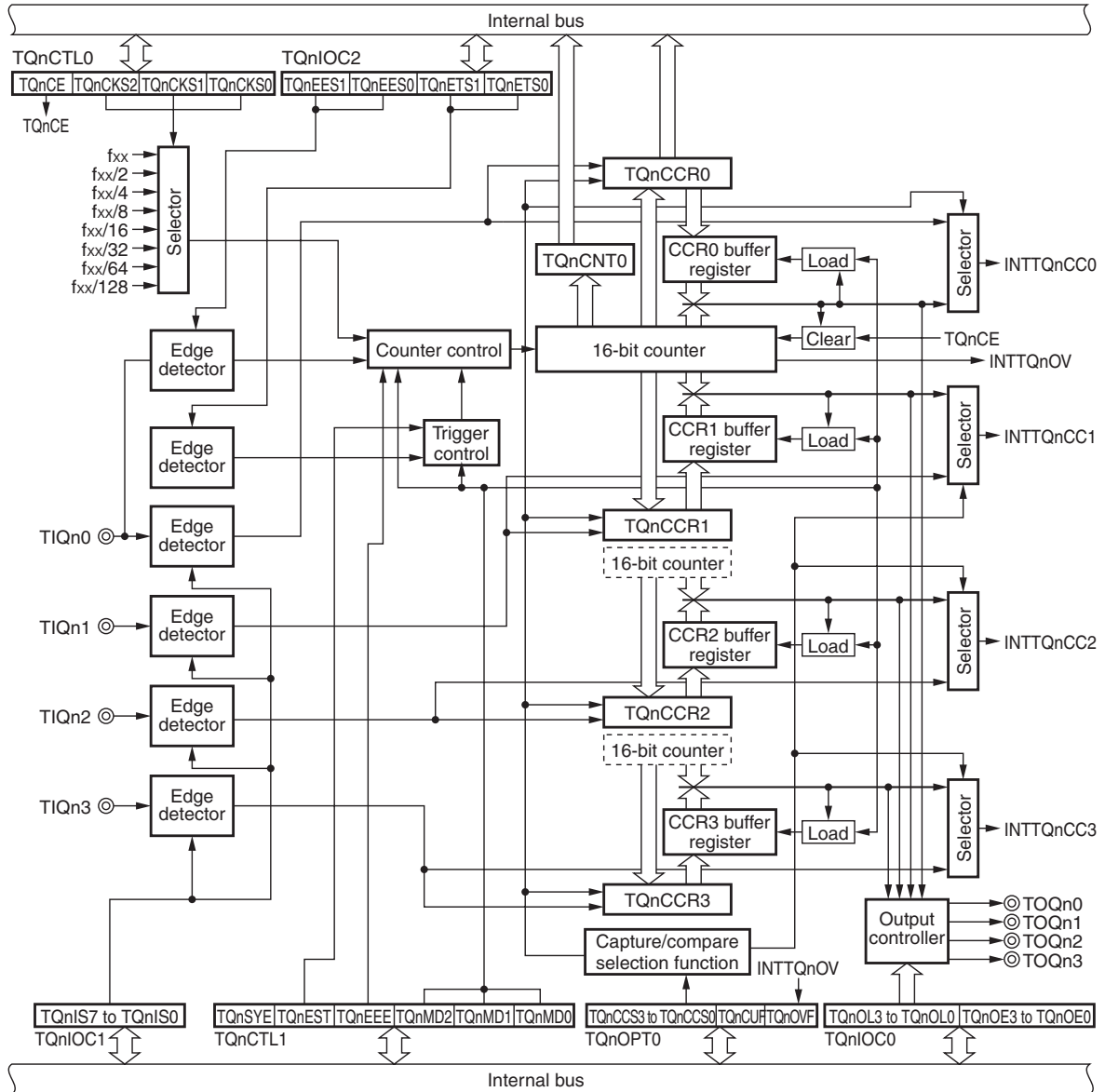
- PWM output
- Interval timer
- External event counter (operation disabled when clock is stopped)
- One-shot pulse output
- Pulse width measurement function
- Triangular wave PWM output
- Timer synchronized operation function

Functional Outline

- Capture trigger input signal × 4
- External trigger input signal × 1
- Clock selection × 8
- External event count input × 1
- Readable counter × 1
- Capture/compare reload register × 4
- Capture/compare match interrupt × 4
- Timer output (TOQn0 to TOQn3) × 4

Remark: n = 0, 1

Figure 2-7: Figure 7-1. Block Diagram of Timer Q



Remark: n = 0, 1

2.7 16-bit Interval Timer M

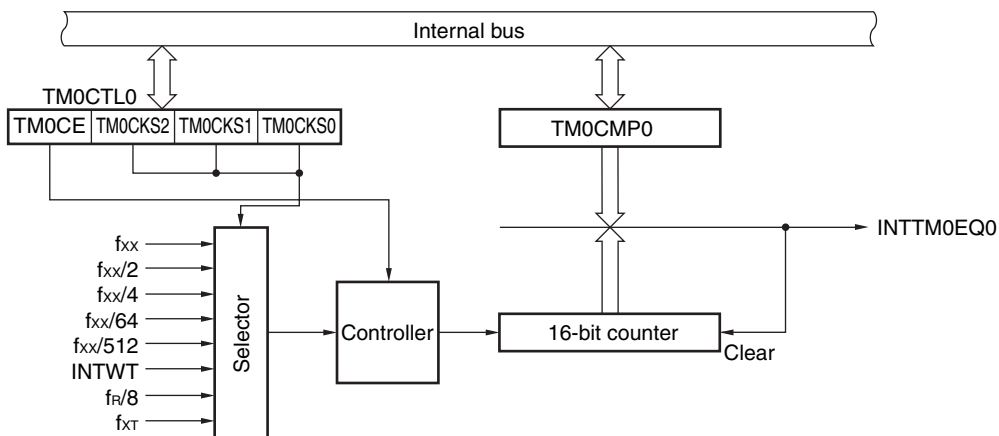
The V850ES/FG2 includes 16-bit interval timer M (TMM0).

Features

Timer M (TMM) supports only a clear & start mode. It does not support a free-running mode. To use timer M in a manner equivalent to in the free-running mode, set the compare register to FFFFH and start the 16-bit counter. A match interrupt will occur when the timer overflows.

- Interval function
- Clock selection × 8
- Simple counter × 1
(The simple counter is a counter that does not use a counter read buffer. This counter cannot be read during timer count operation.)
- Simple compare × 1
(The simple compare register is a register that does not use a compare write buffer. No data can be written to this compare register during timer count operation.)
- Compare match interrupt × 1

Figure 2-8: Block Diagram of Timer M



2.8 Watch Timer Functions

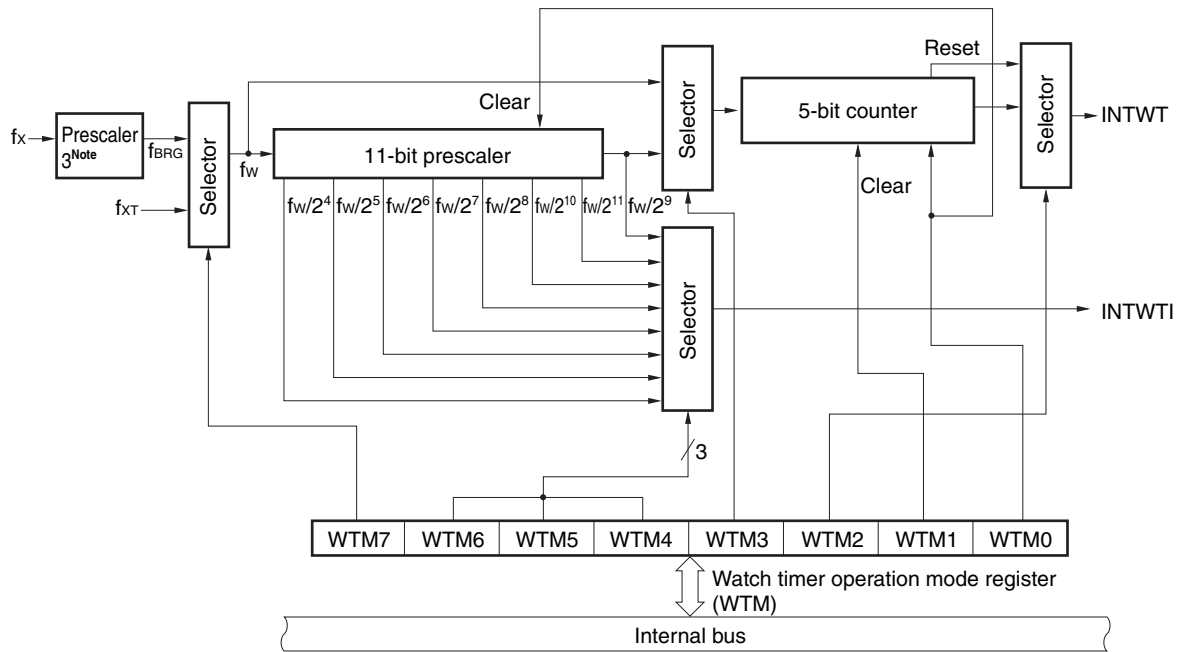
Features

The watch timer has the following functions.

- Watch timer
- Interval timer

The watch timer and interval timer functions can be used at the same time.

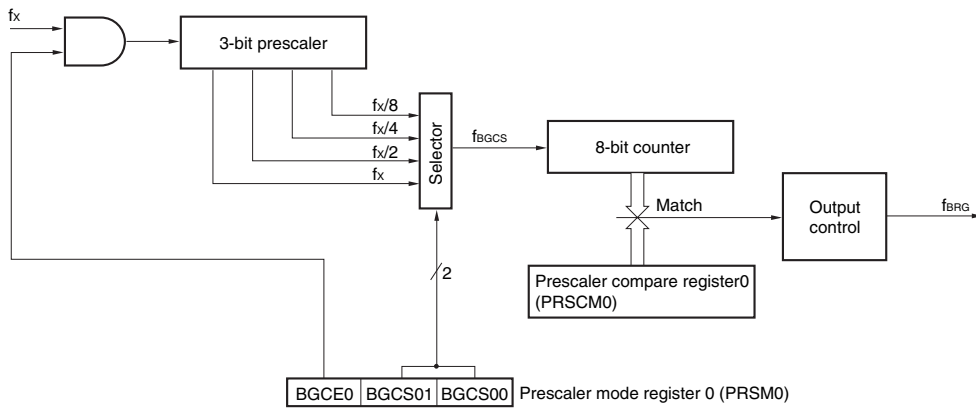
Figure 2-9: Block Diagram of Watch Timer



Note: For details of prescaler 3, see Figure 2-10 “Block Diagram of Prescaler 3”.

- Remarks:**
1. f_{BRG} : Prescaler 3 output frequency
 2. f_x : Oscillation frequency
 3. f_{XT} : Subclock frequency
 4. f_w : Watch timer clock frequency
 5. INTWT: Watch timer interrupt
 6. INTWTI: Interval timer interrupt

Figure 2-10: Block Diagram of Prescaler 3



Remark: f_{BGCS} : Prescaler 3 count clock frequency

1. f_{BRG} : Prescaler 3 output frequency
2. f_x : Oscillation frequency

2.9 Functions of Watchdog Timer 2

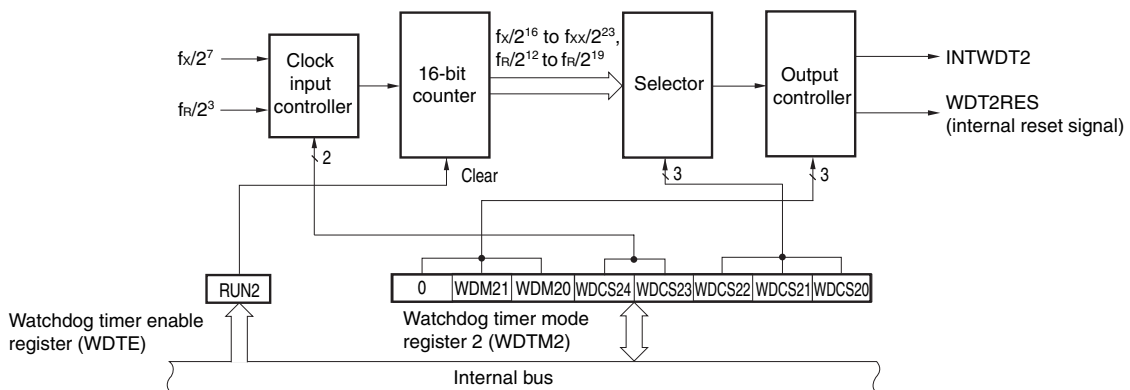
Features

Watchdog timer 2 has the following functions.

- Default-start watchdog timer
 - →Reset mode: Reset operation upon overflow of watchdog timer 2 (generation of WDT2RES signal)
 - →Non-maskable interrupt request mode: NMI operation upon overflow of watchdog timer 2 (generation of INTWDT2 signal)^{Note}
- Input selectable from main clock and Ring-OSC as the source clock

Note: Restoring using the RETI instruction following non-maskable interrupt servicing due to a non-maskable interrupt request signal (INTWDT2) is not possible. Therefore, following completion of interrupt servicing, perform a system reset.

Figure 2-11: Block Diagram of Watchdog Timer 2



- Remarks:**
1. f_x : Oscillation frequency
 2. f_R : Ring-OSC clock frequency
 3. INTWDT2: Non-maskable interrupt request signal from watchdog timer 2
 4. WDT2RES: Watchdog timer 2 reset signal

2.10 A/D Converter

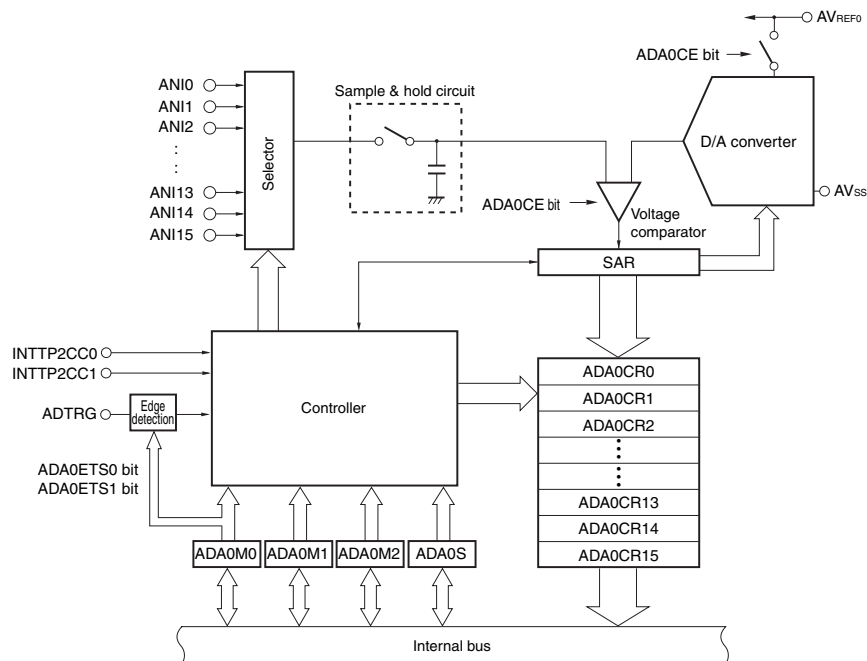
Features

The A/D converter converts analog input signals into digital values, has a resolution of 10 bits, and can handle 16 analog input signal channels (ANI0 to ANI15).

The A/D converter has the following features.

- 10-bit resolution
- 16 channels
- Successive approximation method
- Operating voltage: $AV_{REF0} = 4.0$ to 5.5 V
- Analog input voltage: 0 V to AV_{REF0}
- The following functions are provided as operation modes.
 - Continuous select mode
 - Continuous scan mode
 - One-shot scan mode
- The following functions are provided as trigger modes.
 - Software trigger mode
 - External trigger mode (external, 1)
 - Timer trigger mode
- Power-fail monitor function (conversion result compare function)

Figure 2-12: Block Diagram of A/D Converter



2.11 Asynchronous Serial Interface A (UARTA)

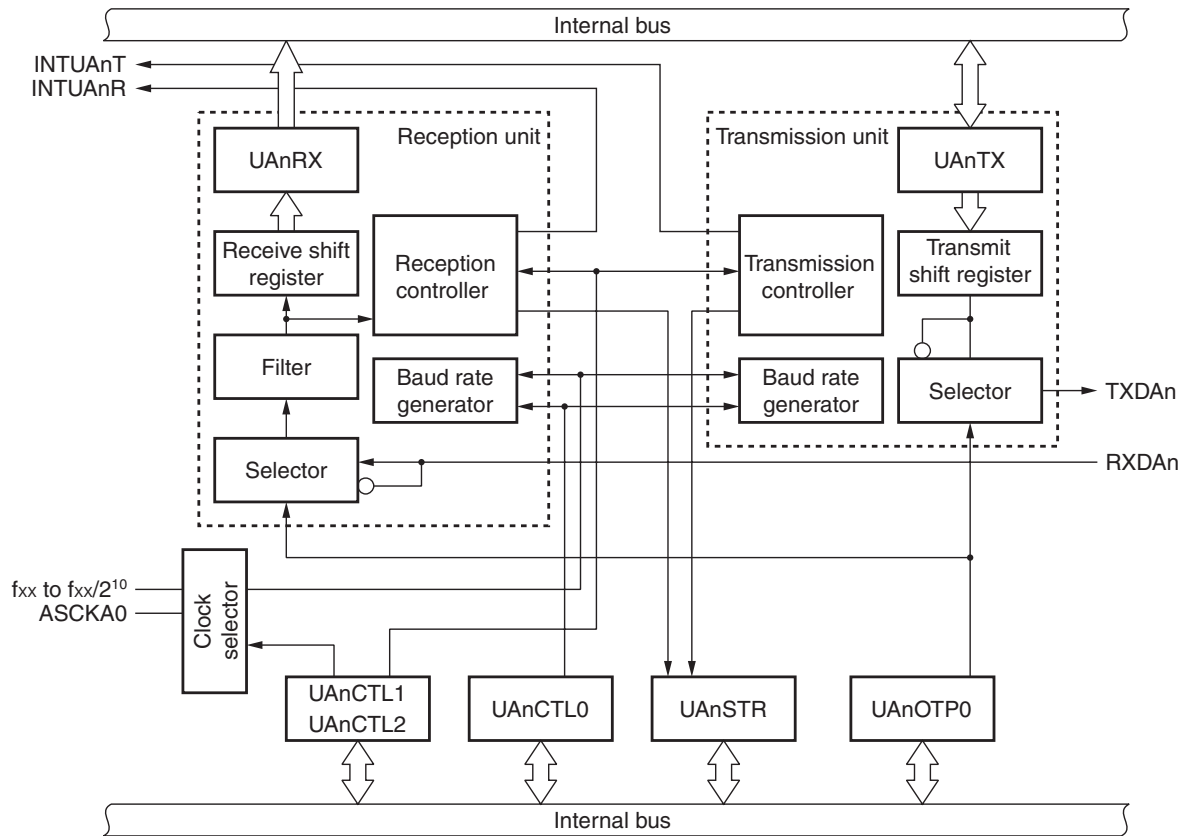
The V850ES/FG2 includes asynchronous serial interface A (UARTA).

Features

- Transfer rate: 300 bps to 312.5 kbps (using internal system clock of 20 MHz and dedicated baud rate generator)
- Full-duplex communication
 - UARTA receive data register n (UAnRX)
 - UARTA transmit data register n (UAnTX)
- 2-pin configuration TXDAn:
 - Output pin of transmit data
 - RXDAn: Input pin of receive data
- Reception error detection function
 - Parity error
 - Framing error
 - Overrun error
- Interrupt sources: 2 types
 - Reception complete interrupt (INTUAnR): An interrupt is generated in the reception enabled status by ORing three types of reception errors. It is also generated when receive data is transferred from the shift register to receive buffer register n after completion of serial transfer.
 - Transmission enable interrupt (INTUAnT): Generated when transmit data is transferred from the transmit buffer register to the shift register in the transmission enabled status.
- Character length of transmit/receive data is specified by the UAnCTL0 register.
- Character length: 7 or 8 bits
- Parity function: Odd, even, 0, none
- Transmission stop bit: 1 or 2 bits
- Dedicated baud rate generator
- MSB/LSB first transfer selectable
- Transmit/receive data reversible
- 13 to 20 bits selectable for SBF (Sync Break Field) transmission in LIN (Local Interconnect Network) communication format
- 11 or more bits recognizable for SBF reception in LIN communication format
- SBF reception flag

Remark: n = 0 to 2

Figure 2-13: Block Diagram of Asynchronous Serial Interface A



Remark: n = 0 to 2

2.12 3-Wire Serial Interface (CSIB)

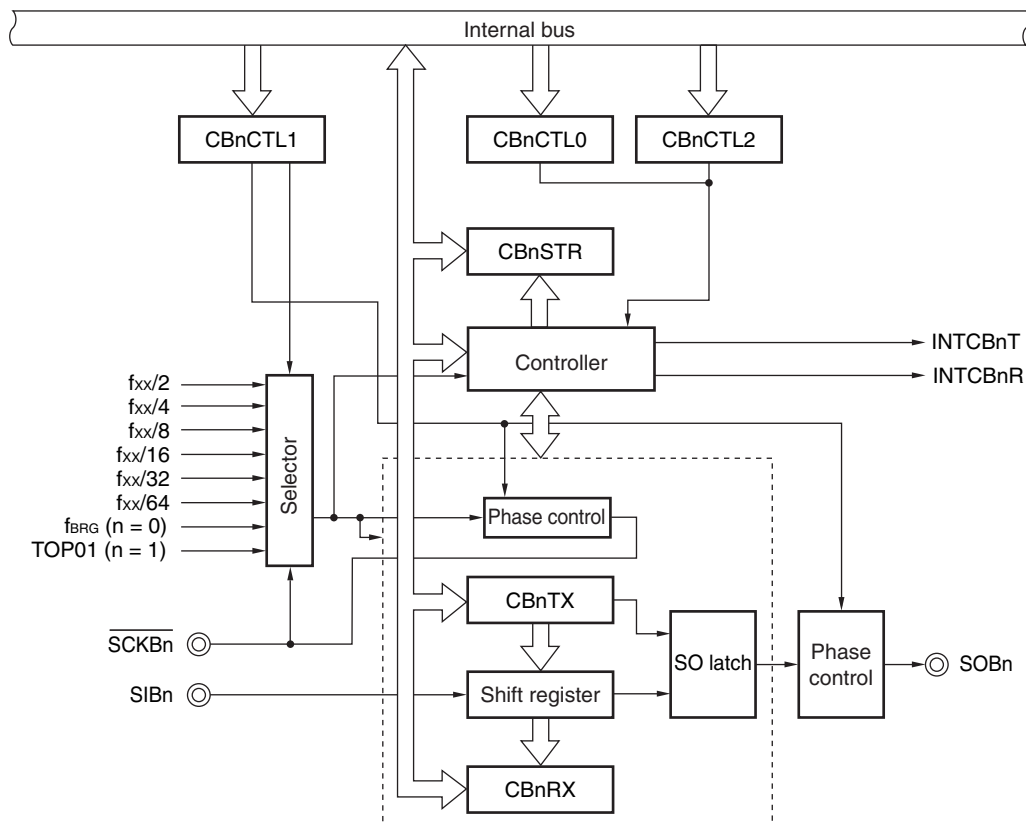
The V850ES/FG2 includes a 3-wire serial interface (CSIB).

Features

- Master mode and slave mode selectable
- 3-wire serial interface for 8-bit to 16-bit transfer
- Interrupt request signals (INTCBnT and INTCBnR)
- Serial clock and data phase selectable
- Transfer data length selectable from 8 to 16 bits in 1-bit units
- Data transfer with MSB- or LSB-first selectable
- 3-wireSOBn:
 - Serial data output
 - SIBn:Serial data input
 - SCKBn:Serial clock I/O
- Transmission mode, reception mode, and transmission/reception mode selectable

Remark: n = 0, 1

Figure 2-14: Block Diagram of 3-Wire Serial Interface



Remark: n = 0, 1

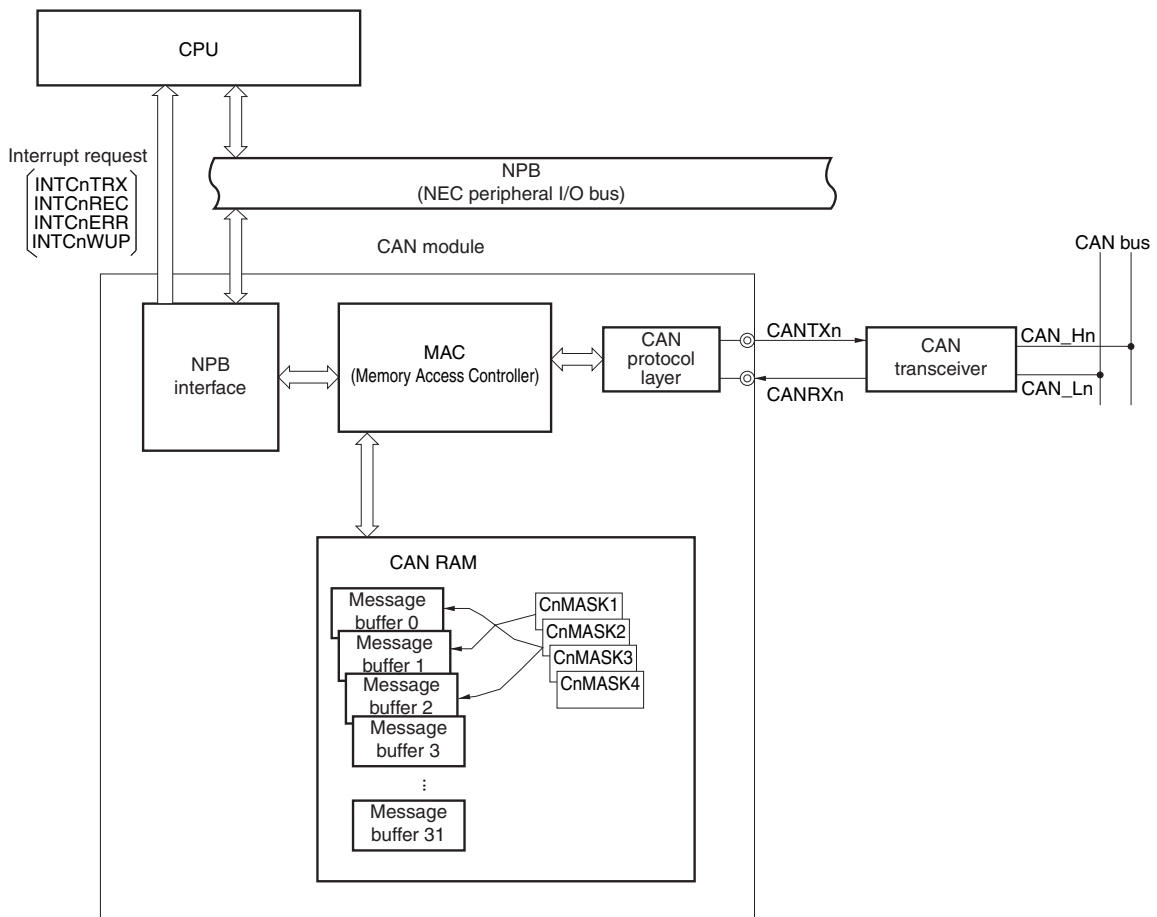
2.13 CAN Controller

This product features an on-chip 2-channel CAN (Controller Area Network) controller that complies with the CAN protocol as standardized in ISO 11898. The number of channels varies depending on the product as shown below.

Features

- Compliant with ISO 11898 and tested according to ISO/DIS 16845 (CAN conformance test)
- Standard frame and extended frame transmission/reception enabled
- Transfer rate: 1 Mbps max. (CAN clock input \geq 8 MHz)
- 32 message buffers \times 2 channels
- Receive/transmit history list function
- Automatic block transmission function
- Multi-buffer receive block function
- Mask setting of four patterns is possible for each channel

Figure 2-15: Block Diagram of CAN Module



Remark: n = 0, 1

2.14 Interrupt/Exception Processing Function

The V850ES/FG2 is provided with a dedicated interrupt controller (INTC) for interrupt servicing. An interrupt is an event that occurs independently of program execution, and an exception is an event whose occurrence is dependent on program execution.

The V850ES/FG2 can process interrupt request signals from the on-chip peripheral hardware and external sources. Moreover, exception processing can be started by the TRAP instruction (software exception) or by generation of an exception event (i.e. fetching of an illegal opcode) (exception trap).

Features

- Interrupts
 - Non-maskable interrupts: 1 source
 - Maskable interrupts: External: 11, Internal: 50 sources
 - 8 levels of programmable priorities (maskable interrupts)
 - Multiple interrupt control according to priority
 - Masks can be specified for each maskable interrupt request
 - Noise elimination, edge detection, and valid edge specification for external interrupt request signals
- Exceptions
 - Software exceptions: 32 sources
 - Exception trap: 2 sources (illegal opcode exception, debug trap)

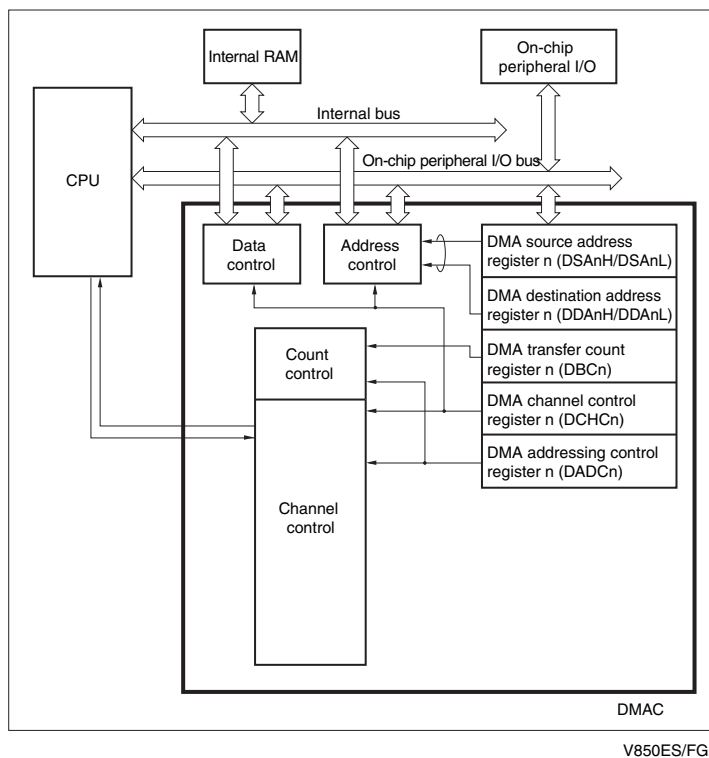
2.15 DMA Controller (DMAC)

The V850ES/FG2 incorporates a direct memory access (DMA) controller (DMAC) that executes and controls DMA transfer. The V850ES/FG2 incorporates four independent DMA channels. The DMAC controls data transfer between memory and I/O, between memories, or between I/Os based on DMA requests issued by the on-chip peripheral I/O (serial interface, real-time pulse unit, and A/D converter), interrupts from external input pins, or software triggers (memory refers to internal RAM or external memory).

Features

- 4 independent DMA channels
- Transfer unit: 8/16 bits
- Maximum transfer count: 65,536 (2^{16})
- Transfer type: Two-cycle transfer
- Transfer mode: Single transfer mode
- Transfer requests
 - Request by interrupts from on-chip peripheral I/O (serial interface, timer/counter, A/D converter) or interrupts from external input pin
 - Requests by software trigger
- Transfer targets
 - Peripheral I/O \Leftrightarrow Peripheral I/O
 - Peripheral I/O \Leftrightarrow Internal RAM

Figure 2-16: Block Diagram of DMA Controller



Remark: n = 0 to 3

2.16 Key Interrupt Function

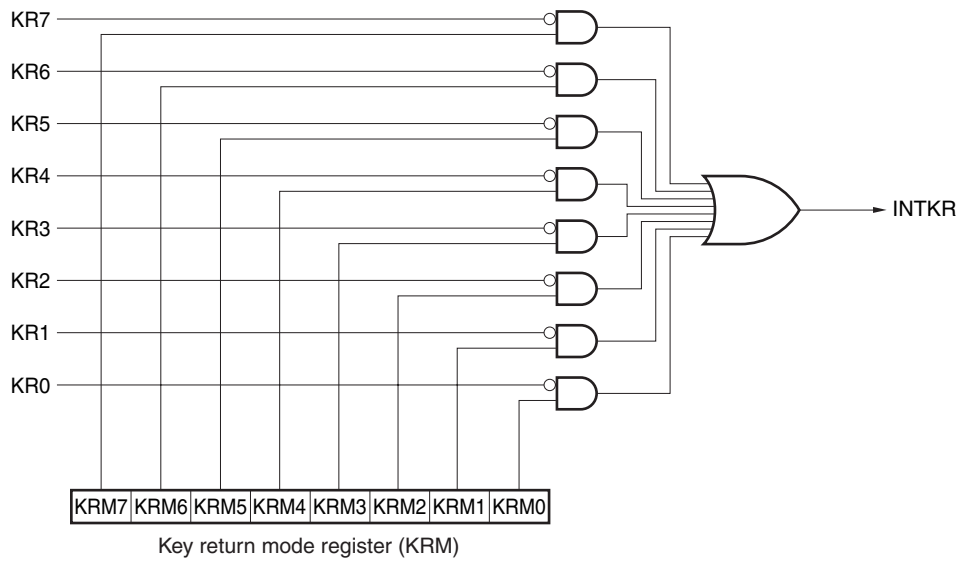
Features

A key interrupt request signal (INTKR) can be generated by inputting a falling edge to the eight key input pins (KR0 to KR7) by setting the key return mode register (KRM).

Table 2-5: Assignment of Key Return Detection Pins

Flag	Pin Description
KRM0	Controls KR0 signal in 1-bit units
KRM1	Controls KR1 signal in 1-bit units
KRM2	Controls KR2 signal in 1-bit units
KRM3	Controls KR3 signal in 1-bit units
KRM4	Controls KR4 signal in 1-bit units
KRM5	Controls KR5 signal in 1-bit units
KRM6	Controls KR6 signal in 1-bit units
KRM7	Controls KR7 signal in 1-bit units

Figure 2-17: Key Return Block Diagram



2.17 Standby Function

Overview

The power consumption of the system can be effectively reduced by using the standby modes in combination and selecting the appropriate mode for the application. The available standby modes are listed below.

Table 2-6: Standby Modes

Mode	Functional Outline
HALT mode	Mode in which only the operating clock of the CPU is stopped
IDLE1 mode	Mode in which all the internal operations of the chip except the oscillator, PLL ^a , and flash memory are stopped
IDLE2 mode	Mode in which all the internal operations of the chip except the oscillator are stopped
Software STOP mode	Mode in which all the internal operations of the chip except the subclock oscillator are stopped
Subclock operation mode	Mode in which the subclock is used as the internal system clock
Sub-IDLE mode	Mode in which all the internal operations of the chip except the oscillator, PLL ^a , and flash memory are stopped, in the subclock operation mode

a. The PLL holds the previous operating status (in clock-through mode or PLL mode).

2.18 Reset Function

The reset function is outlined below.

- Reset function by RESET pin input
- Reset function by overflow of watchdog timer 2 (WDT2RES)
- System reset by low voltage detector (LVI)
- System reset by clock monitor (CLM)

2.19 Clock Monitor

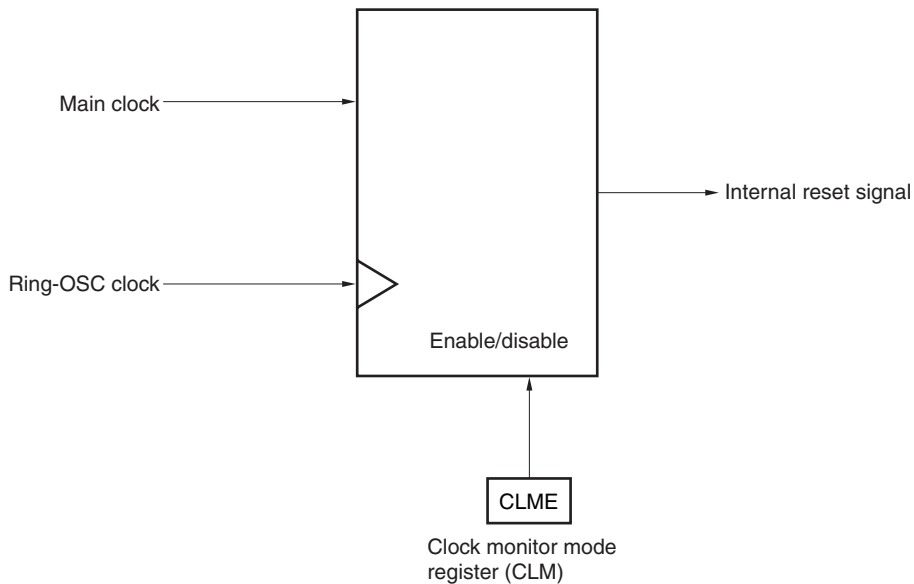
The clock monitor samples the main clock by using the on-chip Ring-OSC and generates a reset request signal when oscillation of the main clock is stopped.

Once the operation of the clock monitor has been enabled by an operation enable flag, it cannot be cleared to 0 by any means other than reset.

The clock monitor automatically stops under the following conditions.

- While oscillation stabilization time is being counted after software STOP mode is released
- When the main clock is stopped (MCK bit of the PCC register = 1 during subclock operation, or CLS bit of the PCC register = 0 during main clock operation)
- When the sampling clock is stopped (Ring-OSC)
- When the CPU operates with Ring-OSC

Figure 2-18: CLM Block Diagram



2.20 Low-voltage Detector

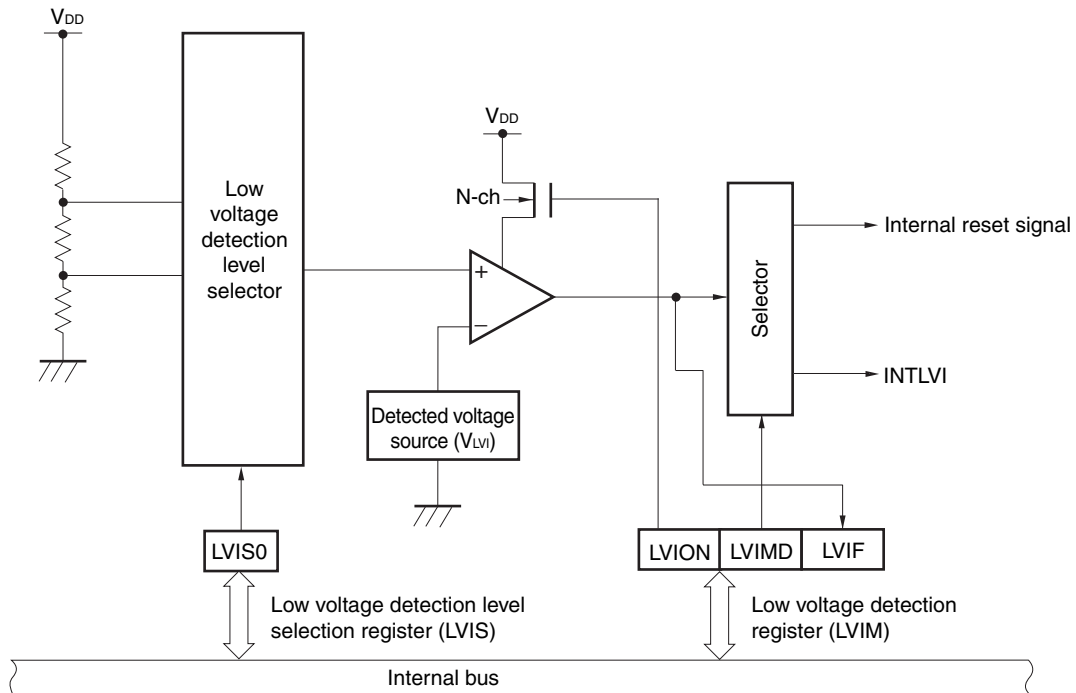
Features

The low-voltage detector (LVI) has the following functions.

- Compares the supply voltage (V_{DD}) and detected voltage (V_{LVI}) and generates an internal interrupt signal or internal reset signal when $V_{DD} < V_{LVI}$.
- The level of the supply voltage to be detected can be changed by software (in two steps).
- Interrupt or reset signal can be selected by software.
- Can operate in STOP mode too.
- Operation can be stopped by software.

If the low-voltage detector is used to generate a reset signal, bit 0 (LVIRF) of the reset source flag register (RESF) is set to 1 when the reset signal is generated.

Figure 2-19: Block Diagram of Low-Voltage Detector

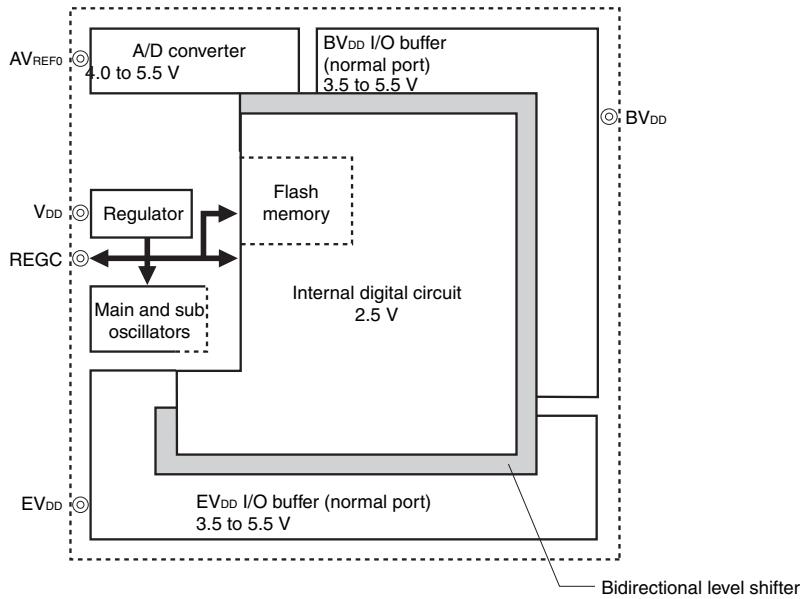


2.21 Voltage Regulator

Features

This product has an on-chip regulator to lower the power consumption and noise. This regulator supplies a voltage lower than the supply voltage V_{DD} to the oscillator block and internal logic circuits (except the A/D converter and I/O buffers). The output voltage of the regulator is set to 2.5 V (± 0.2 V).

Figure 2-20: Regulator

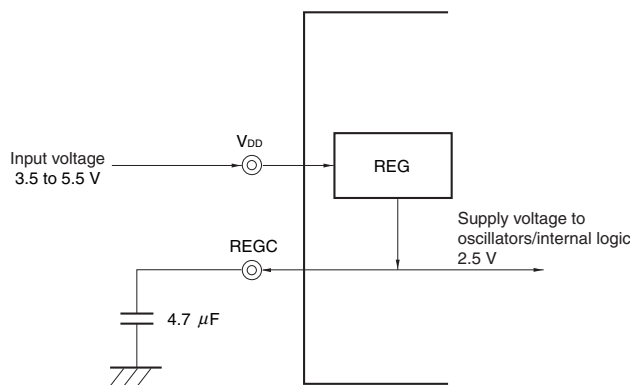


The regulator of this product operates in all operation modes (normal operation, HALT, IDLE1, IDLE2, STOP, and sub-IDLE modes, and during reset).

To stabilize the output voltage of the regulator, connect a capacitor ($4.7 \mu F$ ^{Note}) to the REGC pin.

Note: Connect the REGC pin as illustrated below.

Figure 2-21: Connection of REGC Pin (REGC = Capacitance)



2.22 Flash Memory

The following products are flash memory versions of the V850ES/FG2.

Caution: There are differences in the amount of noise tolerance and noise radiation between flash memory versions and mask ROM versions. When considering changing from a flash memory version to a mask ROM version during the process from experimental manufacturing to mass production, make sure to sufficiently evaluate commercial samples (CS) (not engineering samples (ES)) of the mask ROM versions.

μPD70F3235 On-chip 256 KB flash memory

When fetching an instruction, 4 bytes of the flash memory can be accessed in 1 clock in the same manner as the mask ROM versions.

The flash memory can be written mounted on the target board (on-board write), by connecting a dedicated flash programmer to the target system.

Flash memory is commonly used in the following development environments and applications.

- For altering software after solder-mounting the V850ES/FG2 on the target system
- For differentiating software in small-scale production of various models.
- For data adjustment when starting mass production

Features

- 4-byte/1-clock access (for instruction fetch access)
- Batch erase or block unit erase
- Communication with dedicated flash programmer via serial interface
- Erase/write voltage: Can be erased or written using a single power supply.
- On-board programming
- Flash memory programming by self writing

Erase unit

The units in which the 256 KB flash memory can be erased are as follows.

(1)Batch erasure

The areas of flash memory xx000000H to xx03FFFFH can be erased at the same time.

(2)Block erasure

The flash memory can be erased in block units.

Block 0:	56 KB
Block 1:	8 KB
Block 2:	56 KB
Block 3:	8 KB
Block 4:	56 KB
Block 5:	56 KB
Block 6:	8 KB
Block 7:	8 KB
Block 8:	32 KB

2.23 ROM Mask Options Function

Mask Options (Flash ROM Product)

The flash memory versions in this product series have an option data area where a block subject to mask options is specified.

When writing a program to a flash memory version, be sure to set the option data corresponding to the following option in the program at address 007AH as default data.

The data in this area cannot be rewritten during program execution.

Table 2-7: Mask Options

Address	Set Value	Setting
007AH	00H	Ring-OSC:Can be stopped. WDT2:Count clock can be selected. Overflow signal can be selected from INTWDT2 or WDT2RES. Subclock:Crystal resonator connection
	01H	Ring-OSC:Cannot be stopped. WDT2:Count clock can be selected. Overflow signal can be selected from INTWDT2 or WDT2RES. Subclock:Crystal resonator connection
	02H	Ring-OSC:Can be stopped. WDT2:Count clock is fixed to Ring-OSC. Overflow signal is fixed to WDT2RES. Subclock:Crystal resonator connection
	03H	Ring-OSC:Cannot be stopped. WDT2:Count clock is fixed to Ring-OSC. Overflow signal is fixed to WDT2RES. Subclock:Crystal resonator connection
	C0H	Ring-OSC:Can be stopped. WDT2:Count clock can be selected. Overflow signal can be selected from INTWDT2 or WDT2RES. Subclock:RC oscillation connection
	C1H	Ring-OSC:Cannot be stopped. WDT2:Count clock can be selected. Overflow signal can be selected from INTWDT2 or WDT2RES. Subclock:RC oscillation connection
	C2H	Ring-OSC:Can be stopped. WDT2:Count clock is fixed to Ring-OSC. Overflow signal is fixed to WDT2RES. Subclock:RC oscillation connection
	C3H	Ring-OSC:Cannot be stopped. WDT2:Count clock is fixed to Ring-OSC. Overflow signal is fixed to WDT2RES. Subclock:RC oscillation connection

Caution: Do not make any settings other than the above.

2.24 On-chip Debug Unit (Flash Memory Versions only)

The V850ES/FG2 includes an on-chip debug unit. By connecting an N-Wire emulator, on-chip debugging can be executed with the V850ES/FG2 alone.

Caution: The following debug functions are supported by the V850ES/FG2, and whether they are usable or not differs depending on the debugger. For details of the debugging function, refer to the user's manual of the debugger to be used.

Functional Outline

The on-chip debug unit of the V850ES/FG2 is RCU1 (Run Control Unit 1).

Debug interface

Communication with the host machine is established by using the DRST, DCK, DMS, DDI, and DDO signals via an N-Wire emulator. The communication specifications of N-Wire are used for the interface.

On-chip debug

On-chip debugging can be executed by preparing wiring and a connector for on-chip debugging on the target system. An N-Wire emulator is used as the connector that connects the emulator.

Clear the OCDM0 bit of the OCDM register (special register) to 0 when you use on-chip debug mode.

Forced reset function

The V850ES/FG2 can be forcibly reset.

Break reset function

The CPU can be started in the debug mode immediately after reset of the CPU is released.

Forced break function

Execution of the user program can be forcibly aborted (however, the illegal operation code exception handler (first address: 00000060H) cannot be used).

Hardware break function

Two breakpoints for instruction and access can be used. The instruction breakpoint can abort program execution at any address. The access breakpoint can abort program execution by data access to any address.

Software break function

Up to four software breakpoints can be set in the internal ROM area. The number of software breakpoints that can be set in the RAM area differs depending on the debugger to be used.

Debug monitor function

A memory space for debugging that is different from the user memory space is used during debugging (background monitor mode). The user program can be executed starting from any address.

While execution of the user program is aborted, the user resources (such as memory and I/O) can be read and written, and the user program can be downloaded.

Mask function

Each signal can be masked.

The correspondence with the mask functions of the debugger (ID850NWC) for the N-Wire emulator (IE-V850E1-CD-NW) of NEC Electronics is shown below.

- NMI0 mask function: NMI pin
- NMI1 mask function: WDT2 interrupt
- NMI2 mask function: –
- RESET mask function: RESET pin, WDT2 reset, LVI reset, clock monitor reset

Timer function

The execution time of the user program can be measured.

Peripheral macro operation/stop selection function during break

Depending on the debugger to be used, whether the peripheral macro operates or is stopped during a break can be selected.

Functions that are always stopped during break

- Clock monitor
- Watchdog timer 2

Functions that can operate or be stopped during break (however, each function cannot be selected individually)

- A/D converter
- Timer M
- Timer P
- Timer Q
- Watch timer

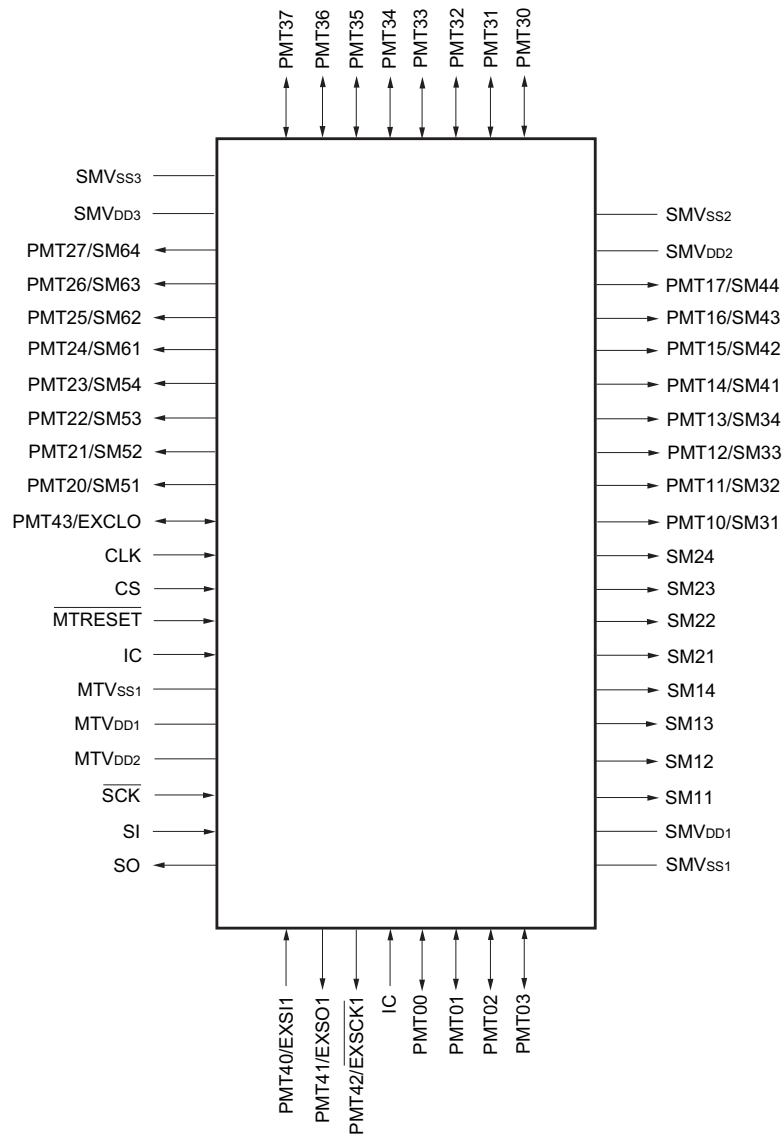
Peripheral functions that continue operating during break (functions that cannot be stopped)

- Peripheral functions other than above

Chapter 3 Pin Function of MTRC

3.1 Pin Configuration (Top View)

Figure 3-1: Pinout of MTRC



3.2 List of Pin Functions

Table 3-1: List of Pin Functions (1/2)

Symbol	IO	Function	Connection
PMT00	IO	I/O Port	External
PMT01	IO	I/O Port	External
PMT02	IO	I/O Port	External
PMT03	IO	I/O Port	External
SM11	O - Hi-Z	Meter1 PWM Output Signal (sin+)	External
SM12	O - Hi-Z	Meter1 PWM Output Signal (sin-)	External
SM13	O - Hi-Z	Meter1 PWM Output Signal (cos+)	External
SM14	O - Hi-Z	Meter1 PWM Output Signal (cos-)	External
SM21	O - Hi-Z	Meter2 PWM Output Signal (sin+)	External
SM22	O - Hi-Z	Meter2 PWM Output Signal (sin-)	External
SM23	O - Hi-Z	Meter2 PWM Output Signal (cos+)	External
SM24	O - Hi-Z	Meter2 PWM Output Signal (cos-)	External
PMT10/SM31	O - Hi-Z / O	Output Port / Meter3 PWM Output Signal (sin+)	External
PMT11/SM32	O - Hi-Z / O	Output Port / Meter3 PWM Output Signal (sin-)	External
PMT12/SM33	O - Hi-Z / O	Output Port / Meter3 PWM Output Signal (cos+)	External
PMT13/SM34	O - Hi-Z / O	Output Port / Meter3 PWM Output Signal (cos-)	External
PMT14/SM41	O - Hi-Z / O	Output Port / Meter4 PWM Output Signal (sin+)	External
PMT15/SM42	O - Hi-Z / O	Output Port / Meter4 PWM Output Signal (sin-)	External
PMT16/SM43	O - Hi-Z / O	Output Port / Meter4 PWM Output Signal (cos+)	External
PMT17/SM44	O - Hi-Z / O	Output Port / Meter4 PWM Output Signal (cos-)	External
PMT20/SM51	O - Hi-Z / O	Output Port / Meter5 PWM Output Signal (sin+)	External
PMT21/SM52	O - Hi-Z / O	Output Port / Meter5 PWM Output Signal (sin-)	External
PMT22/SM53	O - Hi-Z / O	Output Port / Meter5 PWM Output Signal (cos+)	External
PMT23/SM54	O - Hi-Z / O	Output Port / Meter5 PWM Output Signal (cos-)	External
PMT24/SM61	O - Hi-Z / O	Output Port / Meter6 PWM Output Signal (sin+)	External
PMT25/SM62	O - Hi-Z / O	Output Port / Meter6 PWM Output Signal (sin-)	External
PMT26/SM63	O - Hi-Z / O	Output Port / Meter6 PWM Output Signal (cos+)	External
PMT27/SM64	O - Hi-Z / O	Output Port / Meter6 PWM Output Signal (cos-)	External
PMT30	IO	I/O Port	External
PMT31	IO	I/O Port	External
PMT32	IO	I/O Port	External
PMT33	IO	I/O Port	External
PMT34 Caution	IO	I/O Port	Internal ^a
PMT35 Caution	IO	I/O Port	Internal ^a
PMT36 Caution	IO	I/O Port	Internal ^a
PMT37 Caution	IO	I/O Port	Internal ^a
PMT40/EXSI1	IO/I	I/O Port / Expand Pin for SI	External
PMT41/EXSO1	IO/O	I/O Port / Expand Pin for SO	External

Chapter 3 Pin Function of MTRC

Table 3-1: List of Pin Functions (2/2)

Symbol	IO	Function	Connection
PMT42/ $\overline{\text{EXSCK1}}$	IO/O	I/O Port / Expand Pin for $\overline{\text{SCK}}$	External
PMT43/EXCLO	IO/O	I/O Port / Expand Pin for System Clock	External
SMVDD1		Power Supply Input Voltage for Meter1, Meter2	External
SMVSS1		Ground Potential for Meter1, Meter2	External
SMVDD2		Power Supply Input Voltage for Meter3, Meter4	External
SMVSS2		Ground Potential for Meter3, Meter4	External
SMVDD3		Power Supply Input Voltage for Meter5, Meter6	External
SMVSS3		Ground Potential for Meter5, Meter6	External
CLK	I	System Clock Input	Internal to FG2
CS	I	Serial Access Enable	Internal to FG2
MTCS	O	PCM0 pin of FG2 device (PCM0 has to be configured to output for internal communication)	External from FG2
$\overline{\text{MTRSET}}$	I	Reset Input	External
MTVSS		Ground Potential (Digital Unit)	External
MTVDD		Power Supply Input Voltage (Digital Unit)	External
$\overline{\text{SCK}}$	I	Serial Clock Input	Internal to FG2
SI	I	Serial Data Input	Internal to FG2
SO	O	Serial Data Output	Internal to FG2

a. Internally connected, not available on external pins.

Caution: Setting the port mode configuration for PMT34 to PMT37 requires special attention, refer to “Port MT3” on page 87.

Table 3-2: Recommended connection of unused pins (1/2)

Symbol	Alternate Function	I/O Circuit	Recommended connection
PMT00		A-1	Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT01			Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT02			Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT03			Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
SM11		B-1	Leave open
SM12			Leave open
SM13			Leave open
SM14			Leave open
SM21			Leave open
SM22			Leave open
SM23			Leave open
SM24			Leave open
PMT10/SM31	Meter3 PWM Output Signal (sin+)	B-2	Leave open
PMT11/SM32	Meter3 PWM Output Signal (sin-)		Leave open
PMT12/SM33	Meter3 PWM Output Signal (cos+)		Leave open
PMT13/SM34	Meter3 PWM Output Signal (cos-)		Leave open
PMT14/SM41	Meter4 PWM Output Signal (sin+)		Leave open
PMT15/SM42	Meter4 PWM Output Signal (sin-)		Leave open
PMT16/SM43	Meter4 PWM Output Signal (cos+)		Leave open
PMT17/SM44	Meter4 PWM Output Signal (cos-)		Leave open
PMT20/SM51	Meter5 PWM Output Signal (sin+)		Leave open
PMT21/SM52	Meter5 PWM Output Signal (sin-)		Leave open
PMT22/SM53	Meter5 PWM Output Signal (cos+)		Leave open
PMT23/SM54	Meter5 PWM Output Signal (cos-)		Leave open
PMT24/SM61	Meter6 PWM Output Signal (sin+)		Leave open
PMT25/SM62	Meter6 PWM Output Signal (sin-)		Leave open
PMT26/SM63	Meter6 PWM Output Signal (cos+)		Leave open
PMT27/SM64	Meter6 PWM Output Signal (cos-)		Leave open

Chapter 3 Pin Function of MTRC

Table 3-2: Recommended connection of unused pins (2/2)

Symbol	Alternate Function	I/O Circuit	Recommended connection
PMT30		A-1	Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT31			Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT32			Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT33			Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT40/EXSI1	Expand Pin for SI	D-2	Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT41/EXSO1	Expand Pin for SO	D-1	Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT42/ EXSCK1	Expand Pin for SCK	D-3	Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
PMT43/EXCLO	Expand Pin for System Clock	D-4	Input: Independently connect to MTV _{DD} or MTV _{SS} via a resistor Output: Leave open
SMVDD1		-	
SMVSS1		-	
SMVDD2		-	
SMVSS2		-	
SMVDD3		-	
SMVSS3		-	
CLK		CLK ^a	internal connected
MTCS		MTCS ^a	internal connected
$\overline{\text{MTRESET}}$		-	
MTV _{SS}		-	
MTV _{DD}		-	
$\overline{\text{SCK}}$		SCK ^a	internal connected
SI		SI ^a	internal connected
SO		SO	internal connected
IC1, IC2		-	Input: connect to MTV _{SS} directly

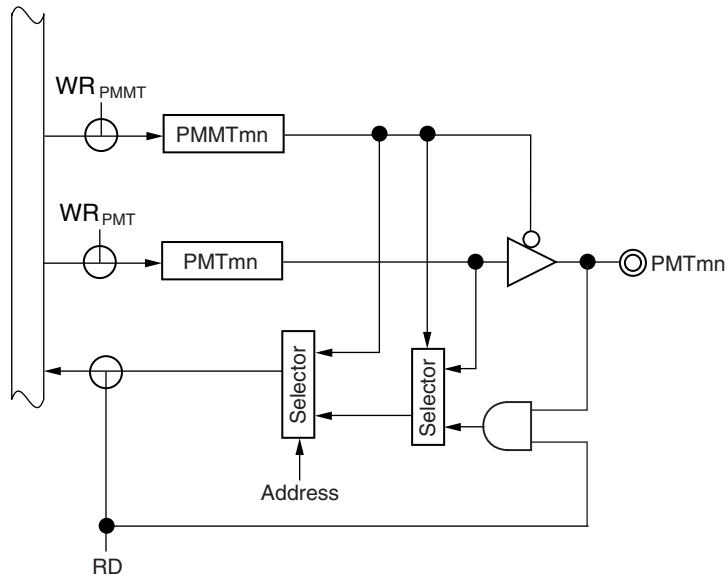
- a. Some input pins of the MTRC have pull down/pull up resistors to avoid noise effects that could cause malfunction during the initialization of the FG2 device. After $\overline{\text{MTRESET}}$ release, these resistors are active. The resistors will be deactivated after the first rising edge of the MTCS signal. They will be reactivated if $\overline{\text{MTRESET}} = 0$. Therefore these resistors consume some current when they are activated.

3.3 Pin I/O Circuits

Each type of port block diagram is as follows. Then, the type of each port is shown in each chapter.

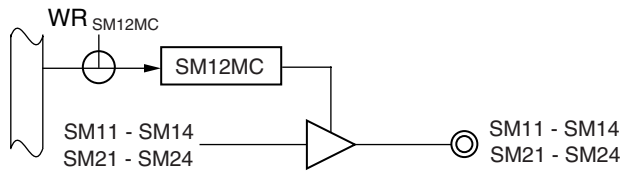
3.3.1 Type A-1

Figure 3-2: Type A-1



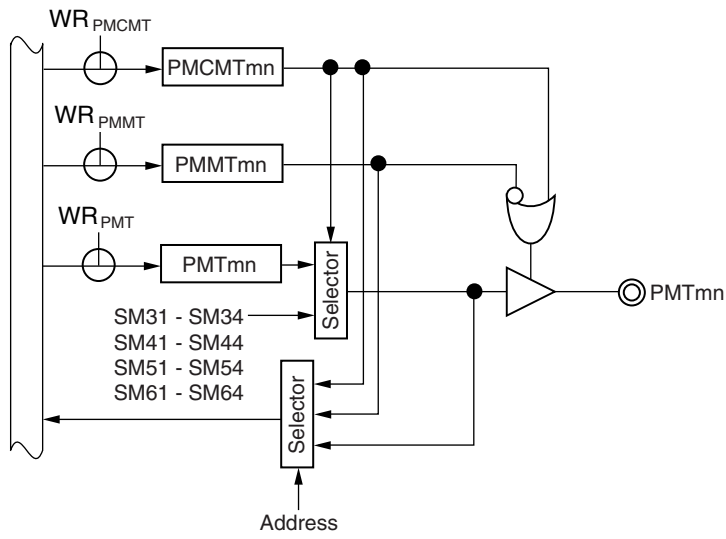
3.3.2 Type B-1

Figure 3-3: Type B-1



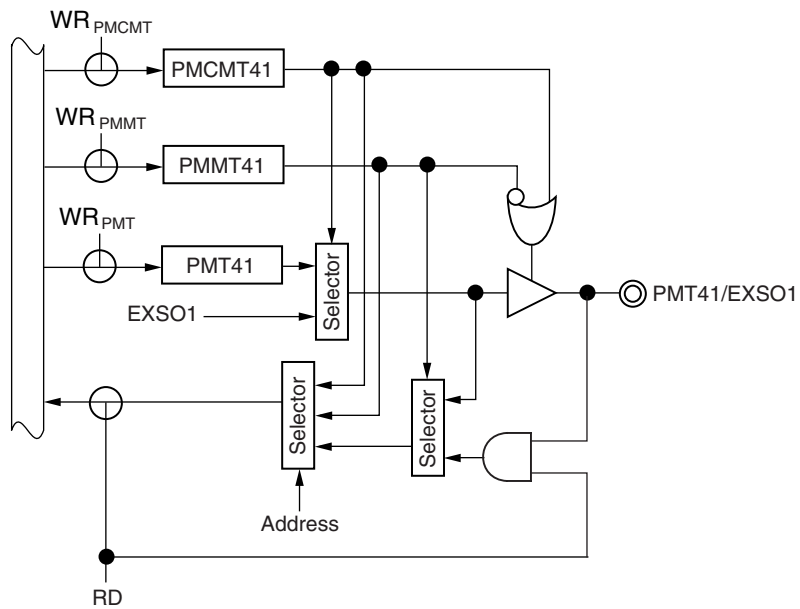
3.3.3 Type B-2

Figure 3-4: Type B-2



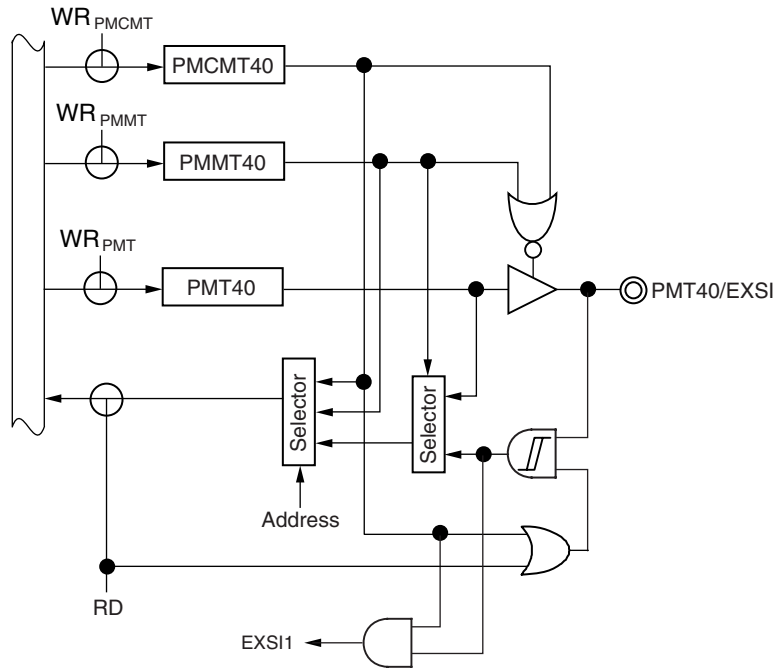
3.3.4 Type D-1

Figure 3-5: Type D-1



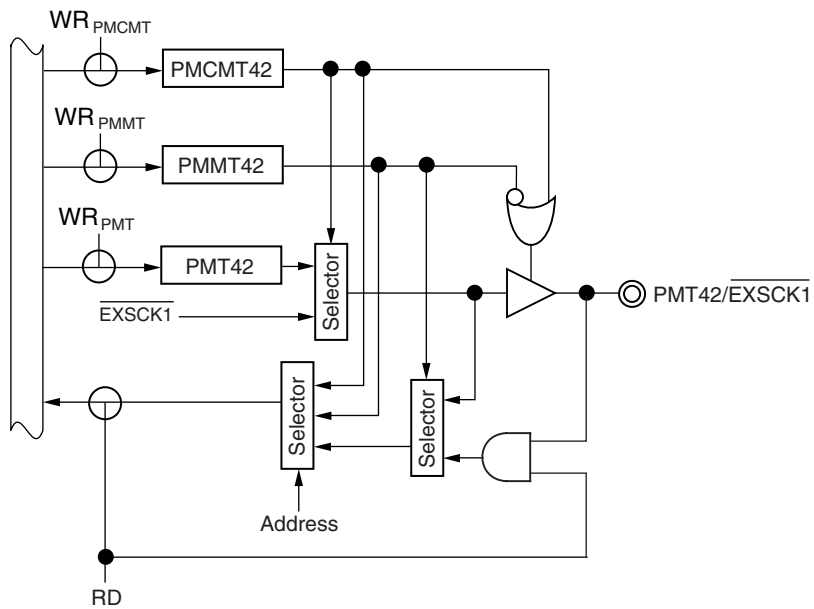
3.3.5 Type D-2

Figure 3-6: Type D-2



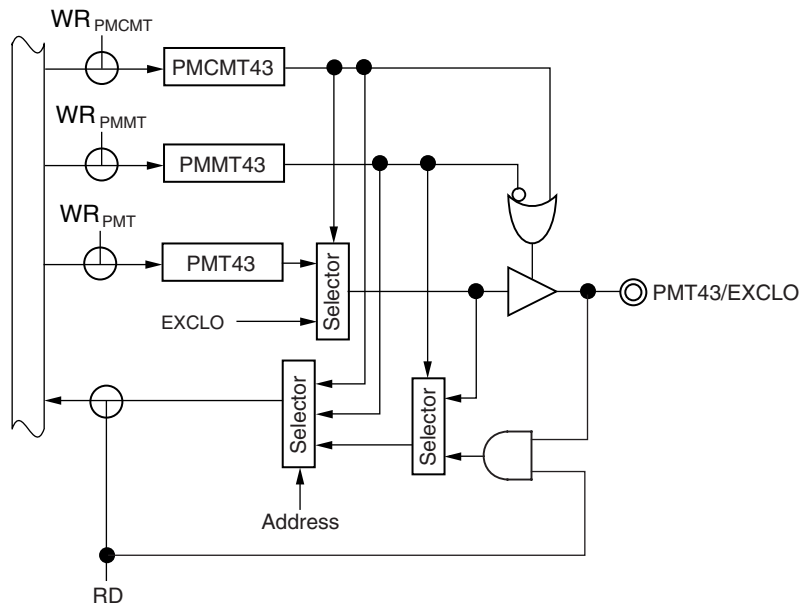
3.3.6 Type D-3

Figure 3-7: Type D-3



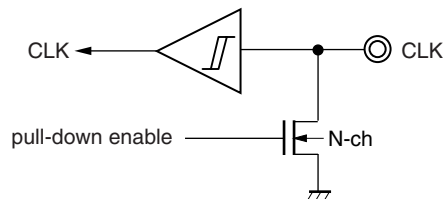
3.3.7 Type D-4

Figure 3-8: Type D-4



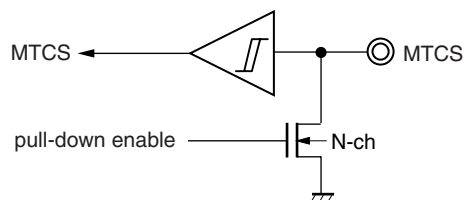
3.3.8 Type CLK

Figure 3-9: Type CLK



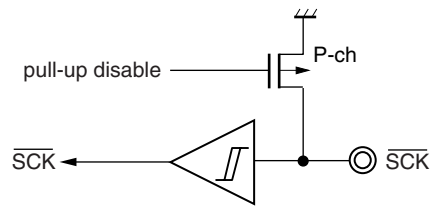
3.3.9 Type MTCS

Figure 3-10: Type MTCS



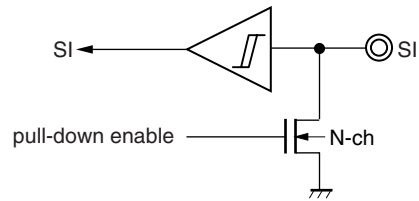
3.3.10 Type \overline{SCK}

Figure 3-11: Type \overline{SCK}



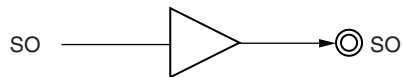
3.3.11 Type SI

Figure 3-12: Type SI



3.3.12 Type SO

Figure 3-13: Type SO



Chapter 4 Port Functions

4.1 Setting Alternate Pin Functions

Set “1” to the PMC_mn bit of PMC_m register to set the pin to the alternate pin function. Refer to the following table for setting the alternate pin function for every port pin. Not any port provides alternate pin function and therefore this registers has no PMCMT_mn register. Please refer to the peripheral function chapter to get more details.

Remark: m = 1, 2, 4
n = 0 to 7

Table 4-1: Alternate Pin Functions (1/2)

Port name	Alternate pin name	Setting value when selecting alternate function			
		PMT _m n	PMMT _m n	PMCMT _m n	Remark
PMT00	-	0/1	1	-	
PMT01					
PMT02					
PMT03					
PMT10	SM31	0/1	0/1	1	
PMT11	SM32				
PMT12	SM33				
PMT13	SM34				
PMT14	SM41				
PMT15	SM42				
PMT16	SM43				
PMT17	SM44				
PMT20	SM51	0/1	0/1	1	
PMT21	SM52				
PMT22	SM53				
PMT23	SM54				
PMT24	SM61				
PMT25	SM62				
PMT26	SM63				
PMT27	SM64				
PMT30	-	0/1	1	-	
PMT31					
PMT32					
PMT33					
PMT34	Caution				
PMT35					
PMT36					
PMT37					

Chapter 4 Port Functions

Table 4-1: Alternate Pin Functions (2/2)

Port name	Alternate pin name	Setting value when selecting alternate function			
		PMTmn	PMMTmn	PMCMTmn	Remark
PMT40	EXSI1	0/1	0/1	1	Connect to SO only if MTCS = 0 ^a
PMT41	EXSO1				Connect to SI only if MTCS = 0
PMT42	EXSCK1				Connect to \overline{SCK} only if MTCS = 0
PMT43	EXCLO				Connect to CLK only if MTCS = 0

- a. The MTCS signal is identical to the V850ES/Fx2's PCM0 signal, which connects the EXCSIB1 interface to the V850ES/Fx2 CSIB1, when PCM0 = MTCS = 0.
 Note that changing the internal connection of the EXCSIB1 interface pins upon a change of PCM0/MTCS may be delayed due to an ongoing CSIB1 data transfer.

Caution: Setting the port mode configuration for PMT34 to PMT37 requires special attention, refer to “Port MT3” on page 87.

4.2 Port MT0

4.2.1 Port MT0 functions

- 4-bit I/O Port
- Port I/O data specified in 1-bit units

Table 4-2: Port MT0 Functions

Port Mode	Alternate Function	TYPE	Register		
			PORT	PM	PMC
PMT00	-	A-1	×	×	-
PMT01	-	A-1	×	×	-
PMT02	-	A-1	×	×	-
PMT03	-	A-1	×	×	-

Remarks: 1. PORT: Port
 PM: Port mode register
 PMC: Port mode control register

2. x: available
 -: not available

4.2.2 Register

(1) Port Register 0 (PMT0)

MTRC Port register 0 (MT0) is an 8-bit register that controls pin level read, output level write.

It can be read and written in 8-bit unit.

Figure 4-1: Port Register 0 (PMT0) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMT0	0	0	0	0	PMT03	PMT02	PMT01	PMT00	0x20	undefined
R/W	R	R	R	R	R/W	R/W	R/W	R/W		

PMT0n	Output data control (n= 0 - 3)
0	Output 0
1	Output 1

(2) Port MT0 Mode Register 0 (PMMT0)

This is an 8-bit register used to specify the input mode/output mode.

It can be read and written in 8-bit unit.

Figure 4-2: Port MT0 Mode Register 0 (PMMT0) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMMT0	1	1	1	1	PMMT03	PMMT02	PMMT01	PMMT00	0x25	0xFF
R/W	R	R	R	R	R/W	R/W	R/W	R/W		

PMMT0n	I/O mode control (n= 0 - 3)
0	Output mode
1	Input mode

4.3 Port MT1

4.3.1 Port MT1 functions

- 8-bit output port
- Port I/O specified in 1-bit units (PMMT1 register)
- Port mode/control mode (alternate function) specified in 1-bit units (PMCMT1 register)

Table 4-3: Port MT1 Functions

Port Mode	Alternate Function	TYPE	Register		
			PORT	PM	PMC
PMT10	SM31	B-2	x	x	x
PMT11	SM32	B-2	x	x	x
PMT12	SM33	B-2	x	x	x
PMT13	SM34	B-2	x	x	x
PMT14	SM41	B-2	x	x	x
PMT15	SM42	B-2	x	x	x
PMT16	SM43	B-2	x	x	x
PMT17	SM44	B-2	x	x	x

- Remarks:**
1. PORT: Port
 PM: Port mode register
 PMC: Port mode control register
 2. x: available
 -: not available

4.3.2 Registers

(1) Port Register 1 (PMT1)

MTRC Port register 1 (MT1) is an 8-bit register that controls pin level read, output level write.

It can be read and written in 8-bit unit.

Figure 4-3: Port Register 1 (PMT1) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMT1	PMT17	PMT16	PMT15	PMT14	PMT13	PMT12	PMT11	PMT10	0x21	undefined
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMT1n	Output data control (n= 0 - 7)
0	Output 0
1	Output 1

(2) Port Mode Register 1 (PMMT1)

It can be read and written in 8-bit unit.

Figure 4-4: Port Mode Register 1 (PMMT1) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMMT1	PMMT17	PMMT16	PMMT15	PMMT14	PMMT13	PMMT12	PMMT11	PMMT10	0x26	0xFF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMMT1n	I/O mode control (n= 0 - 7)
0	Output mode
1	Input mode

(3) Port Mode Control Register (PMCMT1)

It can be read and written in 8-bit unit.

Figure 4-5: Port Mode Control Register 1 (PMCMT1) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMCMT1	PMCMT17	PMCMT16	PMCMT15	PMCMT14	PMCMT13	PMCMT12	PMCMT11	PMCMT10	0x2A	0x00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMCMT1n	PMMT1n	PMCMTn mode control (n = 0 - 7)
0	0	Output port
0	1	Hi-Z output
1	x	SM44 output (n = 7) SM43 output (n = 6) SM42 output (n = 5) SM41 output (n = 4) SM34 output (n = 3) SM33 output (n = 2) SM32 output (n = 1) SM31 output (n = 0)

4.4 Port SM1/SM2

4.4.1 Port SM1/SM2 functions

- 8-bit output port
- Port mode/control mode (Hi-Z output as alternate function) specified in 1-bit units (SM12MC register)

Table 4-4: Port MT2 Functions

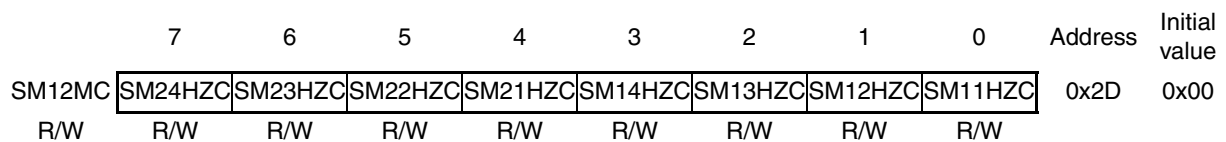
Port Mode	Alternate Function	TYPE	Register		
			PORT	PM	PMC
Hi-Z	SM11	B-1	-	-	x
Hi-Z	SM12	B-1	-	-	x
Hi-Z	SM13	B-1	-	-	x
Hi-Z	SM14	B-1	-	-	x
Hi-Z	SM21	B-1	-	-	x
Hi-Z	SM22	B-1	-	-	x
Hi-Z	SM23	B-1	-	-	x
Hi-Z	SM24	B-1	-	-	x

- Remarks:**
1. PORT: Port
PM: Port mode register
PMC: Port mode control register
 2. x: available
-: not available

(1) SM1SM2 Mode Control Register (SM12MC)

It can be read and written in 8-bit unit.

Figure 4-6: SM1SM2 Mode Control Register (SM12MC) Format



SMmnHZC	Output data control (m = 1, 2 and n = 1 - 4)
0	Hi-Z output
1	SMmn output

4.5 Port MT2

4.5.1 Port MT2 functions

- 8-bit output port
- Port mode/control mode (alternate function) specified in 1-bit units (PMCMT2 register)
- Hi-Z output controllable in 1-bit units (PMMT2, PMCMT2 register)

Table 4-5: Port MT2 Functions

Port Mode	Alternate Function	TYPE	Register		
			PORT	PM	PMC
PMT20	SM51	B-2	x	x	x
PMT21	SM52	B-2	x	x	x
PMT22	SM53	B-2	x	x	x
PMT23	SM54	B-2	x	x	x
PMT24	SM61	B-2	x	x	x
PMT25	SM62	B-2	x	x	x
PMT26	SM63	B-2	x	x	x
PMT27	SM64	B-2	x	x	x

- Remarks:**
1. PORT: Port
 PM: Port mode register
 PMC: Port mode control register
 2. x: available
 -: not available

4.5.2 Registers

(1) Port Register 2 (PMT2)

MTRC Port register 2 (MT2) is an 8-bit register that controls pin level read, output level write.

It can be read and written in 8-bit unit.

Figure 4-7: Port Register 2 (PMT2) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMT2	PMT27	PMT26	PMT25	PMT24	PMT23	PMT22	PMT21	PMT20	0x22	undefined
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMT2n	Output data control (n= 0 - 7)
0	Output 0
1	Output 1

(2) Port Mode Register 2 (PMMT2)

It can be read and written in 8-bit unit.

Figure 4-8: Port Mode Register 2 (PMMT2) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMMT2	PMMT27	PMMT26	PMMT25	PMMT24	PMMT23	PMMT22	PMMT21	PMMT20	0x27	0xFF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMMT2n	I/O mode control (n= 0 - 7)
0	Output mode
1	Input mode

(3) Port Mode Control Register 2 (PMCMT2)

It can be read and written in 8-bit unit.

Figure 4-9: Port Mode Control Register 2 (PMCMT2) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMCMT2	PMCMT27	PMCMT26	PMCMT25	PMCMT24	PMCMT23	PMCMT22	PMCMT21	PMCMT20	0x2B	0x00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMCMT2n	PMMT2n	PMCMTn mode control (n = 0 - 7)
0	0	Output port
0	1	Hi-Z output
1	x	SM64 output (n = 7) SM63 output (n = 6) SM62 output (n = 5) SM61 output (n = 4) SM54 output (n = 3) SM53 output (n = 2) SM52 output (n = 1) SM51 output (n = 0)

4.6 Port MT3

4.6.1 Port MT3 functions

- 8-bit I/O port
- Port I/O specified in 1-bit units

Table 4-6: Port MT3 Functions

Port Mode	Alternate Function	TYPE	Register		
			PORT	PM	PMC
PMT30	-	A-1	×	×	-
PMT31	-	A-1	×	×	-
PMT32	-	A-1	×	×	-
PMT33	-	A-1	×	×	-
PMT34 ^{Caution}	-	A-1	×	×	-
PMT35 ^{Caution}	-	A-1	×	×	-
PMT36 ^{Caution}	-	A-1	×	×	-
PMT37 ^{Caution}	-	A-1	×	×	-

Caution: The ports PMT34 to PMT37 are connected internally to MTVSS. The port configuration for PMT3n (n = 4 to 7) must be set as follows and must not be changed afterwards:

- PMMT3n = 1: port input mode (default after reset)
- PMT3n = 0: port output = 0

Remarks: 1. PORT: Port
 PM: Port mode register
 PMC: Port mode control register

2. ×: available
 -: not available

4.6.2 Registers

(1) Port Register 3 (PMT3)

MTRC Port register 3 (MT3) is an 8-bit register that controls pin level read, output level write.

It can be read and written in 8-bit unit.

Figure 4-10: Port Register 3 (PMT3) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMT3	PMT37	PMT36	PMT35	PMT34	PMT33	PMT32	PMT31	PMT30	0x23	undefined
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMT3n ^{Caution}	Output data control (n= 0 - 7)
0	Output 0
1	Output 1

Caution: Set PMT3n = 0 for n = 4 to 7 .

(2) Port Mode Control Register 3 (PMMT3)

It can be read and written in 8-bit unit.

Figure 4-11: Port Mode Control Register 3 (PMMT3) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMMT3	PMMT37	PMMT36	PMMT35	PMMT34	PMMT33	PMMT32	PMMT31	PMMT30	0x28	0xFF
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

PMMT3n ^{Caution}	I/O mode control (n= 0 - 7)
0	Output mode
1	Input mode

Caution: Set PMMT3n = 1 for n = 4 to 7 .

4.7 Port MT4

4.7.1 Port MT4 functions

- 4-bit I/O port
- Port I/O specified in 1-bit units (PMMT4 register)
- Port mode/control mode (alternate function) specified in 1-bit units (PMCMT4 register)

Table 4-7: Port MT4 Functions

Port Mode	Alternate Function	TYPE	Register		
			PORT	PM	PMC
PMT40	EXSI1	D-2	x	x	x
PMT41	EXSO1	D-1	x	x	x
PMT42	$\overline{\text{EXSCK1}}$	D-3	x	x	x
PMT43	EXCLO	D-4	x	x	x

- Remarks:**
1. PORT: Port
 PM: Port mode register
 PMC: Port mode control register
 2. x: available
 -: not available

4.7.2 Registers

(1) Port Register 4 (PMT4)

MTRC Port register 4 (MT4) is an 8-bit register that controls pin level read, output level write.

It can be read and written in 8-bit unit.

Figure 4-12: Port Register 4 (PMT4) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMT4	0	0	0	0	PMT43	PMT42	PMT41	PMT40	0x24	undefined
R/W	R	R	R	R	R/W	R/W	R/W	R/W		

PMT4n	Output data control (n= 0 - 3)
0	Output 0
1	Output 1

(2) Port Mode Register 4 (PMMT4)

It can be read and written in 8-bit unit.

Figure 4-13: Port Mode Register 4 (PMMT4) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMMT4	1	1	1	1	PMMT43	PMMT42	PMMT41	PMMT40	0x29	0xFF
R/W	R	R	R	R	R/W	R/W	R/W	R/W		

PMMT4n	Output data control (n= 0 - 3)
0	Output mode
1	Input mode

(3) Port Mode Control Register 4 (PMCMT4)

It can be read and written in 8-bit unit.

Figure 4-14: Port Mode Control Register 4 (PMCMT4) Format

	7	6	5	4	3	2	1	0	Address	Initial value
PMCMT4	0	0	0	0	PMCMT43	PMCMT42	PMCMT41	PMCMT40	0x2C	0x00
R/W	R	R	R	R	R/W	R/W	R/W	R/W		

PMCMT43	PMCMT43 mode control
0	I/O port
1	EXCLO output

PMCMT42	PMCMT42 mode control
0	I/O port
1	$\overline{\text{EXSCK1}}$ output Note

PMCMT41	PMCMT41 mode control
0	I/O port
1	EXSO1 output Note

PMCMT40	PMCMT40 mode control
0	I/O port
1	EXSI1 Input Note

Note: The alternate function is only available if MTCS = "0".
When MTCS = "1", each I/O status is as follows.

Pin name	Status
EXSCK1	"H" level output
EXSO1	"L" level output
EXSI1	Input disabled

Chapter 5 Clock Generator

5.1 Ring Oscillator

To support a high frequency clock source for the MTRC an internal high speed Ring Oscillator is implemented in the MTRC. This Ring Oscillator is controlled with SFRs to realize stop, restart and calibration.

After the release of the $\overline{\text{MTRESET}}$ pin the Ring Oscillator is stopped. It will be automatically started if the MTCS signal will be set from "0" to "1".

Remark: For mass production tests the MTRC can be clocked alternatively direct from the FG2 device via the CLKOUT pin. This pin is internally connected with the CLK pin of the MTRC. Due to EME reason this mode is not useful for real applications.

5.1.1 Autocalibration function

At the first start of the ring oscillator it is uncalibrated and therefore significant deviations from its basic frequency (8 MHz) could be possible.

The Ring Oscillator Unit supplies an autocalibration function. With 5 specified calibration pulses at the CS pin of the MTRC (therefore PCM0/WAIT pin at the FG2) direct after MTRES release, the Ring Oscillator self-calibration unit adjusts the frequency iteratively.

The calculated calibration factor is stored in the MRCAL register. This register controls the calibration unit of the Ring Oscillator to set its frequency to 8 MHz.

5.1.2 Ring Oscillator states

With the Ring Oscillator 3 different states have to be separated:

- Calibration Mode
- Start-up after $\overline{\text{MTRESET}}$
- Start-up after Standby Mode release

At each state different actions are necessary to handle the Ring Oscillator. The basic separation depends on the handling of the MRCAL register.

5.2 Ring Oscillator Control Registers

5.2.1 RingOSC Control Register (MRCTL)

The MRCTL register is an 8-bit register that controls the RingOSC operation. This register can be read or written in 8-bit units. However, bits 1 (MRCALSF) and 0 (MRCALERR) are read-only.

- Cautions:**
1. After system reset has been released, the MRCALEN bit can be written only one time.
 2. When the MRON bit = 0, the MRCLKSEL bit can't be written.

Figure 5-1: RingOSC Control Register (MRCTL) Format (1/2)

	7	6	5	4	3	2	1	0	Address	Initial value
MRCTL	MRON	MRCLKSEL	0	MRCALEN	0	0	MRCALSF	MRCALERR	0x2E	0x50
After Reset	0	1	0	1	0	0	0	0		
R/W	R/W	R/W	R	R/W	R	R	R	R		

MRON	Operation / Stop of RingOSC and MRNGCTL operation control
0	Ring Oscillator stopped
1	Ring Oscillator enabled

This bit will be set when MRCLKSEL = 1 and a rising edge at MTCSP pin occurs.

- Cautions:**
1. After MTRESET and MTCS = "1" the MRON bit is changed from "0" to "1" by hardware.
 2. To save power consumption the Ring Oscillator can be stopped by clearing the MRON bit to "0". After that, the MTRC has to be woken up via the PCM0/CS signal. The MRCAL register has to be updated, too.

MRCLKSEL	System clock selection for meter
0	CLK as input for clock supply by FG2
1	internal Ring Oscillator as clock source

Caution: If MRON bit = "0" (Ring Oscillator stopped for power saving) no MTRC register access is possible. Therefore the MRON bit can't be set to "1" (Ring Oscillator as clock source)

Figure 5-1: RingOSC Control Register for the Meter (MRCTL) Format (2/2)

MRCALLEN	Ring Oscillator frequency calibration operation control
0	Calibration disabled
1	Calibration enabled

Caution: After the $\overline{\text{MTRESET}}$ pin has been released, the MRCALLEN bit can be written only one time.

MRCALSF	RingOSC frequency calibration operation status flag
0	Ring Oscillator calibration procedure is not active
1	during the Ring Oscillator calibration procedure

The MRCALSF bit will be set to “1” when the MRON bit = 1 (ring oscillator activated) and the MRCALLEN bit = “1” (MTRC is set to calibration mode)

The MRCALSF bit will be reset to “0” by the following condition:

- when MRON bit = “0” (ring oscillator deactivated)
- when calibration procedure was finished successful
- when calibration error occurred with MRCALLEN bit = “1”
- when MRCALLEN bit = “0” (calibration register MRCAL has to be rewritten manually without automatic calibration procedure)

MRCALERR	RingOSC frequency calibration error flag
0	No calibration error
1	Calibration error

The MRCALERR bit is set to “1”, when the ring oscillator calibration is not normally executed. This will happen, when the pulse width of the calibration pulse at the MTCS pin hasn’t got the specified high and low pulse width, or the calibration temperature is not in the specified range.

When the MRON bit is set to “0” (ring oscillator stopped) the MRCALERR bit will be reset to “0”.

5.2.2 RingOSC Calibration Register (MRCAL)

The MRCAL register is a 5-bit register for the RingOSC calibration operation. This register can be read or written in 8-bit units.

This register can be set in a range of 0x01 to 0x1F. The frequency of RingOSC will be increased by the MRCAL register value.

If the MRON bit = “0” and the MRCALEN bit = “1” (MRCTL register) the MRCAL register will be set to 0x10, which is the middle of its value range.

This register can be written only once:

- after $\overline{\text{MTRESET}}$ pin release:
After setting MRON bit = 1 (done by hardware if MTCS bit = 1) and MRCALEN bit = 0 (written manually)
- after standby mode release:
After setting MRON bit from 0 to 1 while MRCALEN bit = 0

Figure 5-2: RingOSC Calibration Register (MRCAL) Format

	7	6	5	4	3	2	1	0	Address	Initial value
MRCAL	0	0	0	MRCAL4	MRCAL3	MRCAL2	MRCAL1	MRCAL0	0xXX	0x50
After Reset	0	0	0	1	0	0	0	0		
R/W	R	R	R	R/W	R/W	R/W	R/W	R/W		

Caution: When the MRON bit is set to 1 after a power save mode (MRON bit was “0”) this register has to be rewritten with the formerly stored calibration value (e.g. external EEPROM) that has followed from the frequency calibration at the specified temperature and voltage.

5.3 Calibration Procedure

To calibrate the Ring Oscillator 5 specified calibration pulses of the same length at the PCM0 pin of the FG2 are necessary. To guarantee the maximum deviation of the calibrated Ring Oscillator this calibration has to be performed at the specified temperature and with the specified voltage.

After the autocalibration of the ring oscillator the calibration correction value is stored in the MRCAL register. This value has to be read out and stored in a nonvolatile memory (e.g. external EEPROM) if the ring oscillator has to be stopped for power save mode and woken up again after power save mode. This is due to the fact, that the data retention of the MRCAL register can't be guaranteed during the time of the stopped ring oscillator.

Please see the following procedure for the autocalibration function.

Figure 5-3: Flowchart for Frequency Calibration

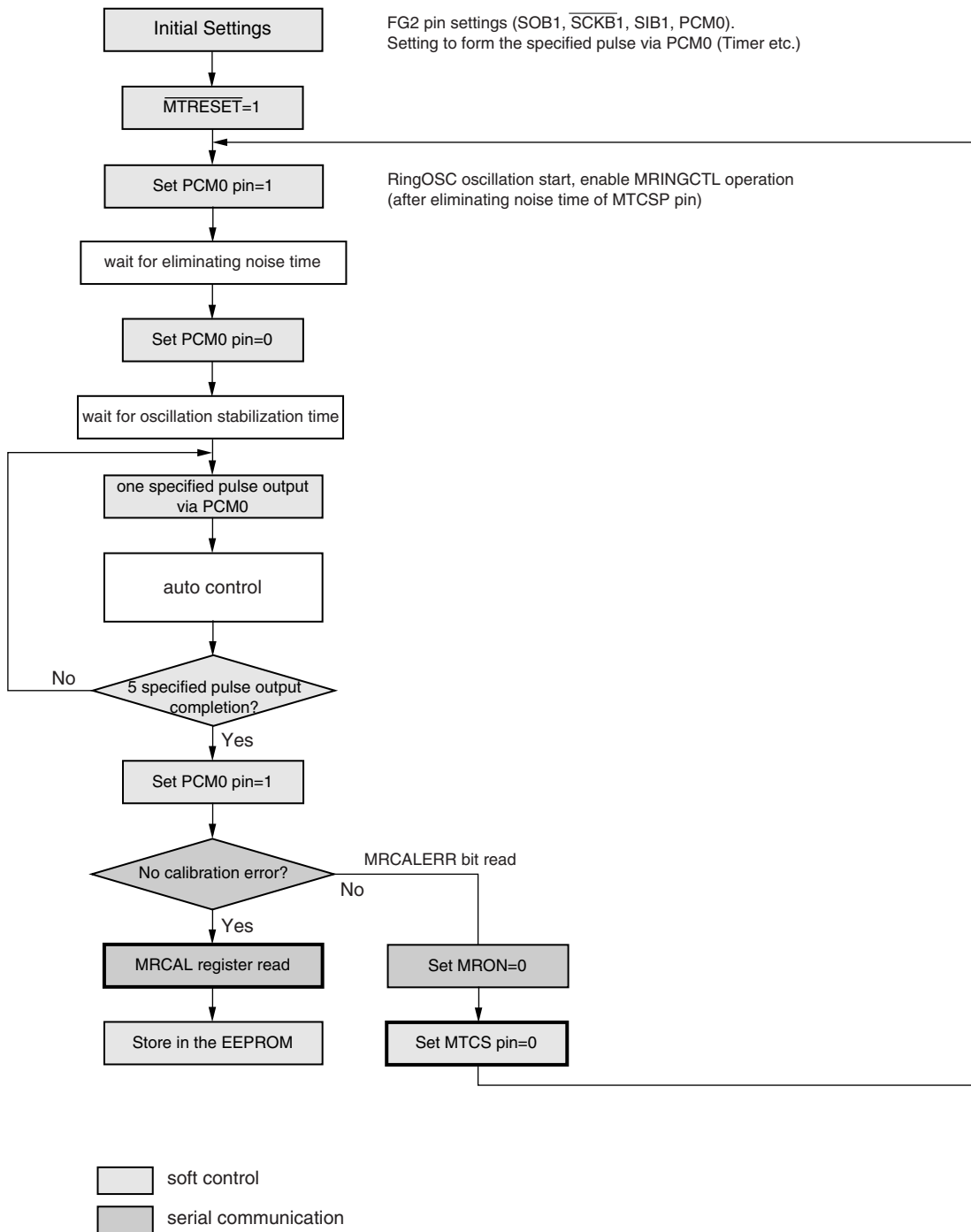
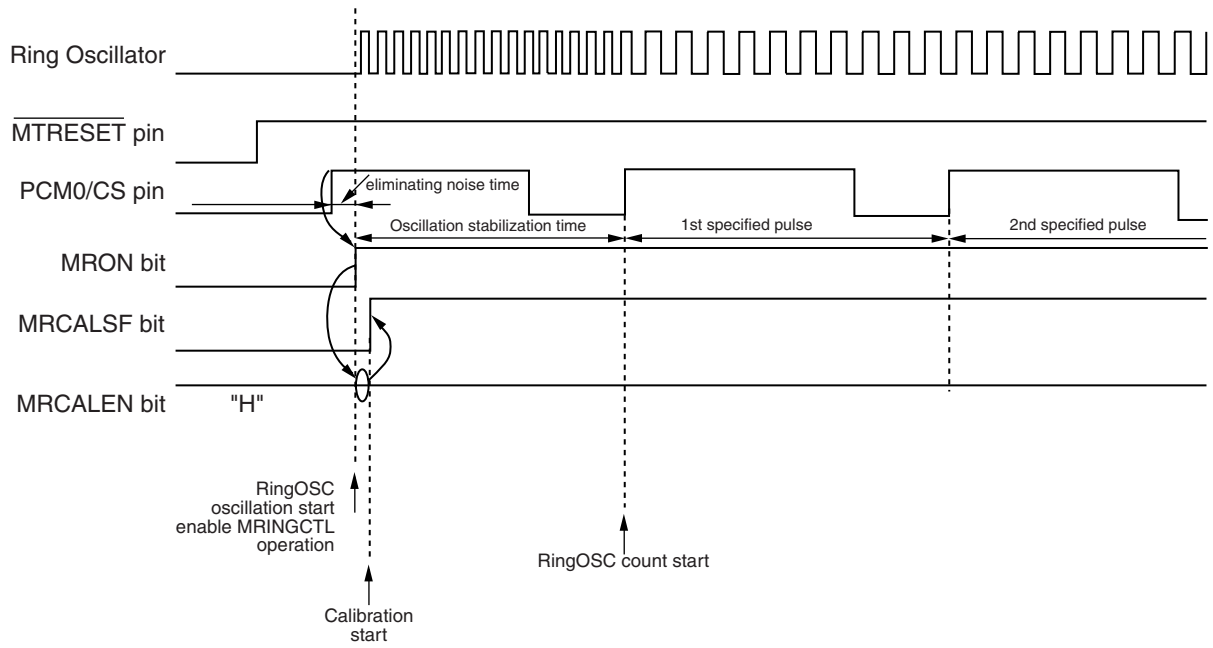


Figure 5-4: Timing Diagram for Frequency Calibration



5.4 MTRRESET Release of the MTRC

If the MTRC is reset, the MRCAL register will be reset, too. Therefore the beforehand stored MRCAL register value has to be written back.

Please see the following procedure for the $\overline{\text{MTRRESET}}$ Release of the MTRC.

Figure 5-5: Flowchart for MTRRESET Release

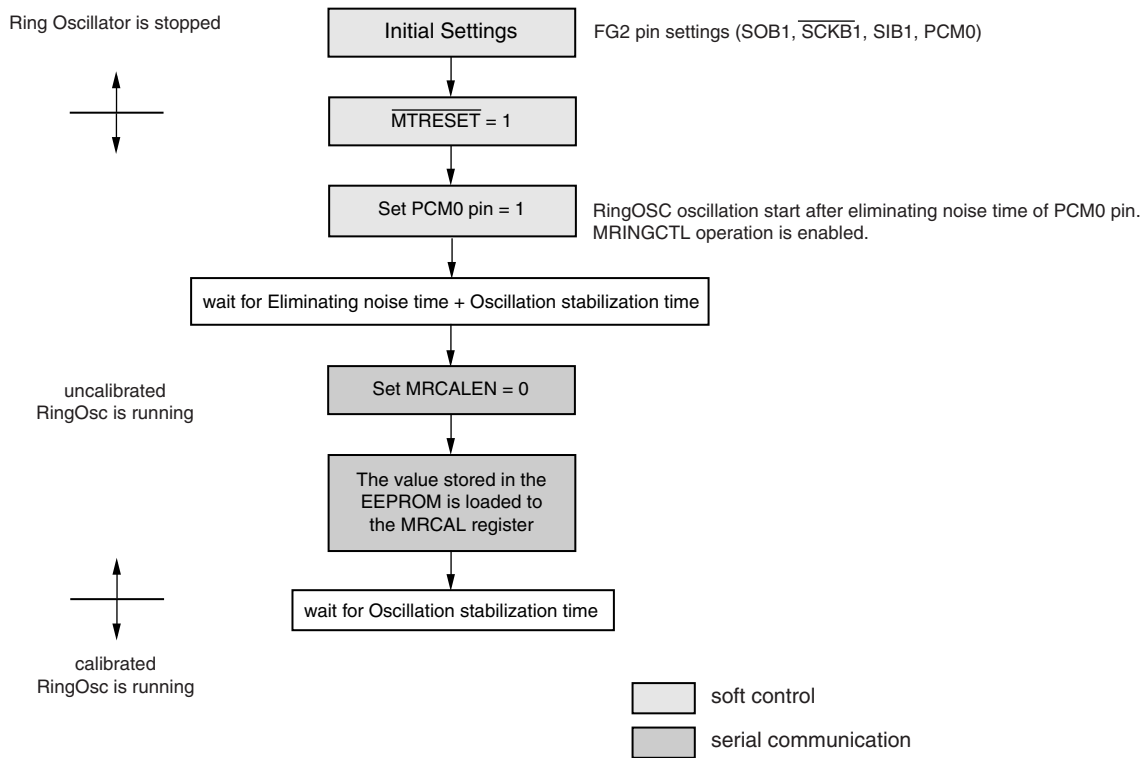
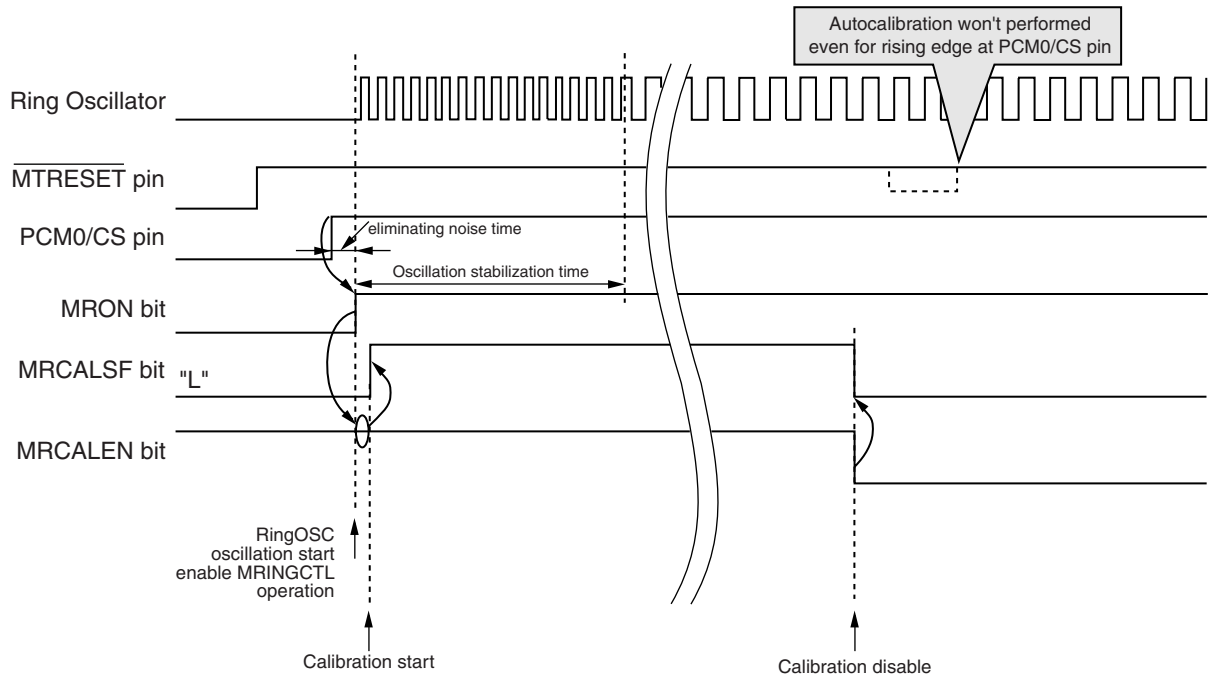


Figure 5-6: Timing for MTRES Release



5.5 Standby Mode Release of the Ring Oscillator

To save power, the ring oscillator could be switched off via setting the MRON bit of the MRCTL register = 0.

During the time of the stopped Ring Oscillator, the data retention of the MRCAL register can't be guaranteed. Therefore the before stored value of the MRCAL register (e.g. in an external EEPROM) has to be write back to the MRCAL register after the waken.

The PCM0 pin of the FG2 will wake up the Ring Oscillator from its standby mode. To switch the Ring Oscillator on again the following procedure has to be fulfilled.

Figure 5-7: Flowchart for Standby Mode Release

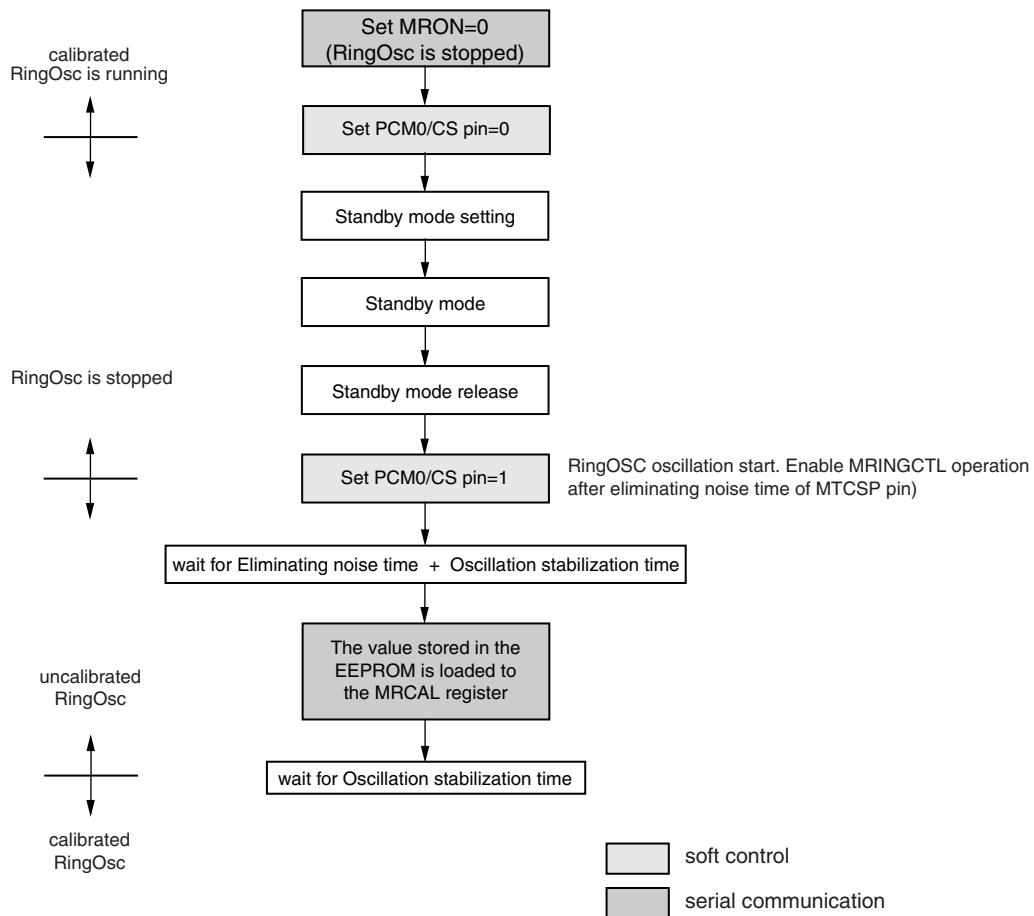
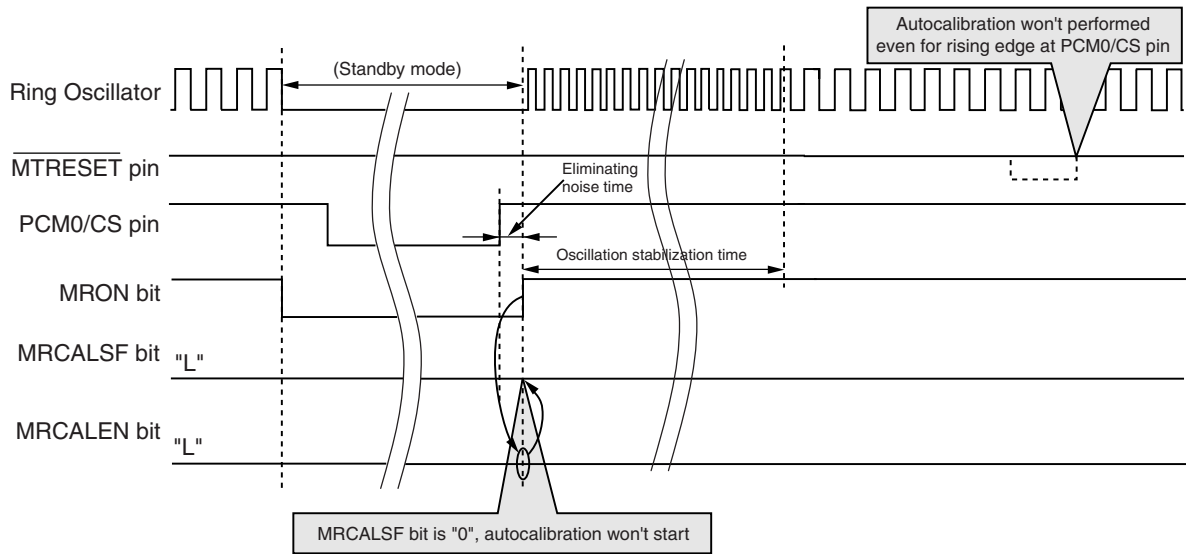


Figure 5-8: Timing Diagram for Standby Mode Release



5.6 Cautions

- (1) The calibration has to be performed at the specified conditions (Temperature and Voltage). If performing at other condition, the accuracy of the ring oscillator cannot be guaranteed.
- (2) The basic calibration pulse must have the specified High and Low pulse width at the PCM0/CS pin.
- (3) Be sure to input 5 basic pulses.
- (4) After calibration executing, the MRCALERR bit = 0 has to be checked before storing the MRCAL value (i.e. in an EEPROM). This has to be done after setting the MTCS pin = 1 and performing the 5 basic calibration pulses.
- (5) If a calibration error occurs (check if after 5 basic calibration pulses the MRCALERR bit = 1), set the MRON bit to "0". After this set it to "1" again and execute the calibration once again. This can be necessary if the calibration conditions were not adhered to the calibration condition specification.
- (6) The power consumption can be reduced by stopping the RingOSCs by clearing the MRON bit to "0". Therefore the basic clock supply of the MTRC will be stopped, too. When after power save mode release the MRON bit is set to "1" again, the stored calibration value has to be written to the MRCAL register first. If this is not executed, the accuracy of the ring oscillator cannot be guaranteed.
- (7) During power save mode the MTCS pin can not be used, except for power save mode release only.
- (8) Be sure to set the MRCALLEN bit = 0 after system reset has been released and the operation of ring oscillator has been started. If this is not done, the accuracy of the ring oscillator cannot be guaranteed.
- (9) Secure the "eliminating noise time" of PCM0/CS signal and the "oscillation stabilization time of the ring oscillator" at power save mode release.
- (10) Secure oscillation stabilization time of the ring oscillator before writing the stored calibration value to the MRCAL register.
- (11) Do not set the MRCALLEN bit = 0 when the automatic calibration is executed.
(The MRCALLEN bit can't be set to "1" after set to "0". This will be done by hardware only at $\overline{\text{MTRESET}} = 0$.)

[MEMO]

Chapter 6 Serial Interface

6.1 Communication Protocol

The CSI of the MTRC is fixed to the following operation mode:

Communication protocol: Clocked synchronous serial interface

- Data length: 8-bits fixed
- Transfer direction: MSB first
- Transfer mode: Transmit/Receive mode
- Serial clock frequency: $f_{SCK} \leq f_{Ring\ Oscillator} / 4$

Remark: f_{SCK} : Serial Interface clock
 $f_{Ring\ Oscillator}$: frequency of MTRC Ring Oscillator

Communication format:

1st byte (Command + Address)	2nd byte to last byte (Data)
---------------------------------	---------------------------------

6.2 Command Table

Instruction	Command (+ Address)	Data
READ	$I_7I_6A_5A_4A_3A_2A_1A_0$ (input)	$D_7D_6D_5D_4D_3D_2D_1D_0$ (output)
WRITE	$I_7I_6A_5A_4A_3A_2A_1A_0$ (input)	$D_7D_6D_5D_4D_3D_2D_1D_0$ (input)

6.2.1 Command Byte

This is the 1st Received Data at communication start, that was sent from the FG2 device.

	7	6	5	4	3	2	1	0
Command	RW	AUTO	A5	A4	A3	A2	A1	A0

RW	R/W Selection of MTRC
0	Read
1	Write

AUTO	Operation mode of Communication
0	Disable Continuous transfer
1	Enable Continuous transfer

A5 to A0	Address
0/1	define address data as 6-bit format

6.2.2 Data Bytes

After the Command Byte the Data Bytes follows.

When read function is selected, the MTRC outputs data which was specified by the address of the Command Byte.

When the write function is selected the FG2 device outputs data which are written to the MTRC addresses specified by the Command Byte before.

	7	6	5	4	3	2	1	0
Data	D7	D6	D5	D4	D3	D2	D1	D0

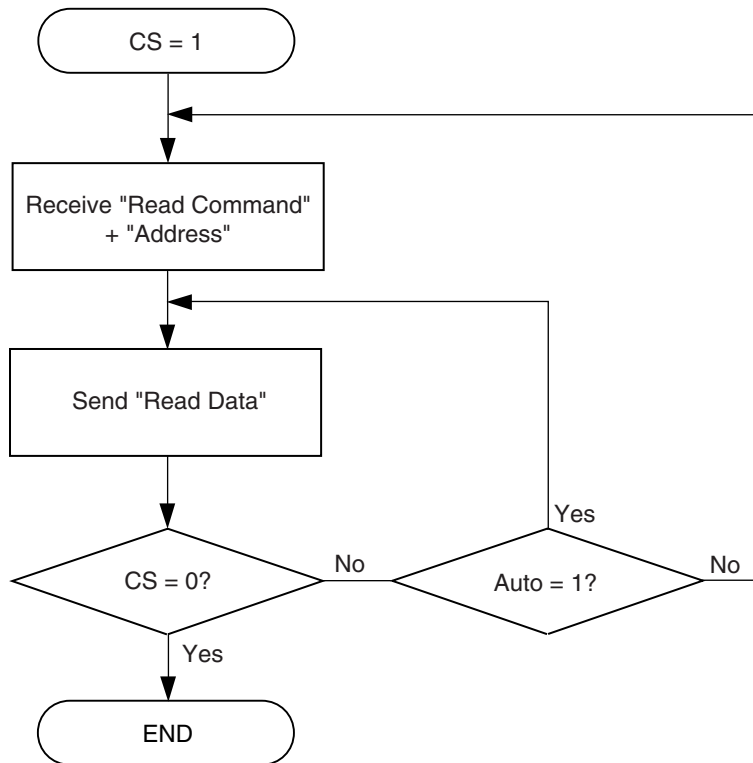
6.3 Serial I/F Operation

6.3.1 Read from MTRC operation

After PCM0/CS = "1", the MTRC is waiting for the command byte via the SI pin. If the read command is received the MTRC outputs data via the SO pin, which were specified with the address bits A5 to A0.

When continuous transfer is selected (Auto bit of Command Byte = "1"), the MTRC outputs next data, at the incremented address via the SO pin.

Figure 6-1: MTRC Operation Flow on Reading



6.3.2 Timing of MTRC Read operation

Figure 6-2: MTRC Read Operation (Auto=0)

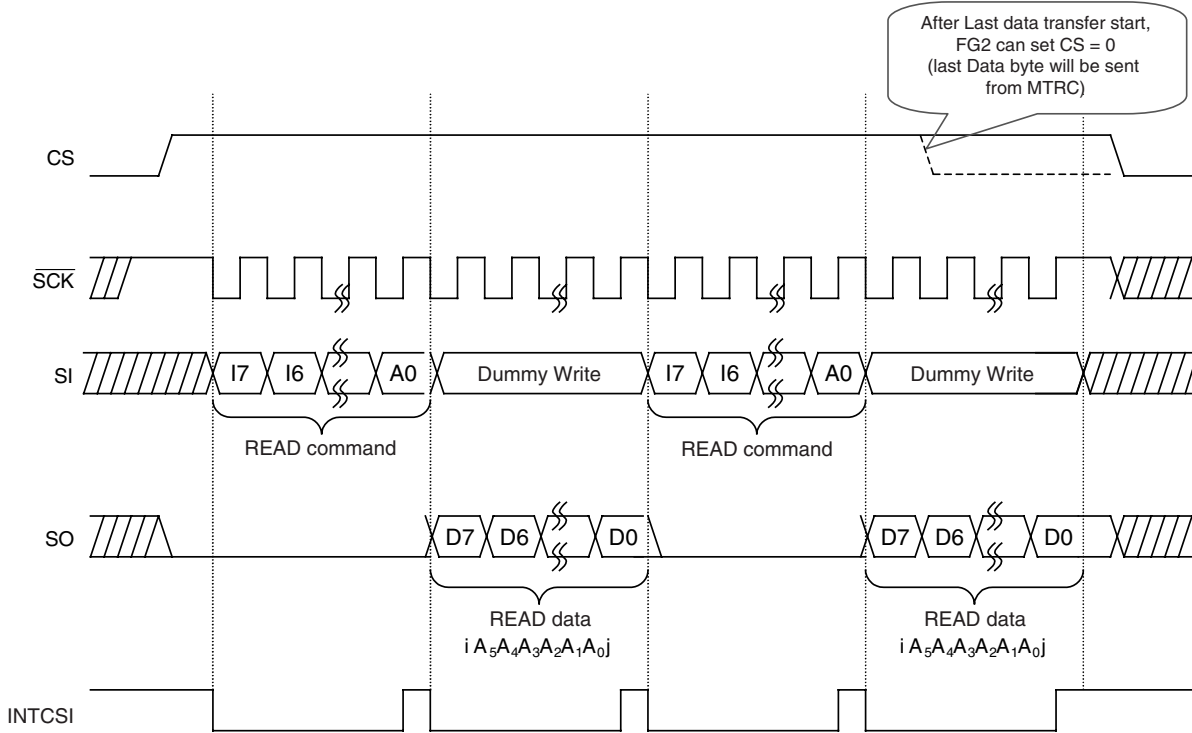
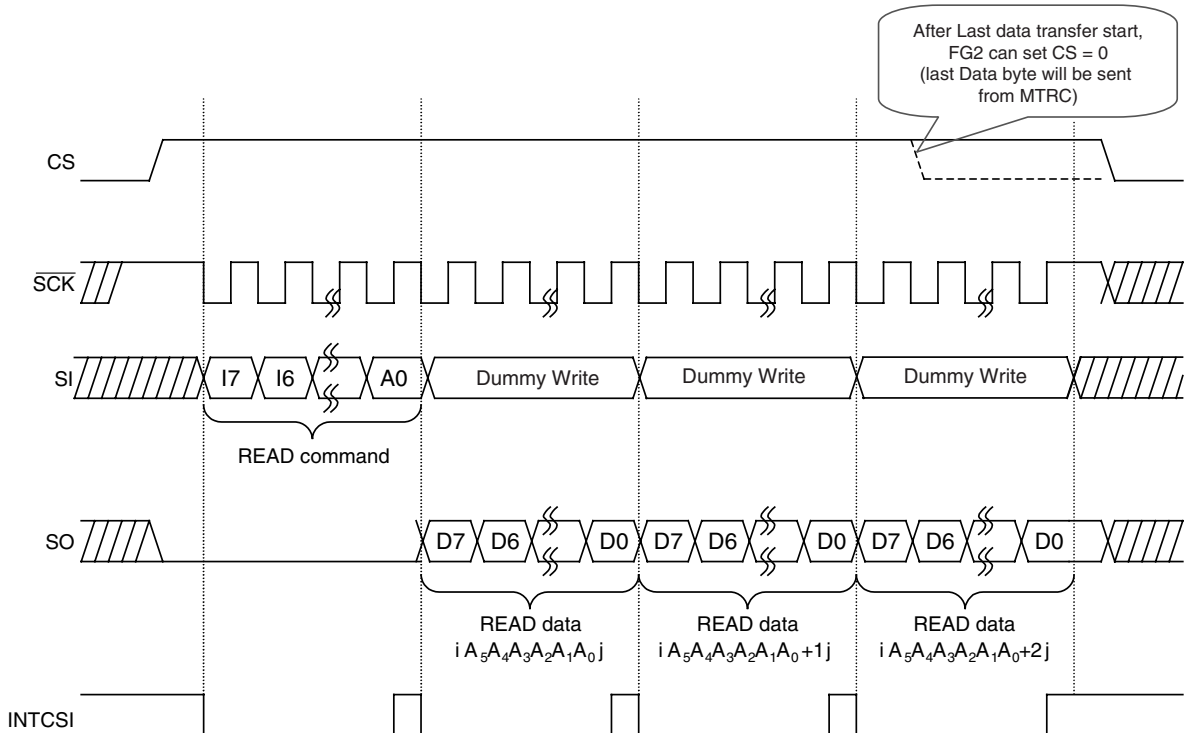


Figure 6-3: MTRC Read Operation (Auto bit = 1)

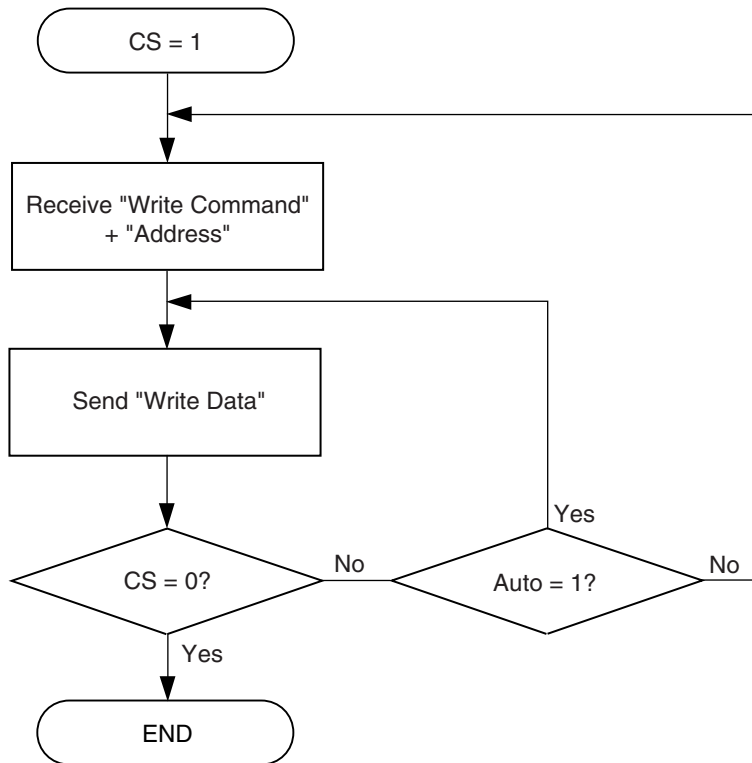


6.3.3 MTRC Write operation

After CS pin = "1", MTRC received write command/address via SI pin. After receive command, MTRC write next receive data, which is specified address.

When select continuous mode (Auto = "1"), next receive data will be written 1 incremented address. When select disable continuous mode (Auto = "0"), After receive 1 byte data, MTRC decide that next received data as command/address

Figure 6-4: Operation Flow on MTRC Writing



6.3.4 Timing of MTRC Write operation

Figure 6-5: MTRC Write Operation (Auto bit = 0)

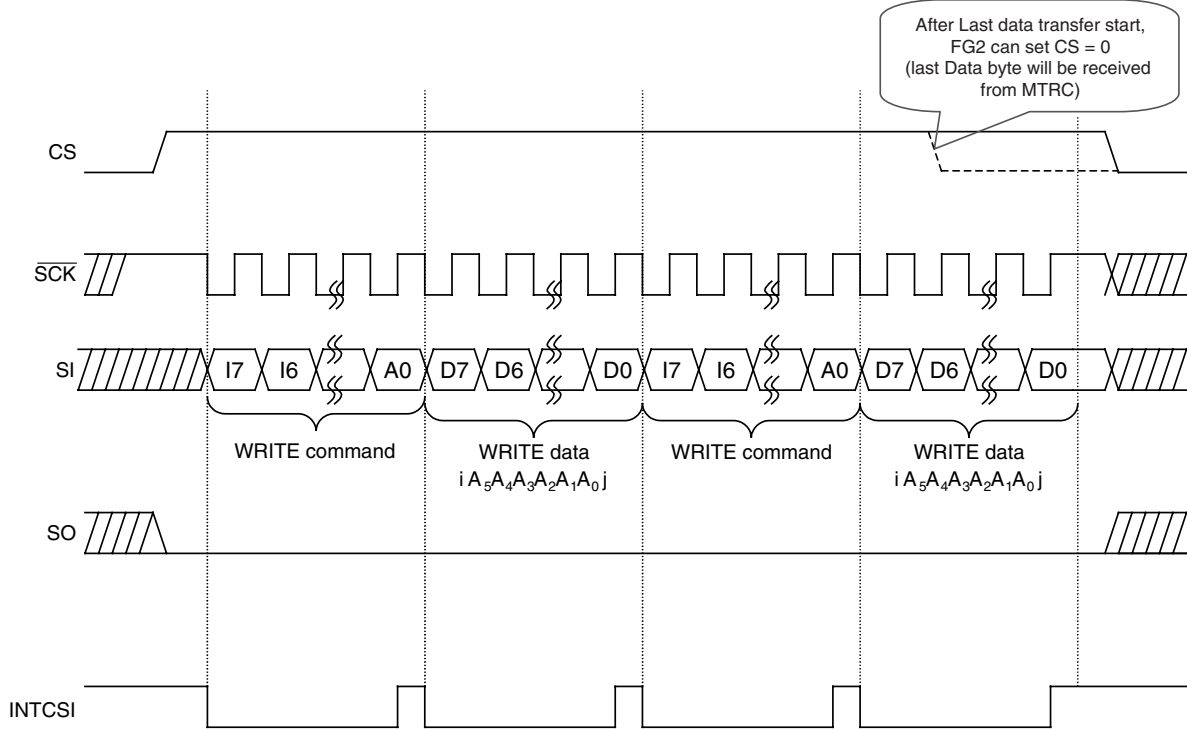
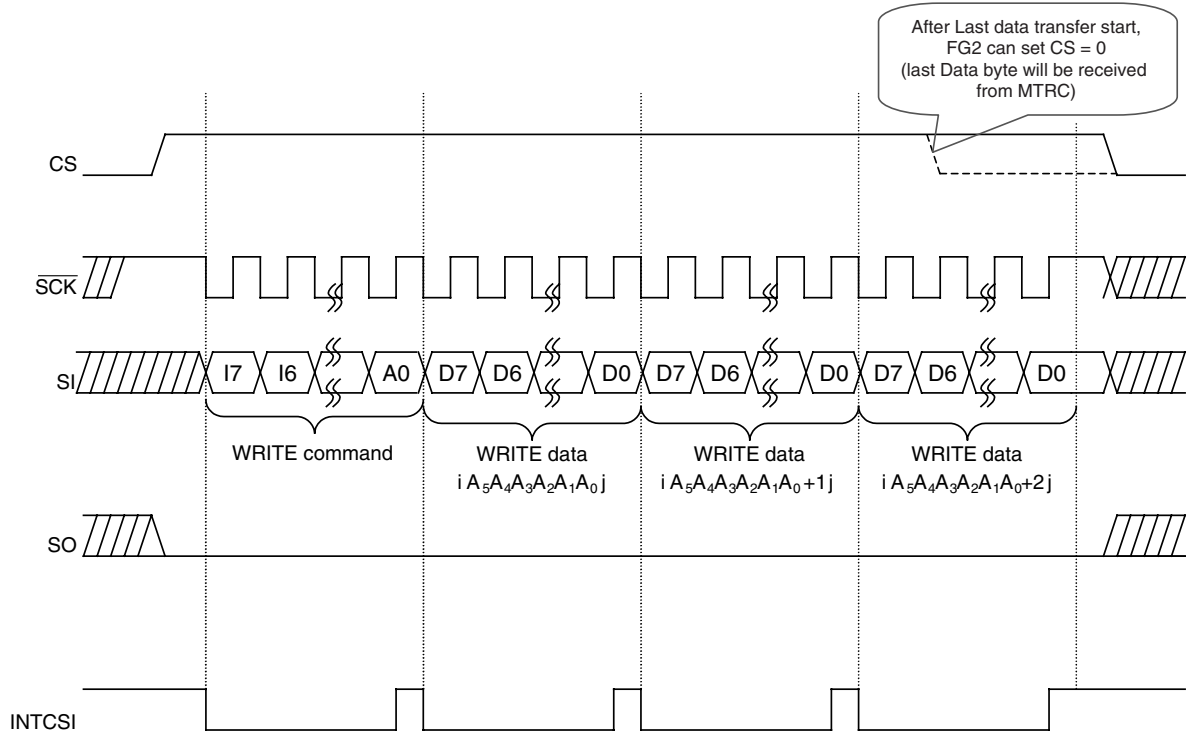


Figure 6-6: MTRC Write Operation (Auto bit = 1)



6.4 External CSIB1 Function (EXCSI1)

If the PMT4 port is configured for peripheral mode the PCM0/CS signal controls the output function of the external CSIB1 (EXCSI1) functionality. The EXCSIB1 provide the FG2 CSIB1 communication for external components, too. This function can be used, if there's no internal communication between the FG2 device and the MTRC (refer to Figure 1-2, "CS Functionality," on page 20).

With special regard to the last byte transfer of the internal communication protocol a switch control will delay the switching until the last byte was transferred between FG2 and the MTRC.

- Remarks:**
1. If the EXCSI1 is used, and the CS is set to "0" during the last byte transfer, the EXSO1 and EXSI1 signal will be suppressed until the last Byte transfer has ended. Therefore an external component receives no signals from the last internal MTRC communication.
 2. After the switching the last communicated signal level at SOB1 of the internal communication will remain at the EXSO1 pin.

6.5 Internal CSIB1 Function

6.5.1 Operation of Serial Interface

The communication I/F of the MTRC is fixed to the following settings:

- I/F: CSI
- Mode: Slave mode
- Data length: 8-bits
(support continuous data transfer,
therefore the FG2 CSIB1 can use 16-bit data
length)
- Transfer: MSB first
- Transmission: transmission/reception mode
- Baudrate: maximum $f_{\text{Ring Oscillator}} / 4$

- Cautions:**
1. The internal ring oscillator of the MTRC is not synchronized to the CSIB1 $\overline{\text{SCKB1}}$ signal. Furthermore the MTRC needs time to process the incoming commands and data. Therefore the baudrate of the FG2 CSIB1 has to be set to maximum of $f_{\text{Ring Oscillator}} / 4$.
 2. After $\overline{\text{MTRESET}}$ release, the Ring Oscillator is uncalibrated. Therefore the maximum specified frequency deviation (especial the min. $f_{\text{Ring Oscillator}}$) for the uncalibrated Ring Oscillator has to be regarded.

(1) Basic operation

The MTRC serial interface is only working in slave mode.

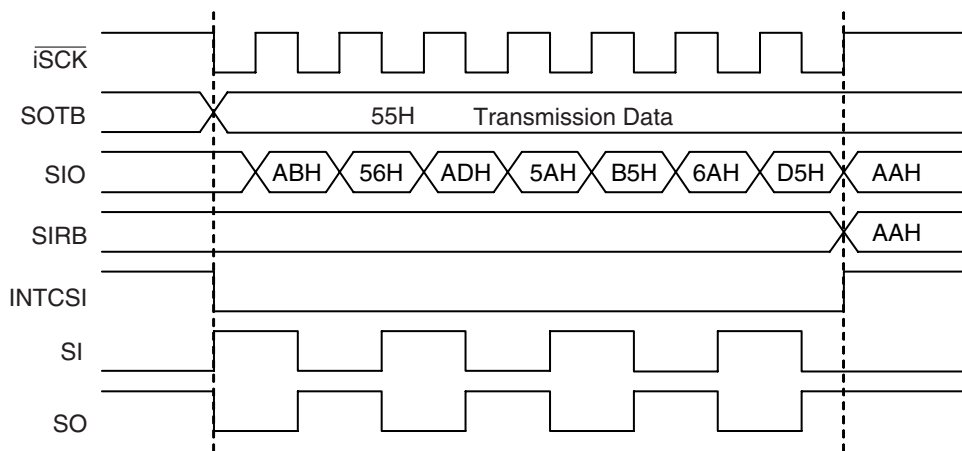
When iSCK clock is applied the transfer operation is started.

There's a delay between SCK of the CSIB1 from FG2 and the iSCK of the MTRC. The iSCK signal is synchronised with the MTRC Ring Oscillator. If the Ring Oscillator is stopped no communication is possible.

SIO shift operation is synchronised with the falling edge of iSCK. The data which is received via SI pin is latched.

SIO on rising edge of iSCK.

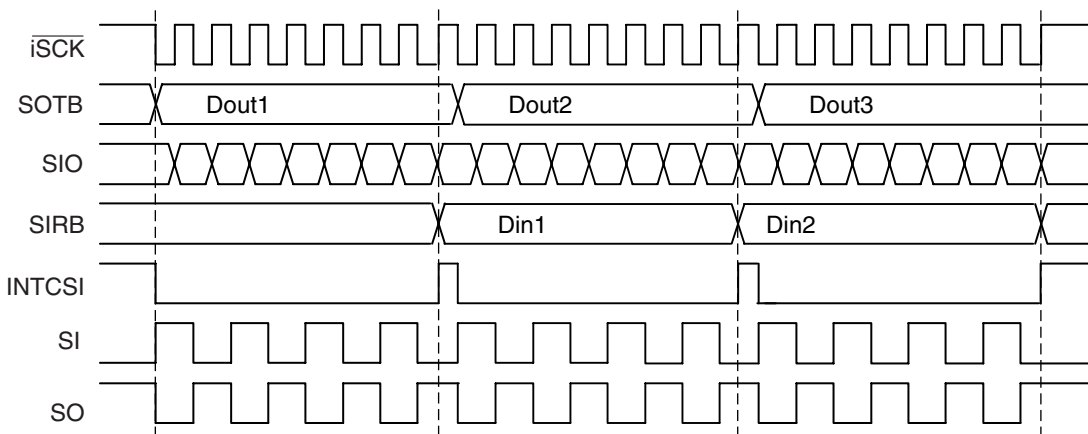
Figure 6-7: Basic Operation



(2) Continuous data transfer

In spite of the fix 8-bit mode of the MTRC CSI, it supports continuous data transfer mode. Therefore the FG2 CSIB1 can set to 16-bit mode and continuous data transfer for the fastest communication.

Figure 6-8: Continuous Data Transfer



[MEMO]

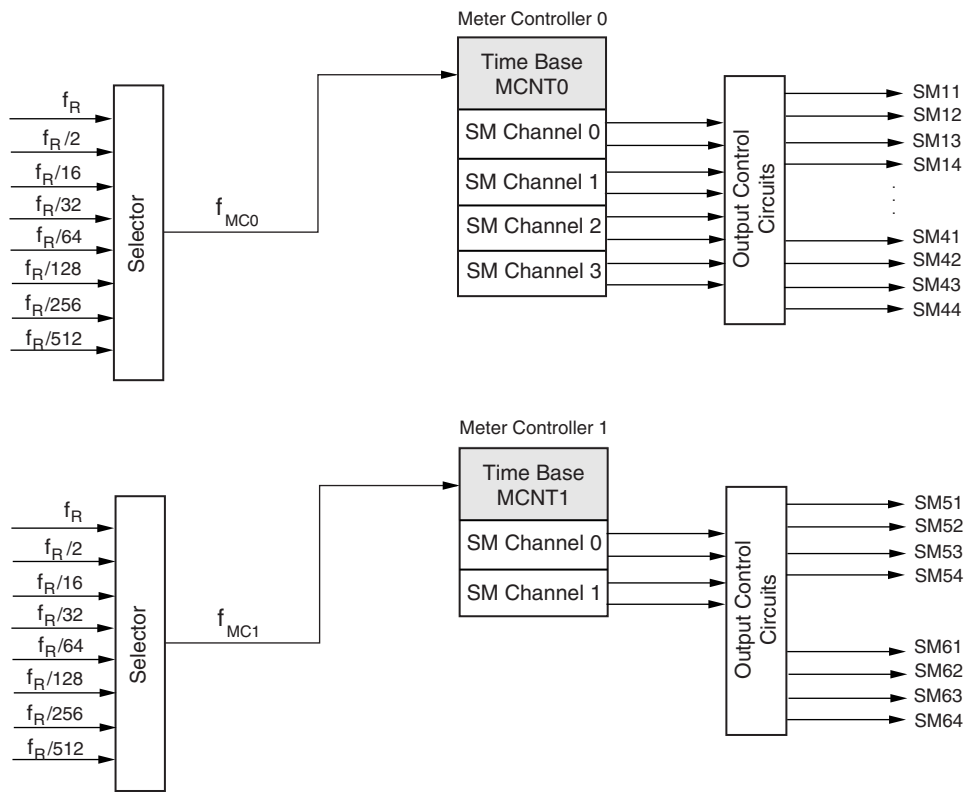
Chapter 7 Meter Controller Driver

This MTRC has $6 \times 360^\circ$ type meters controllable driver.

7.1 Meter Controller Driver Function Outline

- 8-bit free run counter $\times 2$
- 8-bit compare register $\times 12$
- 8-bit +1 accuracy PWM output $\times 24$

Figure 7-1: Meter Controller Driver Block Diagram



7.2 Register Setting

7.2.1 Free Running Counter m (MCNTm, m = 0, 1)

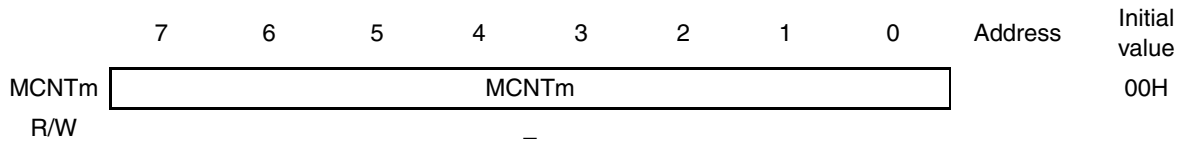
MCNTm is an 8-bit free running counter. This counter will be incremented by f_{MCn} (n = 0, 1). This frequency is generated from CLK1 and the selected prescaler.

The counter starts by setting the PCEm bit = "1" of MCNTCm register.

After reaching the value FFH the counter will be overflowed and set itself to 01H.

MCNTm can't be written or read.

Figure 7-2: Free Running Counter MCNTm Format



The count value is cleared in the following cases.

- RESET = "0"
- PCEm = "0"

The relation of the duty factor for the PWM output from the SMnm pin is calculated by the following expression:

$$\text{PWM (duty)} = \text{Set value MCMPnm} / 255 \times 100\%$$

Remark: n = 1 to 6
m = 0, 1

7.2.2 Sin Compare Register n0 (MCMPn0, n = 1 to 6)

MCMPn0 is an 8-bit register, which continuously compares its value with the MCNTm value. When the two values match, a match signal of sin side of meter n is generated. MCMP10 to MCMP40 are compared with MCNT0, MCMP50 to MCMP60 are compared with MCNT1. MCMPn0 are in master-slave configuration. MCNTm is compared with the slave register.

Transmit from master register to slave register executes at

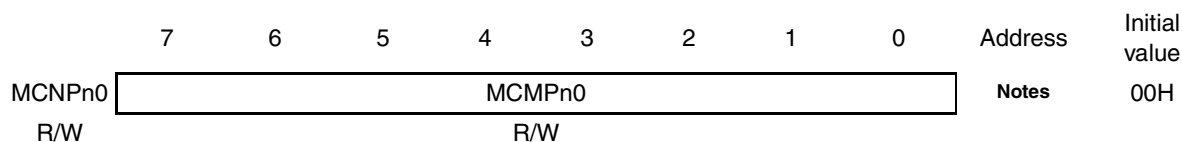
TENn = "1" AND when overflow occurs.

Ensure that the TENn bit = "0" (i.e. rewriting time < PWM cycle time), then set MCMPn0 and the corresponding TENn bit to 1.

The PWM pulse is not output until the first overflow occurs after the counting operation has been started, because the compare data is not transferred to the slave beforehand.

MCMPn0 is set with an 8-bit memory manipulation instruction. The value of these register are set to 00H at MTRESET = "0".

Figure 7-3: Sin Compare Register MCMPn0 Format



- Note:** MCNP10 at 0x00
 MCNP20 at 0x03
 MCNP30 at 0x06
 MCNP40 at 0x09
 MCNP50 at 0x0C
 MCNP60 at 0x0F

Remark: n = 1 to 6

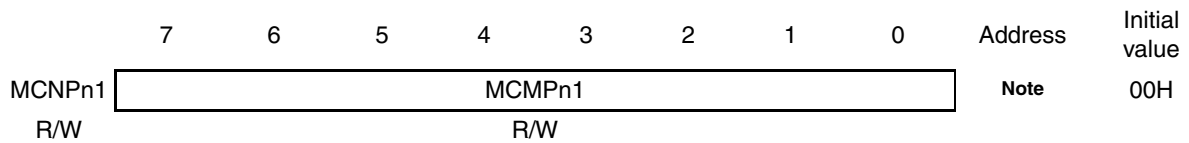
7.2.3 Cos Compare Register n1 (MCMPn1, n = 1 to 6)

MCMPn1 is an 8-bit register, with the same functionality of the MCMPn0 register but for the cos signal. When the above two values match, a match signal of cos side of meter n is generated. MCMP11 to MCMP41 are compared with MCNT0, MCMP51 to MCMP61 are compared with MCNT1.

For the handling of the TENn bit please refer to the MCMPn0 register

MCMPn1 is set with an 8-bit memory manipulation instruction. The value of these register are set to 00H at $\overline{MTRESET} = "0"$.

Figure 7-4: Cos Compare Register MCMPn1 Format



- Note:**
- MCNP11 at 0x01
 - MCNP21 at 0x04
 - MCNP31 at 0x07
 - MCNP41 at 0x0A
 - MCNP51 at 0x0D
 - MCNP61 at 0x10

Remark: n = 1 to 6

7.2.4 Compare Control Register (MCMPCn, n = 1 to 6)

MCMPCn is an 8-bit register that controls the operation of the compare register and output direction of the PWM pin. TENn bit becomes “0” automatically after finished transmission from master register to slave register.

Caution: If the master register is written during transmit from master register to slave register, transmission data may break. Confirm that the time for rewriting the TEN bit is greater than the count period of the MCNTm counter register.

MCMPCn is set with an 8-bit memory manipulation instruction. MTRESET =”0” clears MCMPCn to 00H.

Figure 7-5: Compare Control Register MCMPCn Format (1/2)

	7	6	5	4	3	2	1	0	Address	Initial value
MCMPCn	0	0	0	TENn	ADBn1	ADBn0	DIRn1	DIRn0	Note	0
R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

Note: MCMPC1 at 0x02
 MCMPC2 at 0x05
 MCMPC3 at 0x08
 MCMPC4 at 0x0B
 MCMPC5 at 0x0E
 MCMPC6 at 0x11

TENn	Enable transfer by register from master to slave
0	Disable data transfer from MCMPCn master to slave. New data can be written.
1	Enable data transfer from MCMPCn master to slave. (Data transfer is executed from master to slave when next MCNTm overflow occurs) New data cannot be written.

Caution: Ensure that the time for rewriting the TEN bit is greater than the count period of the MCNTm counter register (PWM cycle time).

Remarks: 1. TENn bit is cleared automatically after data transfer from MCMPCn master register to slave register has finished.
 2. Don't rewrite TENn bit when CAE bit is “0”.

Figure 7-5: Compare Control Register MCMPn Format (2/2)

ADBn1	Control of 1-bit addition circuit (cos side of meter n)
0	No 1-bit addition
1	1-bit addition

ADBn0	Control of 1-bit addition circuit (sin side of meter n)
0	No 1-bit addition
1	1-bit addition

The 1-bit addition adds 1 further PWM tick to the PWM value that was set with the MCMPn register, but only every second PWM cycle. Therefore in the average value will be only 1/2 PWM tick, which corresponds with a further bit for the resolution of the PWM value (quasi 9-bit resolution).

DIRn1	DIRn0	Control of PWM output pin			
		SMn1 (sin+)	SMn2 (sin-)	SMn3 (cos+)	SMn4 (cos-)
0	0	PWM	0	PWM	0
0	1	PWM	0	0	PWM
1	0	0	PWM	0	PWM
0	1	0	PWM	PWM	0

7.2.5 Timer Mode Control Register (MCNTm) (m = 0, 1)

MCNTCm is an 8-bit register that controls the operation of the timer counter MCNTm. MCNTCm is set with an 8-bit memory instruction. MTRESET = "0" clears MCNTCm to 00H.

Figure 7-6: Timer Mode Control Register (MCNTm) Format (1/2)

	7	6	5	4	3	2	1	0	Address	Initial value
MCNTCm	CAE ^{Note1}	0	0	PCEm	0	SMCLm2	SMCLm1	SMCLm0	Note2	0
R/W	R/W	R	R/W	R/W	R	R/W	R/W	R/W		

Notes: 1. CAE is a flag that is only available in MCNTC0.

- 2. MCNTC0 at 0x12
MCNTC1 at 0x13

Cautions: 1. First of all, set CAE = "1" to operate this macro.

- 2. To enable the operation the PCE bit has to be set to "1", after setting the CAE, SMCL02, SMCL01 and SMCL00 bits.
- 3. At DJ2 (6 SM channels): to set this macro into power save mode first set PCE1 = 0 then set the CAE and PCE0 bit simultaneously to "0"

Remark: SMCL02, SMCL01, SMCL00 bit and CAE bit can be written at same time in purpose to decrease frequency of register access.

CAE	Control of internal clock operation
0	Disables the internal clock supply
1	Enables the internal clock supply

By setting CAE = 0 the count operation is stopped. This is used to reduce the power consumption.

Remark: If the CAE bit will be set to "0" the counter MCNTCn register will hold it's value and the PWM output pin will hold its actual Level. To clear the counter and set the PWM output pin to inactive level, PCEm = 0 has to be set beforehand.

PCEm	Timer counter operation control
0	Operation is stopped with clearing the timer value and the associated PWM output pins will be set to Low level
1	Operation enable

Remarks: 1. the CAE and PCE0 bit can be set simultaneously to "0" (same register)

- 2. If only the 4 SM channels of the MCMT0 counter are used the power consumption can be reduced by writing the CAE bit and the PCE0 bit simultaneously. In other cases set PCE1 bit = 0 beforehand.

Figure 7-6: Timer Mode Control Register (MCNTm) Format (2/2)

SMCLm2	SMCLm1	SMCLm0	Timer counter 1 clock selection
0	0	0	f_R
0	0	1	$f_R / 2$
0	1	0	$f_R / 16$
0	1	1	$f_R / 32$
1	0	0	$f_R / 64$
1	0	1	$f_R / 128$
1	1	0	$f_R / 256$
1	1	1	$f_R / 512$

7.3 Operation

7.3.1 Count timing

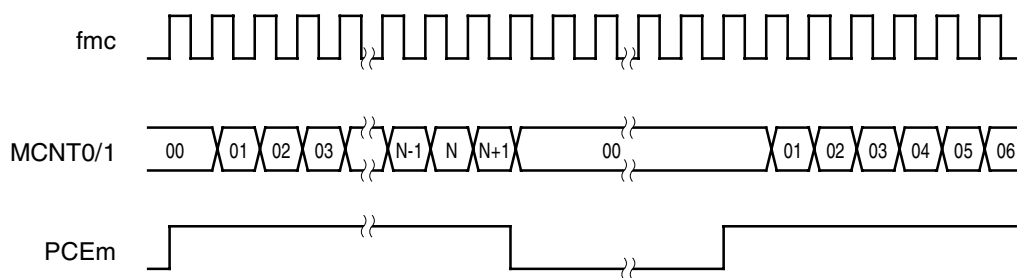
The counter is counted up by the rising edge of the f_{MCn} clock signal that is selected by the SMCLm2 to 0 bits.

The counting operation is enabled or disabled by the PCEm bit of the timer mode control register.

The MCNTm register is cleared by $MTRESET = "0"$ or $PCEm = "0"$ and counting operation stops.

The first count cycle could include a clock error $\leq 1 f_{MCn}$ clock due to the fact of the synchronization with the f_{MCn} clock.

Figure 7-7: Restart Timing after Counting Operation Stopped



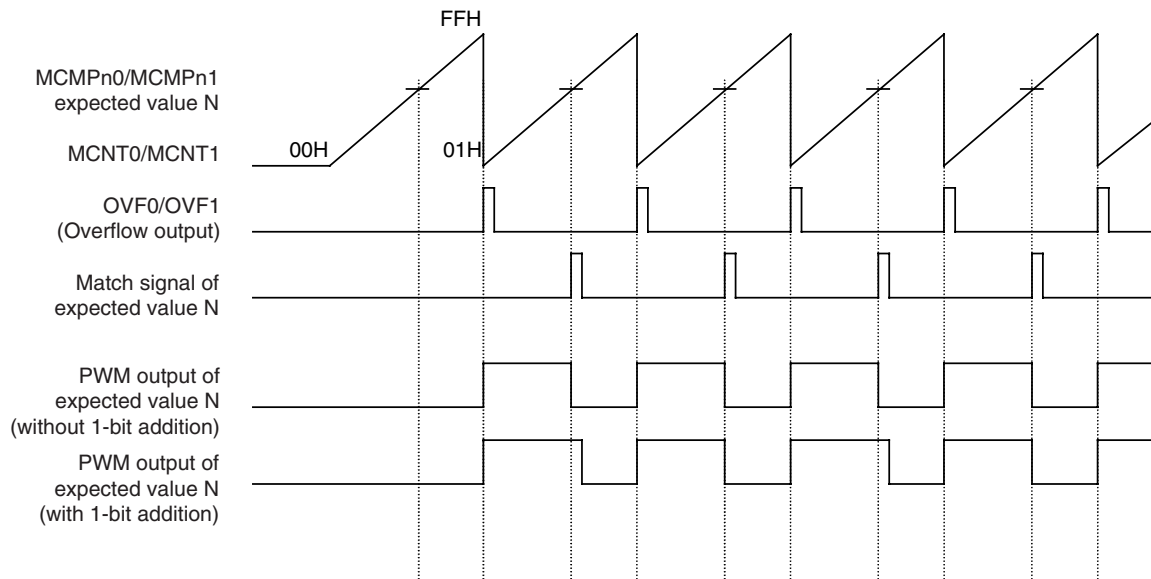
Remark: Counting operation starts → counting operation stops → counting operation start

7.3.2 Operation of 1-bit addition circuit

1-bit addition to the PWM output is activated by setting ADBn1, ADBn0 bit of the MCMPn register to "1".

1-bit addition mode repeats 1-bit addition/non-addition to PWM output alternately upon MCNTm overflow output, and enables the state of PWM output between current compare value N and the next compare value N+1.

Figure 7-8: Operation of 1-bit Addition



Remark: n = 1 to 6
m = 0, 1

7.3.3 PWM output with 1 clock shifted operation

If the output of the sin/cos signal of meter channel 1 to 4 (5 and 6) rises/falls internally as indicated by the broken line, the SM11 to SM44 (SM51 to SM64) pins always shift the rising edge of the output pin by 1 count clock of the MCNTm counter. This shifted outputs prevent high current peaks that leads to V_{DD}/GND fluctuating.

Figure 7-9: Output Timing of SM11 to SM44

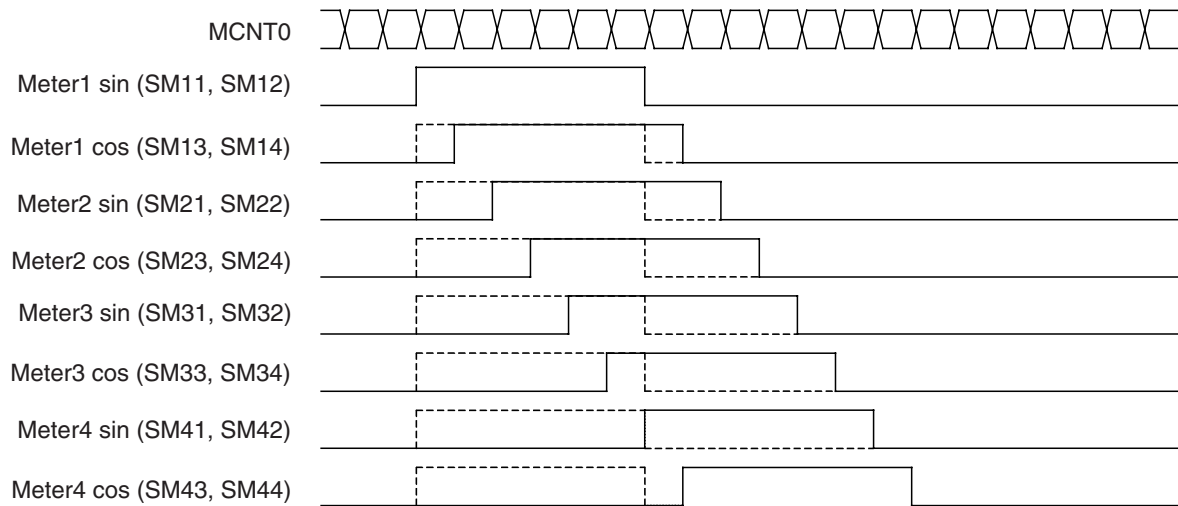
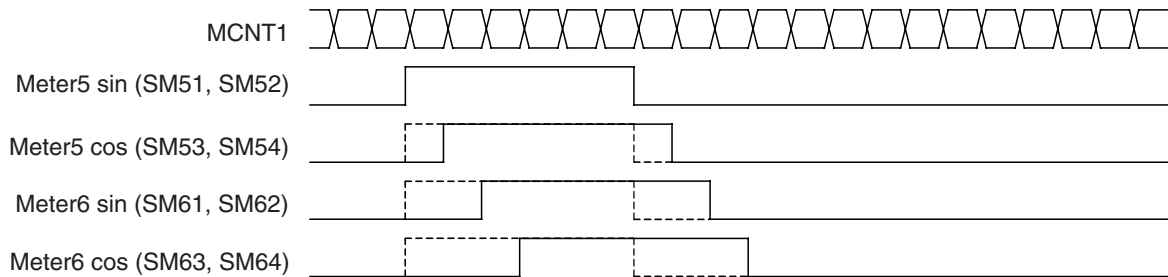
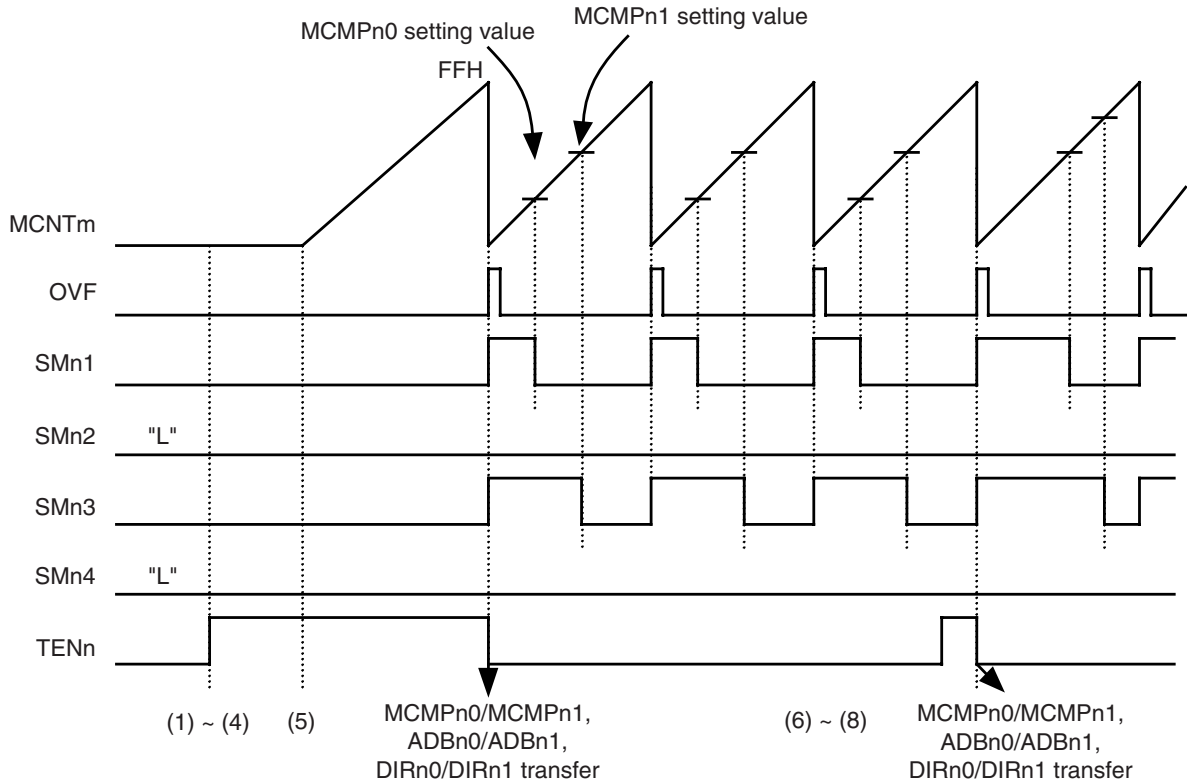


Figure 7-10: Output Timing of SM51 to SM64



7.4 Method of Using

Figure 7-11: Using of the SM

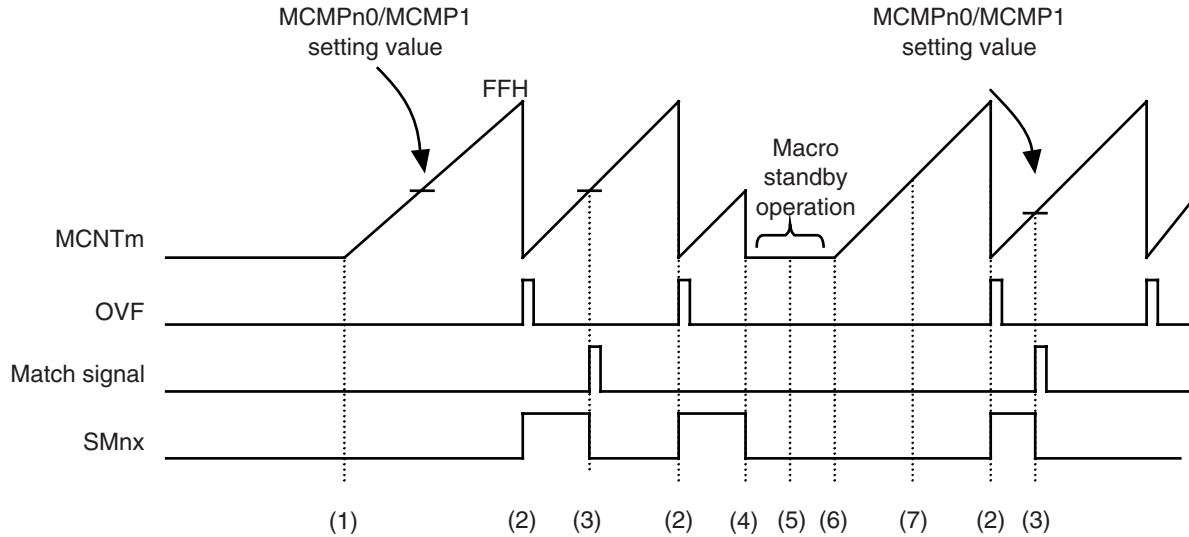


- (1) Setting SM pin to output mode by Port mode register assigned to SMn1 to SMn4 output
- (2) Input clock is supplied to the macro by setting CAE = "1"
- (3) Set compare register MCMPn0, MCMPn1
- (4) Set TENn = "1" and ADBn0/1, DIRn0/1 bits by setting compare mode control register MCMPCn.
- (5) Set PCE0/1 = "1", the counting operation/timing (with the specified counting selection) starts.
- (6) Ensure that TENn = "0" (rewriting period longer than count period until overflow)
- (7) Rewrite compare register MCMPn0, MCMPn1.
- (8) Set TENn = "1" (ADBn1, ADBn0, DIRn1, DIRn0 can be written at the same time if necessary).

7.4.1 Macro Standby operation

By setting PCE1 and PCE0/CAE = "0" of MCMTcN register, the timer stops count operation and the PWM output is set to "0". After that the macro is in power saving standby mode state.

Figure 7-12: SM Standby Operation



ADBn1 = 0, ADBn0 = 0, DIRn1 = 0, DIRn0 = 0

- (1) PCEm = "1" is written, counting operation starts.
- (2) Overflow occurs
- (3) MCMPn0 or MCMPn1 match with setting value.
- (4) CAE = "0" and PCEm = "0" are written, counting value is cleared & operation stops, PWM output is disabled.
- (5) MCMPn0 or MCMPn1 is rewritten.
- (6) CAE = "1" and PCEm = "1" are written, counting operation starts
- (7) TENn = "1" is written (ADBn1, ADBn0, DIRn1, DIRn0 bits can be written at the same time if necessary)

[MEMO]

Chapter 8 Reset Function

8.1 Separated Reset Functions

The reset functions of the FG2 and the MTRC are separated to each other. Therefore the application has to coordinate the reset states.

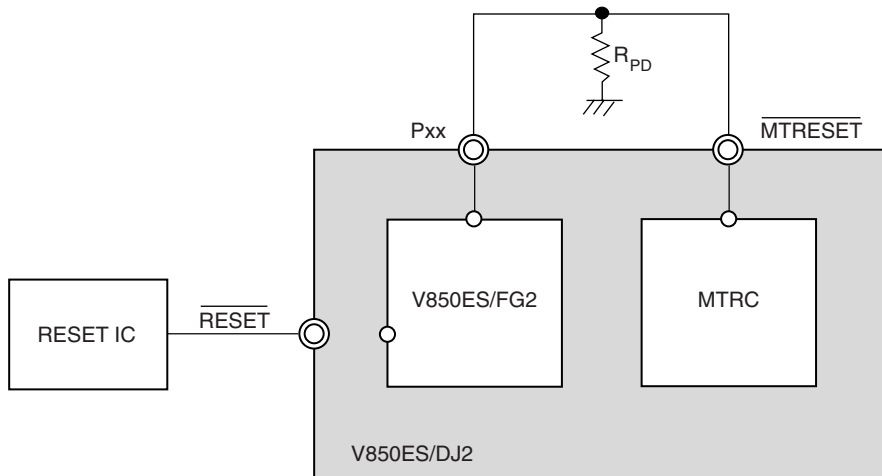
8.2 External Reset Circuitry

To control the Reset state of the MTRC it is recommended, to connect the $\overline{\text{MTRRESET}}$ pin to an output port of the FG2.

- Remarks:**
1. It is not possible to connect the $\overline{\text{MTRRESET}}$ pin of the MTRC and $\overline{\text{RESET}}$ pin of the FG2 together.
(If the FG2 comes into Reset state during a serial transmission via the CSIB1, the communication can't be restarted. Because of the independent clock supply of the MTRC, it will wait for the continuation of the broken communication. But if the Reset state of the F_Series is released, the MTRC SFRs would be re-initialized with a totally new transmission of the CSIB1 again. Therefore the communication will be left out of synchronization.)
 2. During a Power save mode the signal at $\overline{\text{MTRRESET}}$ pin should be high to remain the MTRC in operation mode (but switched off Ring Oscillator). Otherwise the MTRC will consume in reset mode more current via the PU/PD resistors at the internal connection pins.

8.2.1 External reset circuitry with pull-down resistor

Figure 8-1: External Reset Circuitry with Pull-Down Resistor

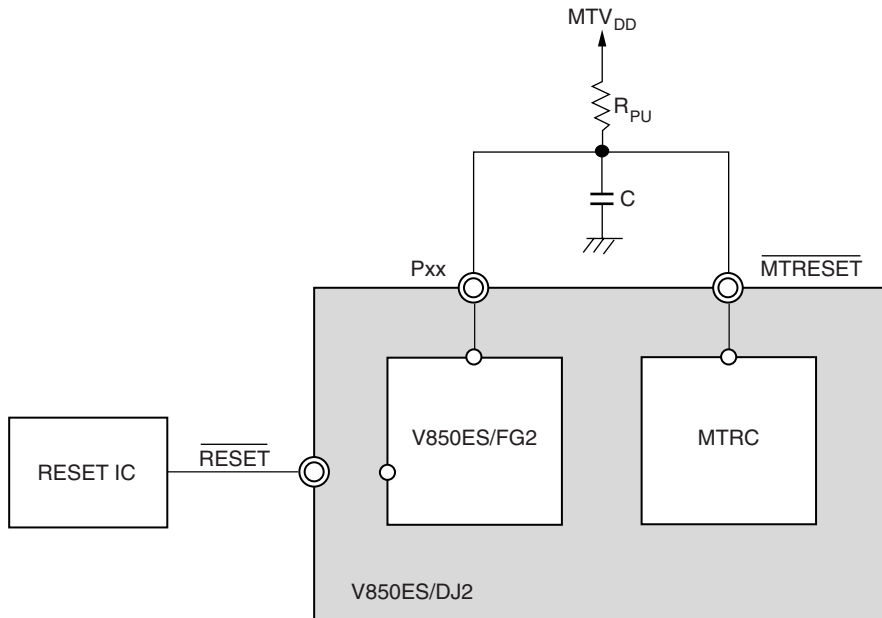


This circuitry is the best choice for safety applications, but consumes more power in power save modes.

If the FG2 will be reset via an internal (LVI or WD) or external function ($\overline{\text{RESET}}$), the Pxx pin will be set into its reset mode (input) and the pull down resistor will set the MTRC into reset state, too. In power save mode a continuous current will be consumed via R_{PD}.

8.2.2 External reset circuitry with pull-up resistor

Figure 8-2: External Reset Circuitry with Pull-Up Resistor



This circuitry saves more power, but at internal reset in the FG2 device, the MTRC will be left active with its last configured settings.

If MTV_{DD} will be applied, the signal at $\overline{\text{MTRESET}}$ pin will release the reset mode of the MTRC. The capacitor will cause a delay between MTV_{DD} apply and $\overline{\text{MTRESET}}$ release, to ensure the minimum specified time between this points of time.

If the FG2 will be reset via an internal (LVI or WD) or external function ($\overline{\text{RESET}}$), the P_{XX} port will be set into its reset mode (input) but the pull up resistor R_{PU} will hold the MTRC in its normal operation mode. Therefore the last configured action (PWM signal) will remain. It has to be checked if this leads to critical application states.

After the RESET release of the FG2 device, the MTRC should be reset via $\overline{\text{MTRESET}}$ pin as soon as possible (i.e. in the start-up code).

Chapter 9 Electrical Specification

9.1 Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Ratings	Unit	
Supply voltage	V_{DD}	$V_{DD}=EV_{DD}=BV_{DD}=AV_{REF0}=MTV_{DD}=SMV_{DD}$	-0.3 to +6.5	V	
	EV_{DD}	$V_{DD}=EV_{DD}=BV_{DD}=AV_{REF0}=MTV_{DD}=SMV_{DD}$	-0.3 to +6.5	V	
	BV_{DD}	$V_{DD}=EV_{DD}=BV_{DD}=AV_{REF0}=MTV_{DD}=SMV_{DD}$	-0.3 to +6.5	V	
	$MTV_{DD1,2}$	$V_{DD}=EV_{DD}=BV_{DD}=AV_{REF0}=MTV_{DD}=SMV_{DD}$	-0.3 to +6.5	V	
	$SMV_{DD1,2,3}$	$V_{DD}=EV_{DD}=BV_{DD}=AV_{REF0}=MTV_{DD}=SMV_{DD}$	-0.3 to +6.5	V	
	AV_{REF0}	$V_{DD}=EV_{DD}=BV_{DD}=AV_{REF0}=MTV_{DD}=SMV_{DD}$	-0.3 to +0.3	V	
	V_{SS}	$V_{SS}=EV_{SS}=BV_{SS}=AV_{SS}=MTV_{SS}=SMV_{SS}$	-0.3 to +0.3	V	
	EV_{SS}	$V_{SS}=EV_{SS}=BV_{SS}=AV_{SS}=MTV_{SS}=SMV_{SS}$	-0.3 to +0.3	V	
	BV_{SS}	$V_{SS}=EV_{SS}=BV_{SS}=AV_{SS}=MTV_{SS}=SMV_{SS}$	-0.3 to +0.3	V	
	MTV_{SS1}	$V_{SS}=EV_{SS}=BV_{SS}=AV_{SS}=MTV_{SS}=SMV_{SS}$	-0.3 to +0.3	V	
	$SMV_{SS1,2}$	$V_{SS}=EV_{SS}=BV_{SS}=AV_{SS}=MTV_{SS}=SMV_{SS}$	-0.3 to +0.3	V	
AV_{SS}	$V_{SS}=EV_{SS}=BV_{SS}=AV_{SS}=MTV_{SS}=SMV_{SS}$	-0.3 to +0.3	V		
Input voltage	V_{I1}	P00-P06, P10-P11, P30-P39, P40-P42, P50-P55, P90-P96, P910-P915, $\overline{\text{RESET}}$, FLMD0	-0.3 to $EV_{DD}+0.3^a$	V	
	V_{I2}	PCM2-PCM3, PCS0-PCS1, PCT0, PCT1, PCT4, PCT6, PDL0-PDL13	-0.3 to $BV_{DD}+0.3^a$	V	
	V_{I3}	X1, X2, XT1, XT2	-0.3 to $V_{RO}^b+0.3^a$	V	
	V_{I4}	PMT00-PMT03, PMT30-PMT35, PMT40-PMT43, $\overline{\text{MTRSET}}$	-0.3 to $MTV_{DD}+0.3^a$	V	
Analog input voltage	V_{IAN}	P70-P715	-0.3 to $AV_{REF0}+0.3^a$	V	
High level output current	I_{OH}	P00-P06, P10-P11, P30-P39, P40-P42, P50-P55, P90-P96, P910-P915	1 pin	-4	mA
			Total	-50	mA
		P70-715	1 pin	-4	mA
			Total	-20	mA
		PCM2-PCM3, PCS0-PCS1, PCT0, PCT1, PCT4, PCT6, PDL0-PDL13, MTCS	1 pin	-4	mA
			Total	-50	mA
		PMT10-PMT17	1 pin	-45	mA
			Total	-135	mA
		PMT20-PMT27	1 pin	-45	mA
			Total	-135	mA
		SM11-SM14, SM21-SM24	1 pin	-45	mA
			Total	-135	mA
		PMT00-PMT03, PMT30-PMT35, PMT40-PMT43	1 pin	-4	mA
			Total	-15	mA

Chapter 9 Electrical Specification

Parameter	Symbol	Conditions	Ratings	Unit	
Low level output current	I_{OL}	P00-P06, P10-P11, P30-P39, P40-P42, P50-P55, P90-P96, P910-P915	1 pin	4	mA
			Total	50	mA
		P70-P715	1 pin	4	mA
			Total	20	mA
		PCM2-PCM3, PCS0-PCS1, PCT0, PCT1, PCT4, PCT6, PDL0-PDL13, MTCS	1 pin	4	mA
			Total	50	mA
		PMT10-PMT17	1 pin	45	mA
			Total	135	mA
		SM11-SM14, SM21-SM24	1 pin	45	mA
			Total	135	mA
		PMT00-PMT03, PMT30-PMT35, PMT40-PMT43	1 pin	4	mA
			Total	30	mA
Operating ambient temperature	T_A	Normal operating mode	-40 to +85	°C	
		Flash programming mode	-40 to +85		
Storage temperature	T_{STG}		-40 to +125		

- a. Be sure not to exceed the absolute maximum ratings (MAX. value) of each supply voltage.
b. V_{RO} is the on-chip regulator output voltage (typ. 2.5 V)

- Cautions:**
1. **Avoid direct connections among the IC device output (or I/O) pins and between V_{DD} or V_{CC} and GND.**
 2. **All V_{DD} pins have to be connected externally.**
 3. **All V_{SS} pins have to be connected externally.**
 4. **Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.**
 5. **The ratings and conditions indicated for DC characteristics and AC characteristics represent the quality assurance range during normal operation.**

Remark: Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

9.2 Capacitance

($T_A=25^{\circ}\text{C}$,

$V_{DD}=EV_{DD}=BV_{DD}=AV_{REF0}=MTV_{DD}=SMV_{DD}=V_{SS}=EV_{SS}=BV_{SS}=AV_{SS}=MTV_{SS}=SMV_{SS}=0\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input capacitance	C_I	f=1 MHz, Other than unmeasured pins:0 V			15	pF
Input / Output capacitance	C_{IO}	f=1 MHz, Other than unmeasured pins:0 V PMT00-PMT03, PMT30-PMT37, PMT40-PMT43			15	pF
Output capacitance	C_O	f=1 MHz, Other than unmeasured pins:0 V Other than following pins			15	pF
	C_{SMO}	f=1 MHz, Other than unmeasured pins:0 V PMT10-PMT17, PMT20-PMT27, SM11-SM14, SM21-SM24			40	pF

9.3 Operation Conditions

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0\text{ to }5.5\text{ V}$,

$V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0\text{ V}$,

$T_A=-40\text{ to }+85^{\circ}\text{C}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Internal system clock frequency	f_{CLK}	$V_{DD}=5\text{ V} \pm 10\%$ PLL mode (OSC=4 MHz to 5 MHz)	16		20	MHz
		$V_{DD} = 4.0\text{ to }5.5\text{ V}$ PLL mode (OSC=4 MHz)	16	16	16	MHz
		$V_{DD}= 4.0\text{ to }5.5\text{ V}$ Through-rate mode (OSC=4 MHz to 5 MHz)	4		5	MHz
		$V_{DD}= 4.0\text{ to }5.5\text{ V}$ Sub-IDLE mode (Crystal) ^a	32		35	KHz
		REGC Capacity = 4.7 μF , at operation with subclock (RC resonator)	12.5		27.5	KHz

- a. Be sure not to access peripheral, even if switched sub operation mode one time, before go sub-IDLE mode.

9.4 Oscillation Circuits

9.4.1 Main System Clock Oscillation Circuit Characteristics

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,

$V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,

$T_A=-40$ to $+85^{\circ}C$)

Resonator	Recommended circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Crystal/ Ceramic resonator		Oscillation frequency		4		5	MHz
		Oscillation stabilization time ^a	After reset is released		$2^{16}/f_X$		s
			After STOP mode is released	0.5 ^b	c		ms
After IDLE2 mode is released	350 ^b	c		μ s			

- a. Time required from when V_{DD} reaches oscillation voltage range (MIN.: 4.0 V) to when the crystal resonator stabilizes.
- b. Stabilization time for Flash macro. Setting by OSTs resistor.
- c. Depend on the setting of the oscillation stabilization time select resistor (OSTs).

Cautions: 1. When using the main clock oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance.

- Keep the wiring length as short as possible.
- Do not cross the wiring with the other signal lines.
- Do not route the wiring near a signal line through which a high fluctuating current flows.
- Always make the ground point of the oscillator capacitor the same potential as V_{SS} .
- Do not ground the capacitor to a ground pattern through which a high current flows.
- Do not fetch signals from the oscillator.

2. When the main clock is stopped and the device is operating on the subclock, wait until the oscillation stabilization time has been secured by the program before switching back to the main clock.

9.4.2 Sub System Clock Oscillation Circuit Characteristics

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$)

Resonator	Recommended circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Crystal resonator		Oscillation frequency (f_{XT})		32	32.768	35	KHz
		Oscillation stabilization time ^a				10	μ s
RC resonator		Oscillation frequency (f_{XT})	$R = 390\text{ k}\Omega \pm 5\%^b$ $C = 47\text{ pF} \pm 10\%^b$	25	40	55	KHz
		Oscillation stabilization time ^a				100	μ s

- a. Time required from when V_{DD} reaches oscillation voltage range (MIN.= 4.0 V) to when the crystal resonator stabilizes.
- b. In order to avoid the influence of wiring capacity, shorten wiring as much as possible.

Cautions: 1. When using the subclock oscillator, wire as follows in the area enclosed by the broken lines in the above figures to avoid an adverse effect from wiring capacitance.

- Keep the wiring length as short as possible.
 - Do not cross the wiring with the other signal lines.
 - Do not route the wiring near a signal line through which a high fluctuating current flows.
 - Always make the ground point of the oscillator capacitor the same potential as V_{SS} .
 - Do not ground the capacitor to a ground pattern through which a high current flows.
 - Do not fetch signals from the oscillator.
2. The subclock oscillator is designed as a low-amplitude circuit for reducing current consumption, and is more prone to malfunction due to noise than the main clock oscillator. Particular care is therefore required with the wiring method when the subclock is used.

9.4.3 MTRC Ring Oscillator Oscillation Circuit Characteristics

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$)

Resonator	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Ring Oscillator	Oscillation frequency (f_{XR}) ^a		6.8 ^b	8	9.2	MHz
	Oscillation stabilization time ^c				20	μs
calibration pulse	Calibration high pulse ^d			14		μs
	calibration low pulse		3			μs
MTCS	High-Level width		600			ns
	Low-Level width		600			ns
	analog delay for noise suppression		71	192		ns

- a. if calibration routine was successfully performed
- b. 4 MHz if uncalibrated
- c. time required when MRON bit is set from "0" to "1"
- d. has to be exact the typ. value

9.4.4 PLL Characteristics

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input frequency	f_x		4		5	MHz
Output frequency	f_{xx}		16		20	MHz
Clock time	t_{PLL}	After V_{DD} reaches MIN.: 3.5 V			800	μs

9.4.5 μPD70F3235(A) V850FG2 Ring-OSC Characteristics

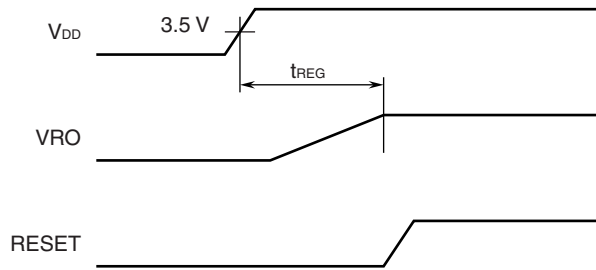
($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output frequency	f_r		100	200	400	KHz

9.5 Voltage Regulator Characteristics

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input voltage	V_{DD}		3.5		5.5	V
Output voltage	V_{RO}			2.5		V
Lock time	t_{REG}	After V_{DD} reaches MIN.: 3.5 V Connect $C = 4.7 \mu F \pm 20\%$ to REGC pin			1	ms



9.6 DC Characteristics

9.6.1 Input/Output Level

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$)

Parameter	Symbol	Conditions	MIN.	TYP	MAX.	Unit
Input voltage, high	V_{IH1}	P30, P34, P36-P38, P41, P911	0.7 EV_{DD}		EV_{DD}	V
	V_{IH2}	P00-P06, P10-P11, P31-P33, P35, P39, P40, P42, P50-P55, P90-P96, P910, P912-P915	0.8 EV_{DD}		EV_{DD}	V
	V_{IH3}	PCM2-PCM3, PCS0-PCS1, PCT0, PCT1, PCT4, PCT6, PDL0-PDL13	0.7 BV_{DD}		BV_{DD}	V
	V_{IH4}	P70-P715	0.7 AV_{REF0}		AV_{REF0}	V
	V_{IH5}	\overline{RESET} , FLMD0	0.8 EV_{DD}		EV_{DD}	V
	V_{IH6}	PMT40, $\overline{MTRESET}$	0.8 MTV_{DD}		MTV_{DD}	V
	V_{IH7}	PMT00-PMT03, PMT30-PMT35, PMT41-PMT43	0.7 MTV_{DD}		MTV_{DD}	V
Input voltage, low	V_{IL1}	P30, P34, P36-P38, P41, P98, P911	EV_{SS}		0.3 EV_{DD}	V
	V_{IL2}	P00-P06, P10-P11, P31-P33, P35, P39, P40, P42, P50-P55, P90-P96, P910, P912-P915	EV_{SS}		0.2 EV_{DD}	V
	V_{IL3}	PCM2-PCM3, PCS0-PCS1, PCT0, PCT1, PCT4, PCT6, PDL0-PDL13	BV_{SS}		0.3 BV_{DD}	V
	V_{IL4}	P70-P715	AV_{SS}		0.3 AV_{REF0}	V
	V_{IL5}	\overline{RESET} , FLMD0	EV_{SS}		0.2 EV_{DD}	V
	V_{IL6}	PMT40, $\overline{MTRESET}$	MTV_{SS}		0.2 MTV_{DD}	V
	V_{IL7}	PMT00-PMT03, PMT30-PMT35, PMT41-PMT43	MTV_{SS}		0.3 MTV_{DD}	V
Output voltage, high	V_{OH1}^a	P00-P06, P10-P11, P30-P39, P40-P42, P50-P55, P90-P96, P910-P915	$I_{OH}=-1.0$ mA	$EV_{DD}-1.0$	EV_{DD}	V
			$I_{OH}=-100$ μ A	$EV_{DD}-0.5$	EV_{DD}	V
	V_{OH2}^a	PCM0-PCM3, PCS0-PCS1, PCT0, PCT1, PCT4, PCT6, PDL0-PDL13	$I_{OH}=-1.0$ mA	$BV_{DD}-1.0$	BV_{DD}	V
			$I_{OH}=-100$ μ A	$BV_{DD}-0.5$	BV_{DD}	V
	V_{OH3}^b	P70-P715	$I_{OH}=-1.0$ mA	$AV_{REF0}-1.0$	AV_{REF0}	V
			$I_{OH}=-100$ μ A	$AV_{REF0}-0.5$	AV_{REF0}	V
Output voltage, high	V_{OH4}^c	PMT10-PMT17, PMT20-PMT27, SM11-SM14, SM21-SM24	$I_{OH}=-27$ mA ($T_A=85^{\circ}C$) $I_{OH}=-30$ mA ($T_A=25^{\circ}C$) $I_{OH}=-40$ mA ($T_A=-40^{\circ}C$)	$SMV_{DD}-0.07$	$SMV_{DD}-0.7$	V
			$I_{OH}=-19$ mA ($T_A=85^{\circ}C$) $I_{OH}=-21$ mA ($T_A=25^{\circ}C$) $I_{OH}=-28$ mA ($T_A=-40^{\circ}C$)	$SMV_{DD}-0.5$	$SMV_{DD}-0.7$	V
	V_{OH5}^d	PMT00-PMT03, PMT30-PMT35, PMT40-PMT43	$I_{OH}=-1.0$ mA	$MTV_{DD}-1.0$	MTV_{DD}	V

Chapter 9 Electrical Specification

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Output voltage, low	V_{OL1}^e	P00-P06, P10-P11, P30-P39, P40-P42, P50-P55, P90-P96, P910-P915	0		0.4	V	
	V_{OL2}^e	PCM0-PCM3, PCS0-PCS1, PCT0, PCT1, PCT4, PCT6, PDL0-PDL13					
	V_{OL3}^f	P70-P715					
	V_{OL4}^g	PMT10-PMT17, PMT20-PMT27, SM11-SM14, SM21-SM24	$I_{OL}=27\text{ mA } (T_A=85^\circ\text{C})$ $I_{OL}=30\text{ mA } (T_A=25^\circ\text{C})$ $I_{OL}=40\text{ mA } (T_A=-40^\circ\text{C})$	0.07		0.7	V
			$I_{OH}=19\text{ mA } (T_A=85^\circ\text{C})$ $I_{OH}=21\text{ mA } (T_A=25^\circ\text{C})$ $I_{OH}=28\text{ mA } (T_A=-40^\circ\text{C})$	0.07		0.5	V
V_{OL5}^h	PMT00-PMT03, PMT30-PMT35, PMT40-PMT43	$I_{OL}=1.0\text{ mA}$	0		0.4	V	
Pull-up resistor	R1	$V_I=0\text{ V}$	10	30	100	$\text{K}\Omega$	
Pull-down resistor ⁱ	R2	$V_I=V_{DD}$	10	30	100	$\text{K}\Omega$	

- a. Total I_{OH} (Max.) is -20 mA
- b. I_{OL} max of V_{OL3} is -16 mA.
- c. I_{OH} max of V_{OH4} is -135 mA.
- d. I_{OH} max of V_{OH5} is -12 mA.
- e. I_{OL} max of V_{OL3} is 20 mA.
- f. I_{OL} max of V_{OL3} is 16 mA.
- g. I_{OL} max of V_{OL4} is 135 mA.
- h. I_{OL} max of V_{OL5} is 12 mA
- i. Exists only at DRST pin

9.6.2 Pin Leak Current

$(V_{DD}=E V_{DD}=B V_{DD}=M T V_{DD}=S M V_{DD}=A V_{REF0}=4.0\text{ to }5.5\text{ V},$
 $V_{SS}=E V_{SS}=B V_{SS}=M T V_{SS}=S M V_{SS}=A V_{SS}=0\text{ V},$
 $T_A=-40\text{ to }+85^\circ\text{C})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input leakage current, high	I_{LIH1}	$V_{IN} = V_{DD}$	Analog pins			+0.2	μA
			Except the above			+0.5	
Input leakage current, low	I_{LIL1}	$V_{IN} = 0\text{ V}$	Analog pins			-0.2	μA
			Except the above			-0.5	
Output leakage current, high	I_{LOH1}	$V_O = V_{DD}$	Analog pins			+0.2	μA
			Except the above			+0.5	
Output leakage current, low	I_{LOL1}	$V_O = 0\text{ V}$	Analog pins			-0.2	μA
			Except the above			-0.5	

Caution: In flash memory versions, spec of FLMD0 pin is as follows.:

- Input leakage current, high: 2 μA
- Input leakage current, low: 2 μA

9.6.3 Power Supply Current

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=4.0$ to 5.5 V

$AV_{REF0}=4.0$ to 5.5 V

$V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V

$T_A=-40$ to $+85^{\circ}C$)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Supply current ^a	IDD1	Operating mode	$f_{XX}=20$ MHz (OSC=5 MHz) MTRC-Ring Oscillator On		32.5	50	mA
			All peripherals stopped MTRC-Ring Oscillator On		22		mA
	IDD2	HALT mode	$f_{XX}=20$ MHz (OSC=5 MHz) MTRC-Ring Oscillator On		20.5	33	mA
			All peripherals stopped MTRC-Ring Oscillator On		11		mA
	IDD3	IDLE1 mode	$f_{XX}=5$ MHz (OSC=5 MHz) PLL Off MTRC-Ring Oscillator Off		0.6	0.92	mA
	IDD4	IDLE2 mode	$f_{XX}=5$ MHz (OSC=5 MHz) PLL Off MTRC-Ring Oscillator Off		0.25	0.72	mA
	IDD5	Sub Operation mode ^b	Crystal resonator $f_{XT}=32.768$ KHz RC resonator ^c $f_{XT}=40$ KHz MTRC-Ring Oscillator Off		200	420	μA
	IDD6	Sub IDLE mode ^d	Crystal resonator $f_{XT}=32.768$ KHz MTRC-Ring Oscillator Off		20	140	μA
			RC resonator ^c $f_{XT}=40$ KHz MTRC-Ring Oscillator Off		35	160	μA
	IDD7	STOP mode ^e	Ring Oscillator On MTRC-Ring Oscillator Off		15	85	μA
Ring Oscillator Off MTRC-Ring Oscillator Off				7	70	μA	

a. V_{DD} , EV_{DD} , BV_{DD} and MTV_{DD} total current. AV_{REF0} and SMV_{DD} current, port buffer current (including a current flowing in the on-chip pull-up/pull-down resistors) are not included.

b. Main Oscillator is off and Ring Oscillator is on.

c. RC Oscillator frequency is typ.40 KHz. This clock is divided (1/2) internally.

d. Main Oscillator is off.

e. Main Oscillator is off and Sub Oscillator is not used.

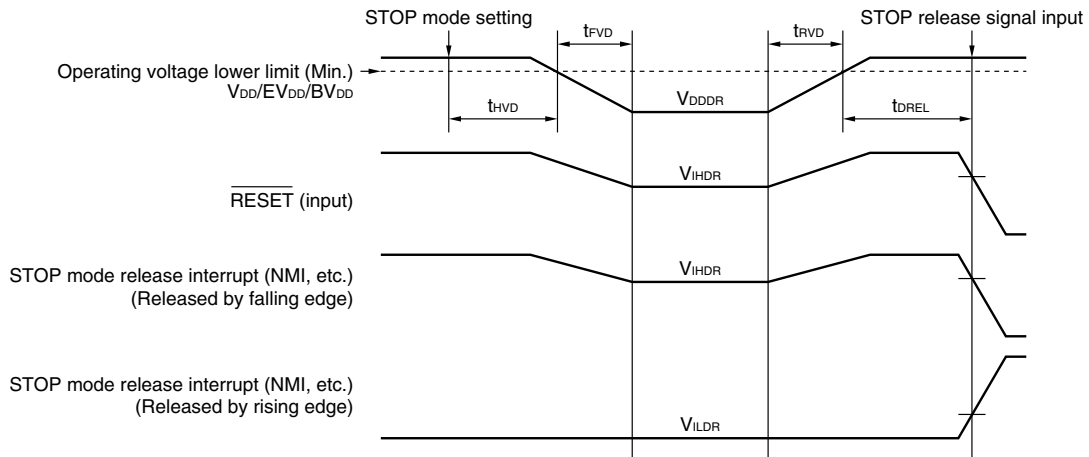
9.6.4 Data Retention Characteristics

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=2.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}\text{C}$)

Table 9-1: Data Retention Characteristics

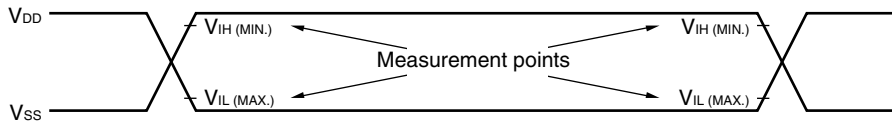
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention voltage	V_{DDDR}	In STOP mode	1.9		5.5	V
Data retention current	I_{DDDR}	$V_{DDDR} = 2.0$ V		6	65	μA
Supply voltage rise time	t_{rVD}		1			μs
Supply voltage fall time	t_{fVD}		1			μs
Supply voltage retention time	t_{HVD}	After STOP mode release	0			ms
STOP release signal input time	t_{dREL}	After V_{DD} reaches MIN.: 3.5 V	0			μs
Data retention input voltage, high	V_{IHDR}	All input ports	$0.9V_{DDDR}$		V_{DDDR}	V
Data retention input voltage, low	V_{ILDR}	All input ports	0		$0.1V_{DDDR}$	V

Caution: Shifting to STOP mode and restoring from STOP mode must be performed within the rated operating range.

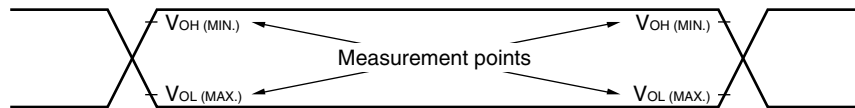


9.7 AC Characteristics

AC Test Input Measurement Points (V_{DD} , AV_{DD} , EV_{DD} , BV_{DD} , MTV_{DD} , MTV_{DD}),



AC Test Output Measurement Points



Load Conditions



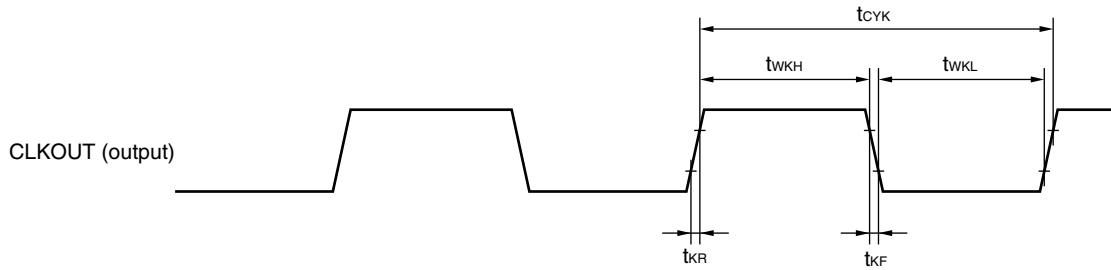
Caution: If the load capacitance exceeds 50 pF due to the circuit configuration, bring the load capacitance of the device to 50 pF or less by inserting a buffer or by some other means.

9.7.1 EXCLO output timing

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^\circ\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
Output cycle	t_{CYK}		62.5 ns	8 μs	
High level width	t_{WKH}		$t_{CYK}/2 - 15$		ns
Low level width	t_{WKL}		$t_{CYK}/2 - 15$		ns
Rising time	t_{KR}			15	ns
Falling time	t_{KF}			15	ns

Clock Timing



9.7.2 $\overline{\text{RESET}}$, Interrupt, FLMD0 timing

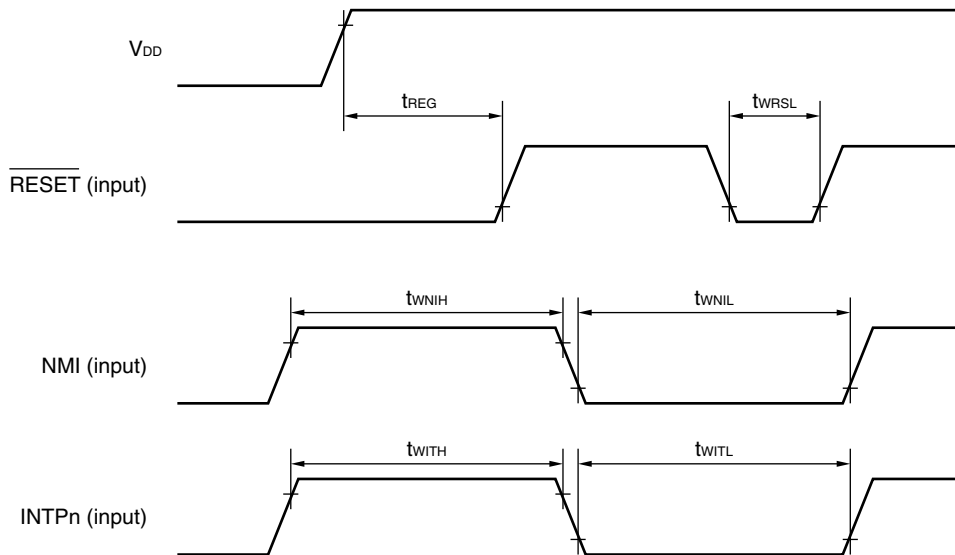
($V_{DD}=E_{V_{DD}}=B_{V_{DD}}=M_{V_{DD}}=S_{V_{DD}}=A_{V_{REF0}}=4.0$ to 5.5 V,
 $V_{SS}=E_{V_{SS}}=B_{V_{SS}}=M_{V_{SS}}=S_{V_{SS}}=A_{V_{SS}}=0$ V,
 $T_A=-40$ to $+85^\circ\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
$\overline{\text{MTRRESET}}$ input low level width	t_{WMRSL}		500		ns

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
RESET low-level width	t_{WRSL}		500		ns
NMI high-level width	t_{WNIH}	Analog noise elimination	500		ns
NMI low-level width	t_{WNIL}	Analog noise elimination	500		ns
INTPn high-level width ^a	t_{WITH}	Analog noise elimination (n = 0 to 7)	500		ns
		Digital noise elimination (n = 3)	b		ns
INTPn low-level width ^a	t_{WITL}	Analog noise elimination (n = 0 to 7)	500		ns
		Digital noise elimination (n = 3)	b		ns

- a. ADTRG is same spec (P03/INTP0/ADTRG). DRST is same spec (P05/INTP2/DRST).
- b. $2T_{\text{samp}} + 20$ or $3T_{\text{samp}} + 20$

Reset/Interrupt

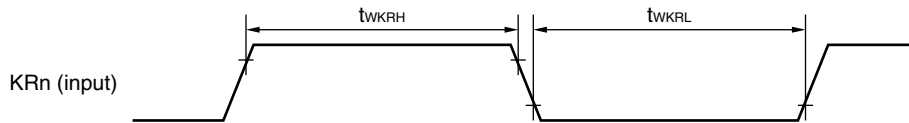


Remark: n = 0 to 7

9.7.3 Key Return timing

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^\circ\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
KRn input high-level width	t_{WKRH}	Analog noise elimination ($n = 0$ to 7)	500		ns
KRn input low-level width	t_{WKRL}		500		ns



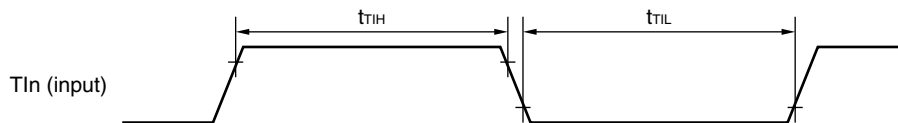
Remark: $n = 0$ to 7

9.7.4 Timer Input timing

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^\circ\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
TIn high-level width	t_{TIH}	TIP00, TIP01, TIP10, TIP11, TIP20, TIP21, TIP30, TIP31,	Note		ns
TIn low-level width	t_{TIL}	TIQ00 to TIQ03, TIQ10 to TIQ13	Note		ns

Note: $2T_{\text{samp}} + 20$ or $3T_{\text{samp}} + 20$
 T_{samp} : Sampling clock for noise elimination



9.7.5 CSI timing

(1) CSIB0

(a) Master Mode

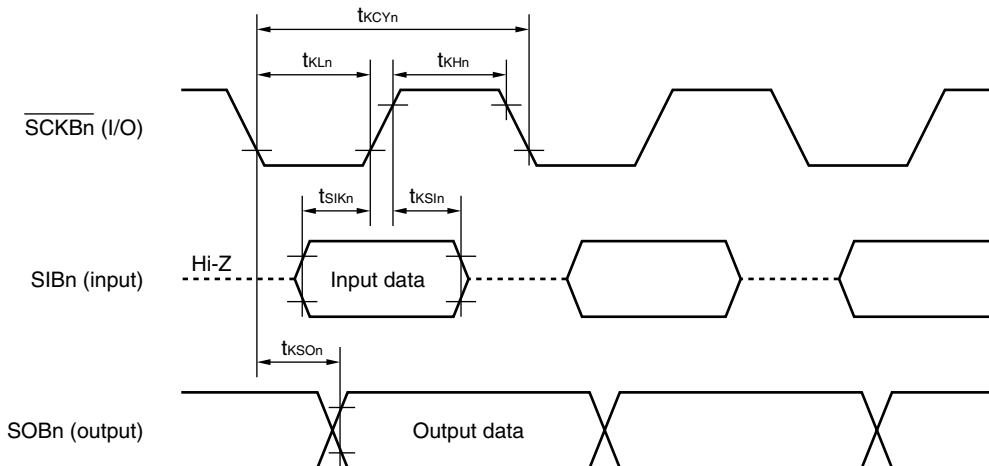
($V_{DD}=E V_{DD}=B V_{DD}=M T V_{DD}=S M V_{DD}=A V_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=E V_{SS}=B V_{SS}=M T V_{SS}=S M V_{SS}=A V_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
$\overline{\text{SCKB0}}$ cycle time	t_{KCY0}		125		ns
$\overline{\text{SCKB0}}$ high level width	t_{KH0}		$t_{\text{KCY0}}/2-15$		ns
$\overline{\text{SCKB0}}$ low level width	t_{KL0}		$t_{\text{KCY0}}/2-15$		ns
SIB0 setup time (to $\overline{\text{SCKB0}}$)	t_{SIK0}		30		ns
SIB0 hold time (from $\overline{\text{SCKB0}}$)	t_{KSI0}		25		ns
$\overline{\text{SCKB0}}$ to SOB0 output delay time	t_{KSO0}			25	ns

(b) Slave Mode

($V_{DD}=E V_{DD}=B V_{DD}=M T V_{DD}=S M V_{DD}=A V_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=E V_{SS}=B V_{SS}=M T V_{SS}=S M V_{SS}=A V_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
$\overline{\text{SCKB0}}$ cycle time	t_{KCY0}		200		ns
$\overline{\text{SCKB0}}$ high level width	t_{KH0}		90		ns
$\overline{\text{SCKB0}}$ low level width	t_{KL0}		90		ns
SIB0 setup time (to $\overline{\text{SCKB0}}$)	t_{SIK0}		50		ns
SIB0 hold time (from $\overline{\text{SCKB0}}$)	t_{KSI0}		50		ns
$\overline{\text{SCKB0}}$ to SOB0 output delay time	t_{KSO0}			50	ns



(2) CSIB1

CSIB1 can be only used in Master Mode.

(a) Master Mode

($V_{DD}=E V_{DD}=B V_{DD}=M T V_{DD}=S M V_{DD}=A V_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=E V_{SS}=B V_{SS}=M T V_{SS}=S M V_{SS}=A V_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	MAX.	Unit
$\overline{EXSCK1}$ cycle time	t_{KCY1}		250/1000 ^a		ns
$\overline{EXSCK1}$ high level width	t_{KH1}		$t_{KCY1}/2 - 30$		ns
$\overline{EXSCK1}$ low level width	t_{KL1}		$t_{KCY1}/2 - 30$		ns
EXS11 setup time (to $\overline{EXSCK1}$)	t_{SIK1}		50		ns
EXS11 hold time (from $\overline{EXSCK1}$)	t_{KSI1}		50		ns
$\overline{EXSCK1}$ to EXSO1 output delay time	t_{KSO1}			50	ns

- a. Be sure to set cycle time ($\overline{EXSCK1}$) over 4 times as the internal system clock cycle ($1/f_{CLK}$). $t_{KCY1} \geq 1/f_{CLK} \times 4$
 If the CSI1 communicate with the uncalibrated MTRC (f_{RO_uncal} min. 4 MHz) t_{KCY1} has to be ≥ 1000 ns

9.7.6 UART timing

($V_{DD}=E V_{DD}=B V_{DD}=M T V_{DD}=S M V_{DD}=A V_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=E V_{SS}=B V_{SS}=M T V_{SS}=S M V_{SS}=A V_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}C$, $C_L=50$ pF)

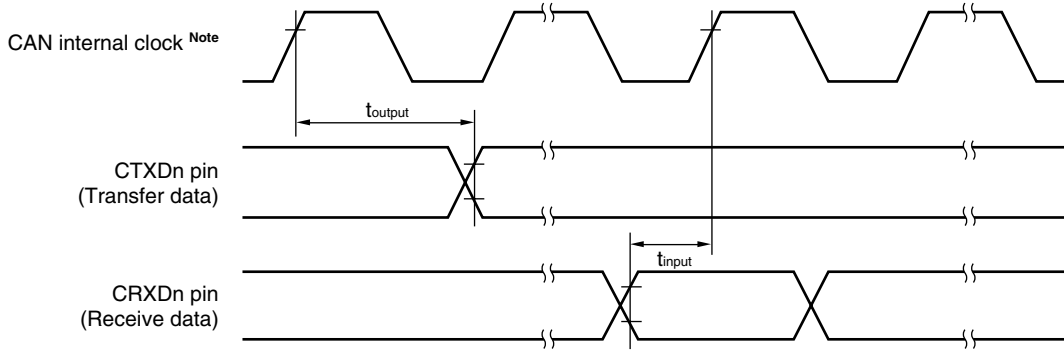
Parameter	Symbol	Conditions	MIN.	MAX.	Unit
Communication rate				312.5	kbps
ASCK0 cycle time				10	MHz

9.7.7 CAN timing

($V_{DD}=E_{V_{DD}}=B_{V_{DD}}=M_{V_{DD}}=S_{V_{DD}}=A_{V_{REF0}}=4.0$ to 5.5 V,
 $V_{SS}=E_{V_{SS}}=B_{V_{SS}}=M_{V_{SS}}=S_{V_{SS}}=A_{V_{SS}}=0$ V,
 $T_A=-40$ to $+85^{\circ}\text{C}$, $C_L=50$ pF)

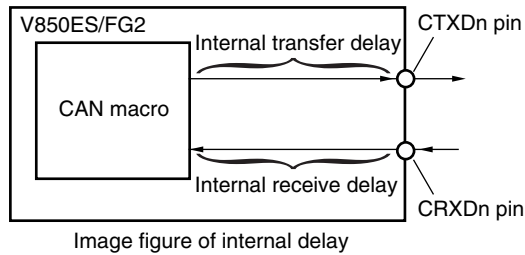
Parameter	Symbol	Conditions	MIN.	MAX.	Unit
Transfer rate				1	Mbps
Internal delay time ^a				100	ns

a. Internal delay time (t_{NODE}) = Internal transfer delay time (t_{OUTPUT}) + Internal receive delay time (t_{INPUT}).



Note: CAN internal clock (f_{CAN}): CAN baud rate clock

Remark: $n = 0, 1$



9.7.8 AD Converter

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution					10	bit
Overall error ^a		$4.0 \leq AV_{REF0} \leq 5.5$ V		± 0.15	± 0.45	%FSR
Conversion time	t_{CONV}		3.1		16	μs
Analog input voltage	V_{IAN}		AV_{SS}		AV_{REF0}	V
AV_{REF0} current	I_{AREF0}	When using A/D converter		5	10	mA
		When not using A/D converter		1	10	μA

a. Excluding quantization error ($\pm 0.05\%$ FSR). Indicates the ratio to the full-scale value (%FSR).

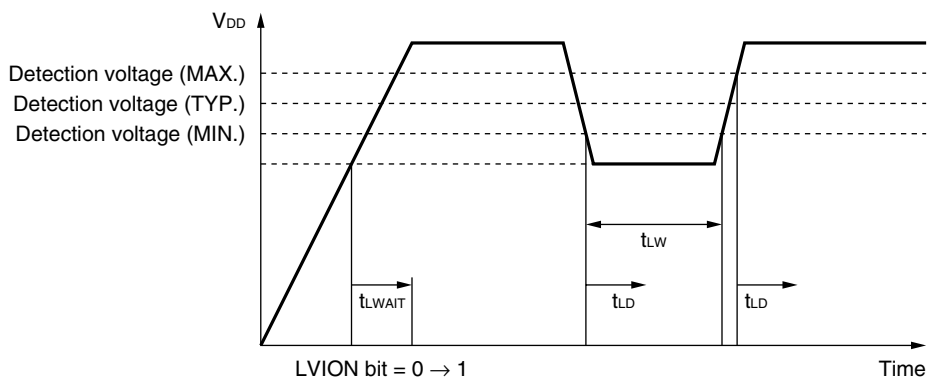
Note: FSR: Full Scale Range

9.7.9 LVI

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{LV10}		4.2	4.4	4.6	V
	V_{LV11}		4.0	4.2	4.4	V
Response time ^a	t_{LD}	After V_{DD} reaches V_{LV10}/V_{LV11} (Max.). After V_{DD} drops V_{LV10}/V_{LV11} (Min.).		0.2	2.0	ms
Minimum V_{DD} width	t_{LW}		0.2			ms
Reference voltage stabilization wait time ^b	t_{LWAIT}	After V_{DD} reaches 3.5 V. After LVION bit (LVIM.bit7) = 0 \rightarrow 1		0.1	0.2	ms

a. The time required to output an interrupt/reset after the detection voltage is detected.
 b. Unnecessary when the POC function is used.

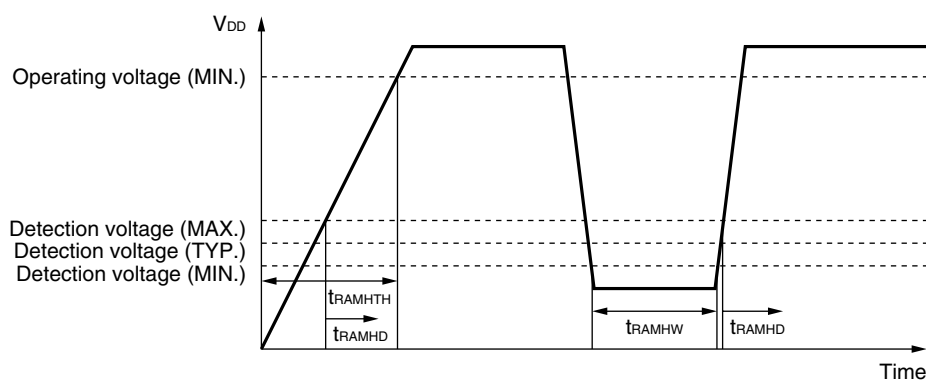


9.7.10 RAM retention flag

($V_{DD}=E_{V_{DD}}=B_{V_{DD}}=M_{TV_{DD}}=S_{MV_{DD}}=A_{V_{REF0}}=4.0$ to 5.5 V,
 $V_{SS}=E_{V_{SS}}=B_{V_{SS}}=M_{TV_{SS}}=S_{MV_{SS}}=A_{V_{SS}}=0$ V,
 $T_A=-40$ to $+85^\circ\text{C}$, $C_L=50$ pF)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{RAMH}		1.9	2.0	2.1	V
Supply voltage rise time	t_{RAMHTH}	$V_{DD} = 0 \text{ V} \rightarrow 3.5 \text{ V}$	0.002		1,800	ms
Response time ^a	t_{RAMHD}	After the supply voltage reaches the detection voltage (MAX.)		0.2	2.0	ms
Minimum V_{DD} width	t_{RAMHW}		0.2			ms

a. Time required to set the RAMF bit after the detection voltage is detected.



9.7.11 Flash Memory Programming characteristics

($V_{DD}=EV_{DD}=BV_{DD}=MTV_{DD}=SMV_{DD}=AV_{REF0}=4.0$ to 5.5 V,
 $V_{SS}=EV_{SS}=BV_{SS}=MTV_{SS}=SMV_{SS}=AV_{SS}=0$ V,
 $T_A=-40$ to $+85^{\circ}\text{C}$, $C_L=50$ pF)

(1) Basic characteristics

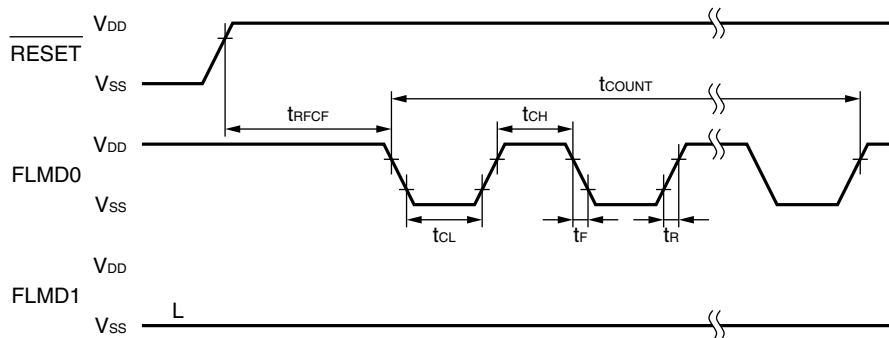
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Operating frequency	f_{CPU}		4		20	MHz
Supply voltage	V_{DD}		4.0		5.5	V
Number of writes	$C_{\text{WRT}}^{\text{a}}$				100	Times
Input voltage, high	V_{IH}	FLMD0	$0.8EV_{\text{DD}}$		EV_{DD}	V
Input voltage, low	V_{IL}	FLMD0	EV_{SS}		$0.2EV_{\text{DD}}$	V
Programming temperature	t_{PRG}		-40		+85	$^{\circ}\text{C}$

a. The initial write when the product is shipped, any erase → write set of operations, or any programming operation is counted as one rewrite.

(2) Serial Write Operation Characteristics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
FLMD0 setup time from RESET↑	t_{RFCF}		$5000/f_x + \alpha^{\text{a}}$			s
Count execution time	t_{COUNT}				3	ms
FLMD0 high-level width	t_{CH}		10		100	μs
FLMD0 low-level width	t_{CL}		10		100	μs
FLMD rise time	t_{R}				50	μs
FLMD fall time	t_{F}				50	μs

a. α denotes the oscillation stabilization time

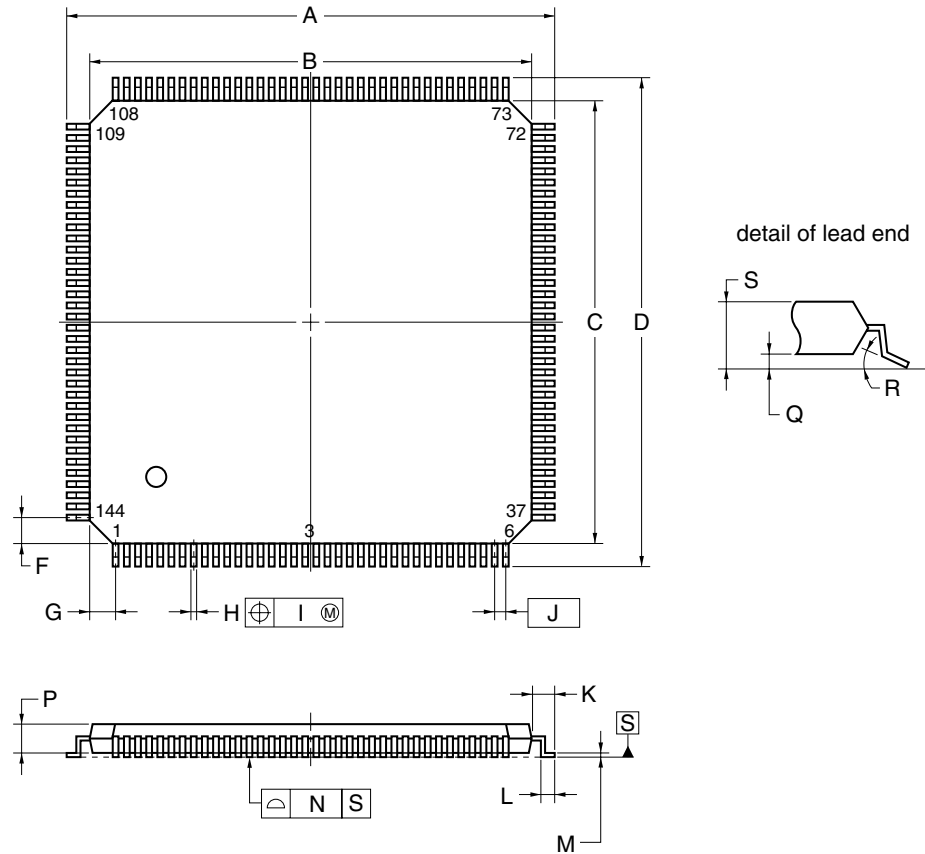


[MEMO]

Chapter 10 Package Drawings

Figure 10-1: V850ES/DJ2

144-PIN PLASTIC LQFP (FINE PITCH) (20x20)



NOTE

Each lead centerline is located within 0.08 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	22.0±0.2
B	20.0±0.2
C	20.0±0.2
D	22.0±0.2
F	1.25
G	1.25
H	0.22±0.05
I	0.08
J	0.5 (T.P.)
K	1.0±0.2
L	0.5±0.2
M	0.17 ^{+0.03} _{0.07}
N	0.08
P	1.4
Q	0.10±0.05
R	3° ^{+4°} _{3°}
S	1.5±0.1

S144GJ-50-UEN

[MEMO]

Chapter 11 Recommended Soldering Conditions

Solder this product under the following recommended conditions.

For details of the recommended soldering conditions, refer to information document Semiconductor Device:

Mounting Technology Manual (C10535E).

For soldering methods and conditions other than those recommended please consult NEC.

Soldering Method	Soldering Condition	Symbol of Recommended Soldering Condition
Infrared reflow	Package peak temperature: 235°C	IR35-207-3
Partial heating	350°C	P350

Caution: Do not use two or more soldering methods in combination (except partial heating method).

[MEMO]

Revision History

Version	Date	Remarks
1.1	2005/09/01	Initial release
1.2	2006/12/13	Chapter 1.5.2: new description of internal and external communication via CSIB1
		Chapter 3.1: MTCS corrected to CS in MTRC pinout
		Chapter 3.2: description of MTCS completed
		Chapter 4.6.1: new caution: configuration of PMT34 to PMT37
		Chapter 4.6.2: new caution: configuration of PMT34 to PMT37
		Chapter 9.6.3: IDD3 condition corrected: PLL Off

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